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MICROCIRCUIT COST FACTORS

Hughes Aircraft Company

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Section 0.0

FOREWORD

A methodology is developed in this report for assessing the life cycle cost (LCC) impacts of microcircuit (MC) devices on system design, production and lifetime support. The methodology is based on the development of parametric cost-estimating-relationships (CER's) which relate specific MC characteristics (eg, reliability grade, packaging, complexity, technology, etc.) to costs that are incurred of various phases of system development, manufacturing, and maintenance and support. The data used to develop the CER's was compiled from Hughes' historical data files, literature searches, and government sources.

A computerized LCC model is provided which aggregates costs based on a set of MC characteristics and summarizes the results into the major cost elements of each program phase. A typical application of the methodology would be to compare the LCC of competing families of MC devices in the design implementation stage of system development. The level of integration (i.e., SSI/MSI vs. LSI vs. custom LSI), for example, would effect design partitioning which determines the number and types of circuit card assemblies to inventory and provide as spares during system maintenance and support.

Finally, a step-by-step guide is provided for using the LCC model which details the input requirements and default options, and describes the various outputs of the computer printout. Example applications of this model are also provided which involve: to MC tradeoffs of device quantity level, inhouse screening vs. vendor qualification, and custom LSI vs. standard SSI/MSI.



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The objective of this study was to develop parametric cost estimating relationships for guidance in selecting microcircuits that are intended for utilization in maintainable equipments operating in military environments. Cost relationships were developed and formatted in a comprehensive computerized model that provides a measure of relative impact that technology, function, package complexity and quality/reliability have on system Life Cycle Cost (LCC). The major LCC phases affected by microcircuits; development, production and maintenance, each has been accounted for in the model. Model users can input their specific data or default options are provided when the required inputs are unavailable.

The following microcircuit factors were found to have a measurable impact on system LCC:

Technology - Primary impact on material procurement cost.

Function - Strong influences on both material procurement and assembly cost.

Package - Material procurement and assembly costs are greater for flat-packages than for dual-in-line.

Complexity - Increased complexity, particularly for custom circuits have a noticeable impact on material and assembly cost. Test costs are significantly increased when linear microcircuit complexity is increased.

Quality/Reliability - Higher quality devices increased material cost and reduced assembly cost through less rework.

The resulting microcircuit cost factor model is applicable primarily to monolithic devices that represent today's technology. Updating of the model will be necessary to accommodate hybrids, technology evolution and testing improvements, as they are introduced. The model has been exercised using primarily the study contractors data set; additional verification will therefore be necessary before general purpose use can be recommended. The ultimate mechanism for distributing this model, once verification has been satisfactorily accomplished, will be the RADC Reliability Design Handbook.

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Project Engineer

Section 1.0

SUMMARY OF STUDY RESULTS

1.1 INTRODUCTION

The extensive use of microcircuits (MC's) of all types and complexities in military electronic systems necessitates a close examination of the cost impact of these devices when alternate equipment designs, modifications, etc. are under consideration. Decisions on whether to use standard or custom MC's, JAN B or B-2 reliability grade, bipolar or MOS memory etc. can have far reaching impacts on the costs of system development, production and lifetime maintenance and support. Accordingly, the objectives of the study are to 1) analyze the cost factors associated with MC characteristics (i.e., type, complexity, packaging, technology, etc.), 2) develop parametric cost estimating relationships (CER's) based on relevant MC characteristics and 3) provide an application guide for selecting optimal (i.e., least cost) MC characteristics for use in military equipments.

Hughes adopted a "systems" approach in deriving CER's which would account for the major cost impacts resulting from changes in MC characteristics. In this systems approach, the entire population of a family of candidate MC devices is used to assess the life cycle cost (LCC) impact. A change from one family of devices to another not only has a direct effect on the MC population cost and, therefore, the system cost, but also has many "hidden" cost effects that are not generally accounted for in cost tradeoffs. Some of the major cost areas impacted by MC changes are given in Table 1.1-1.

The extent of the cost impact is, of course, a direct function of the MC device population effected by the change. Thus, if the effected population is large only a small change in MC characteristics could lead to a significant difference in LCC. In small populations (i.e., involving less than 100 devices), however, it is doubtful that the difference in LCC would be of any significance regardless of the change in MC characteristics.

1.2 MC DEVICE MODEL DESCRIPTION, GROUND RULES AND ASSUMPTIONS

The algorithm developed for estimating MC LCC consists of CER's derived from data gathered on device development and procurement, card and system

Table 1.1-1. Major LCC Areas Effected by MC Differences

Major Cost Area	Typical Causes Related to MC Differences
Card Production	Differences in device type (linear, digital), complexity, quality grade have an effect on assembly and test labor, and on test yield (which is the card production cost driver in the test-rework cycle.)
Sparing	Differences in device complexity generally effects the unit cost, and system re-partitioning which changes the number of card types. Changes in device quality grade impacts the quality of spares per operating site and the pipeline.
Depot Maintenance	The repair labor and materials cost is directly effected by differences in device complexity and quality grade.
Inventory and Supply Management	These costs are effected whenever new items, e.g., custom LSI) are introduced into government inventory. If the device complexity is changed and causes a re-partitioning of the system, a very significant cost impact could result.

manufacture and from system maintenance support. The cost impact of a family of MC devices over the life cycle (y) of a program is represented by the following model:

$$(1.1) \quad LCC_{MC}(y) = RCER + \sum_{i=1}^4 PCER_i + \sum_{i=1}^6 MCER_i(y)$$

Each of the cost factors in (1.1) represent a CER and is described in Table 1.2-1. The sources of data and methodology for processing the data are provided in Section 2 and a complete discussion of the CER's is given in Section 3 with examples illustrating the LCC model application given in Section 4.

A computer program was developed for the LCC model as a tool for performing trade-off analyses involving multiple changes in MC device characteristics. The computer program is written in ANSI FORTRAN IV and is documented in Appendix C. The program provides a number of input default options which are exercised when the user does not have the required data. For example, the CER's for some of the cost areas consist of a "basic" equation plus alternate equations based on a reduced set of MC variables. The "basic" equations provide the best (in terms of statistical correlation) regression fit, whereas the alternate equations require fewer input variables at the expense of a small loss in fit. Another type of default is provided to supplement data normally supplied by the user primarily in the area of maintenance support costs and factors. The default values in these cases are generally taken from government standards or from published literature. A detailed discussion of all default options is provided in Section 4.1.1.

Table 1.2-1. LCC Model CER's

LCC Phase	CER	Description
RDT&E	RCER	Total development cost (RDT&E) of new custom/semicustom devices.
PRODUCTION	PCER ₁	Procurement cost of total MC device population (i. e., used in all systems being acquired under a program procurement).
	PCER ₂	Total screening cost for upgrading desired MC types to higher quality grades.
	PCER ₃	Total card assembly cost (excluding PCER ₂) of all cards effected by the MC devices under consideration.
	PCER ₄	The total cost incurred by cards going through card test and system test. This CER includes a test-rework cycle based on card yields at card-level and system-level testing.
MAINTENANCE AND SUPPORT (M&S)	MCER ₁	Initial and replenishment spares cost. Initial spares includes site and pipeline stockage. Replenishment spares are based on lifetime losses due to condemnation, pipeline "leakages" etc.
	MCER ₂	Support equipment cost consists of the development cost for test software and card adapters for fault isolation at the circuit card level.
	MCER ₃	Inventory entry and supply management costs for new MC devices and cards entered into government inventory.
	MCER ₄	Depot repair labor cost for fault verification and card repair.
	MCER ₅	Depot repair materials cost for card repair.
	MCER ₆	Two-way transportation cost for transporting failed (or suspected failed) cards during the repair cycle.

In using the model computer program and CER's in general, there are a number of ground rules and assumptions that should be noted. These are summarized below:

- All cost factors used in developing the CER's are based on FY 1980 dollars. FY 1980 is used as a "base year" from which all cost escalations are taken.
- LCC estimates are provided in constant, escalated and discounted dollars at sell (i.e., general and administrative factors and a nominal fee have been included) to the government. The rates for escalation and discounting are user inputs with a default to 6% and 10%*, respectively.
- Program phase start dates (i.e., RDT&E, Production and M&S) are user inputs with defaults to FY 1980 start for RDT&E and Production with O&S starting in FY 1981. If a start date other than FY 1980 is used, all cost factors (including default values) are escalated to the new base year.
- Program phase schedules are user inputs for RDT&E and Production with default to zero for RDT&E and one (1) year duration for Production. If multiple year phases are input, the total cost for the phase is allocated uniformly. The schedule for the O&S phase is automatically computed for 5, 10 and 15 years.
- Although it is reasonable to extend the ranges of the MC CER variables to values not included in the data base, care should be exercised to select valid combinations (i.e., a normal physical relationship must be retained.) In this sense the CER parameters are not free to vary in an arbitrary way to investigate cause-and-effect relationships.
- The CER's developed in this study are not applicable to hybrid technology. There was not sufficient data to develop statistical relationships or make meaningful comparisons. However, Hughes has conducted an independent study of hybrid fabrication techniques and costs including a model for estimating fabrication costs.⁶
- Finally, the CER's developed in this study are intended for comparative cost analysis as in design tradeoffs rather than absolute estimation. Thus, common costs which are not sensitive (directly or indirectly) to differences in MC characteristics have been neglected.

1.3 GENERAL EFFECTS OF MC CHARACTERISTICS ON LCC

The MC characteristics (or factors) effecting LCC are discussed in Section 2.3. A large number of factors were considered, a reasonable number of which proved to be good predictors of cost in the CER's. MC factors which were not included in

*Per DOD Instruction 7041.3, Economic Analysis of Proposed Department of Defense Investments.

the CER's were omitted for various reasons or combinations thereof. Typically, these were:

- Insufficient data to make statistical inferences.
- Variations in the dependent variables (i. e., cost, labor hours etc.) already explained by other more important MC factors.
- No significant relationship exists between the factor and the dependent variable.

The following paragraphs summarize the general effects of those MC factors which can have a significant impact on system LCC.

Technology - Device Technology (i. e., bipolar, MOS, ECL, ITL etc.) has an obvious effect on the purchase cost of the device. Not surprising, the most significant factors to consider are whether the device is bipolar or MOS. Bipolar devices are more expensive than MOS particularly in the case of memories. Also, whether or not the device uses ECL logic has a significant effect on increasing the purchase cost. At the card level and higher levels of assembly, device technology exhibits no appreciable affect on assembly and test costs.

Function - As a general rule, memory devices are significantly more expensive to purchase than other functions. MOS memory devices, the exception, are generally less expensive than other functions. Cards with RAM devices tend to have more complex associated circuitry (see below) and, therefore, are more expensive to assemble than cards without RAMS. The percent of MC devices that are RAM's can, therefore, be used as a measure of the card assembly cost. Figure 1.4-1 illustrates the general relationship between fraction of RAM devices used, card density and card assembly costs. Using percentage of RAM usage as a measure of card complexity, Figure 1.4-1 shows that cards containing 25 percent RAM's are approximately twice as expensive to assemble as cards that contain no RAM's. Other device functions, such as decoders, counters, line drivers, etc., showed no significant correlation with cost.

Packaging - The only difference that was discernable in device packaging was whether a dual-in-line package (DIP) or flat-package (FP) was used. Hermeticity was a factor but not significant enough for use in any of the CER's. FP devices are more expensive to procure but, except for material costs, do not have any significant effects on card assembly or test costs. Cards using FP devices are probably more expensive (because of hand wiring) than cards using DIP devices; however, there was not sufficient data to test this premise. Hughes primarily uses DIP devices in card assembly or a mix of DIP's and FP's.

Complexity - The number of gates per device had an effect on the cost of device development (RDT&E), device procurement and device screening (for quality upgrade). Figure 1.4-2 gives the development cost per gate for custom LSI devices

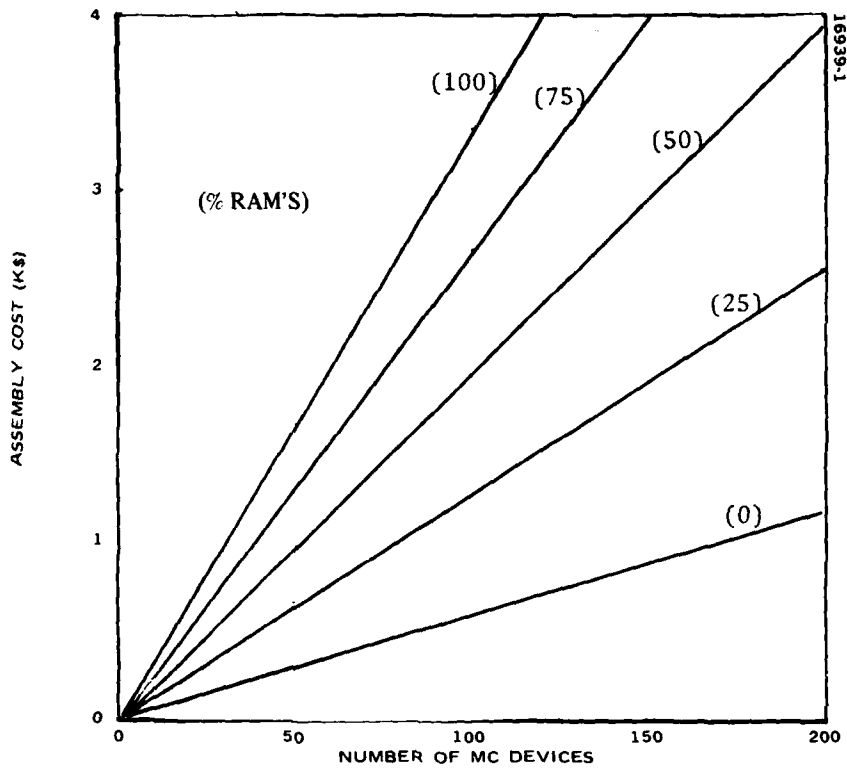


Figure 1.4-1. Card Density vs Assembly Cost

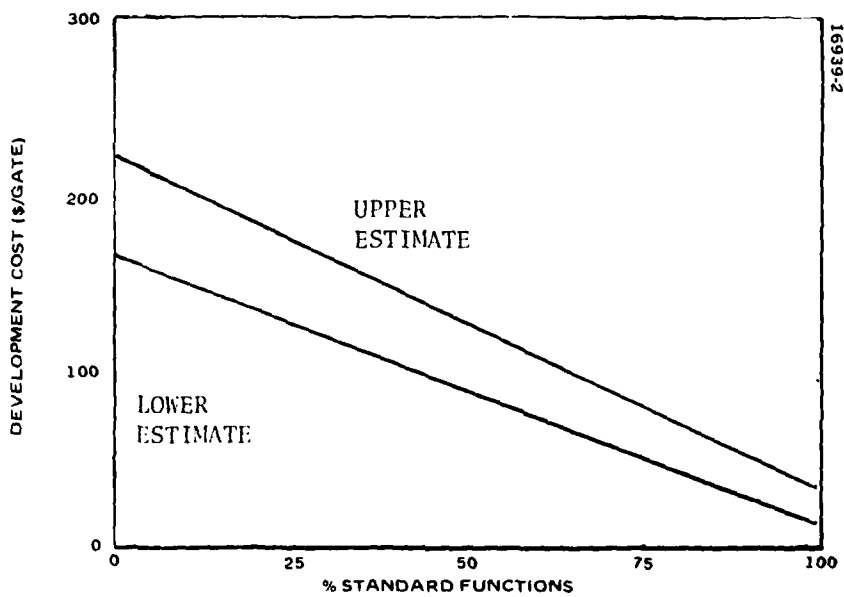


Figure 1.4-2. LSI Development Cost Per Gate

as a function of the fraction of standard (already developed) functions. The upper and lower bounds in the figure are extrapolations from published data. For example, the development cost for a 2000 gate device utilizing 50% standard functions would range from \$180K to \$250K depending on functional complexity. Differences in the device complexity also has an effect at the card level particularly if the devices are linear. Figure 1.4-3 illustrates the impact of increasing complexity on card test labor for various mixes of linear devices. For a 1K gate card which contains 25% linear devices the test labor is approximately 5.5 hours. This compares to a digital card of the same gate count which requires approximately 2 hours testing.

Quality/Reliability - Device quality grade affects procurement cost when considered on a per gate or per BIT basis. For off-the-shelf available devices, reliability is not a significant factor in cost determination particularly at the higher gate or BIT counts. At the card level, reliability had a very significant effect on the card test-rework cycle. The number of MC devices which are of quality grade B-2 or lower has significant correlation with test yield. Figure 1.4-4 gives the fractional yield at card test as a function of fraction MC devices with quality grade B-2 or lower using a 100-device card. A 75% MC device usage is assumed on the card. The figure shows that as the number of linear MC devices increases, the yield at card test becomes lower.

Other MC Factors - Card density (i.e., quantity of devices per card) has an effect on higher assembly test yield which becomes more significant as the usage of MC devices increases (see Figure 1.4-5). For example, cards that contain 100 devices all of which are MC's will have an assembly test yield of approximately 83 percent.

When a change in device family results in a re-partitioning of the system (eg, from SSI/MSI devices to LSI devices), government inventory, spares and lifetime maintenance costs can be effected. Figure 1.4-6 illustrates the impact of introducing new items (devices, cards, etc.) into government inventory and maintaining these items for 15 years. These costs are also a function of the number of base supply systems involved in which card inventories must be maintained (see Section 3.3.4). If, for example, 30 new device types are inventoried the 15 year maintenance cost would be approximately \$60K. If, 10 new card types are also inventoried at 5 base supply systems, an additional cost of \$50K would be incurred for a total cost of \$110K.

The effect of a change in device family on sparing, support equipment and depot maintenance is dependent on a large number of system-level and logistic support considerations. These effects are best illustrated by examples using the LCC model (see Section 4.2).

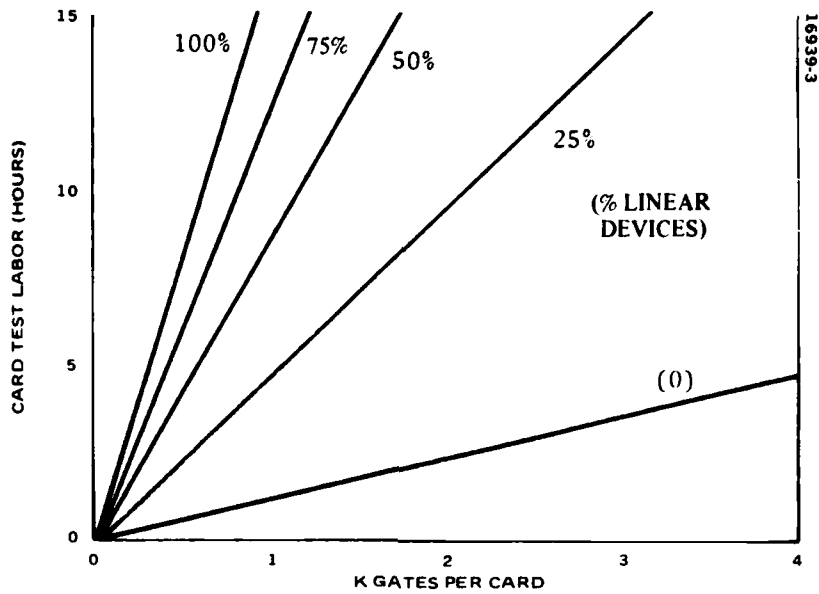


Figure 1.4-3. Card Complexity vs Card Test Labor

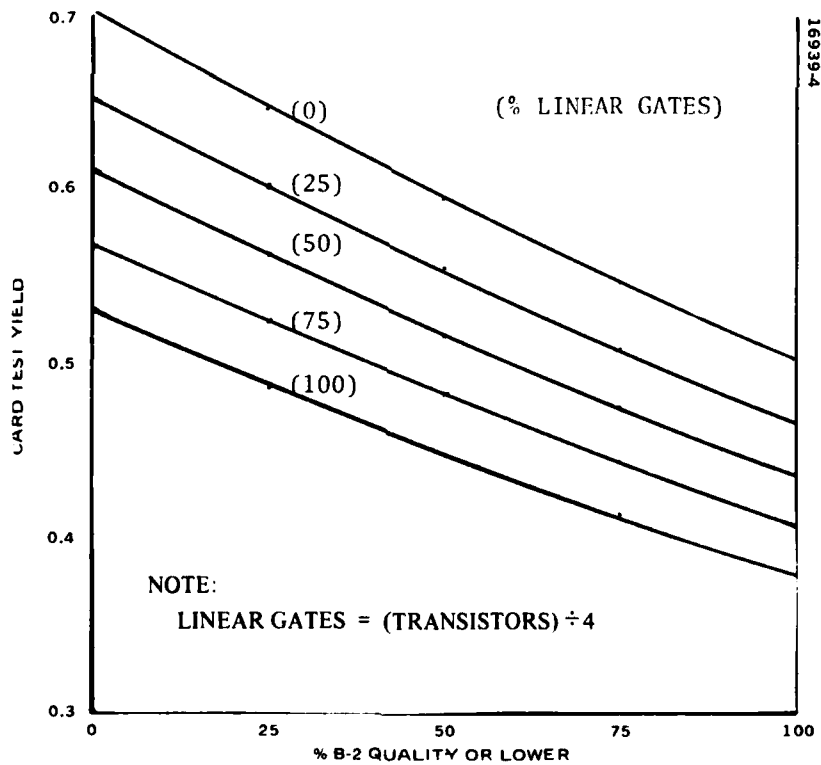


Figure 1.4-4. Device Quality vs Card Test Yield (100 Devices Per Card with 75% MC)

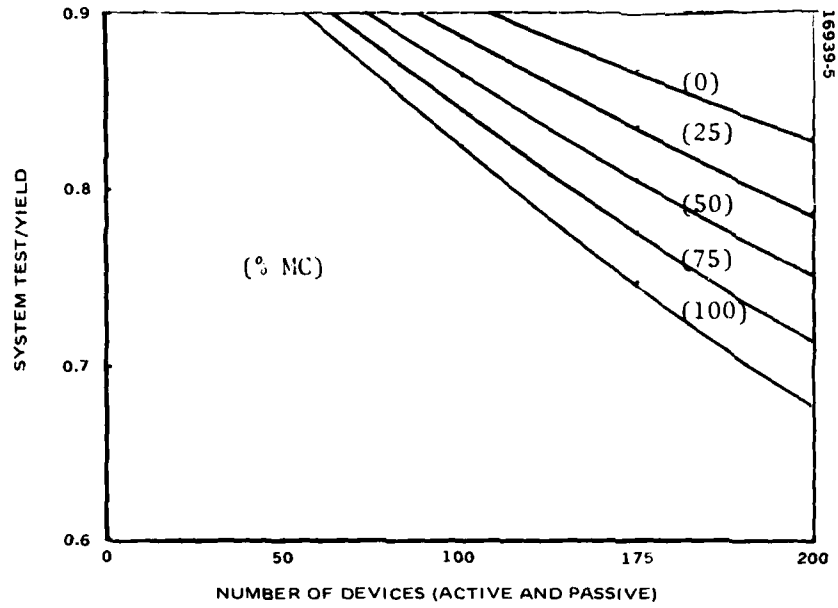


Figure 1.4.5. Card Density vs System Test Yield

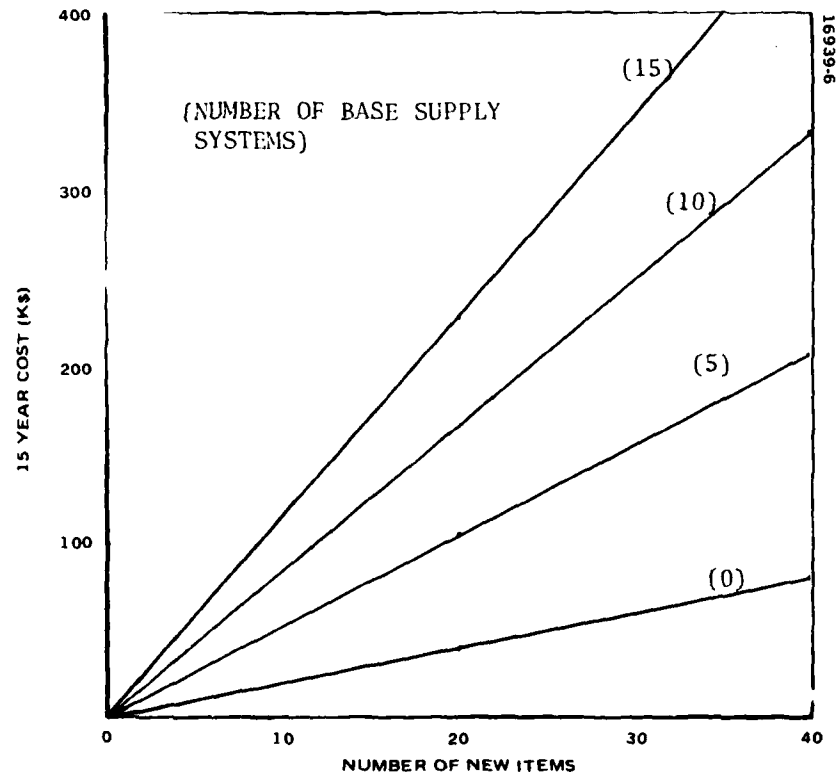


Figure 1.4.6. Inventory Entry and Supply Management Cost

Section 2.0

DATA BASE DESCRIPTION

2.1 SOURCES OF DATA

In order to provide a statistically significant data base for the prediction model, fifteen systems/product lines in current manufacture at Hughes were surveyed.

From the surveyed systems, seven were selected to provide the study data base. The criteria for selection of the seven systems were:

- a) Systems selected must represent a variety of equipment types.
- b) Formal reliability analysis and prediction per MIL-HDBK-217C must have been completed on the system.
- c) The systems must be of recent vintage (i.e., post 1970), employing current state-of-the-art MC technology.
- d) Data collected on the systems must be relatable to MC cost factors considered in this study.

The product lines and card types used in the data base are given in Table 2.1-1. Within each product line a wide variety of card types were selected to enhance the range of applications for the MC parameters under consideration. For each product line, data was collected according to four sources: Plant, Program, Card and Device. The MC characteristics for which data was collected from these sources is summarized in Section 2.3.

Plant or factory level data could not be allocated to specific cards (i.e., by assembly number) or programs but did provide measures of the combined trend of the selected systems. Such data was used only when obtaining lower level data was impractical or statistically meaningless. Plant level sources of data include labor logs on card-rework (exclusive of fault isolation and checkout testing labor which was accessible at the card level), system test (i.e., labor required to fault isolate to the card level), and device reliability upgrade data.

Table 2.1-1. Systems and Card Configurations Used in Data Base

Production Line	Card Function	Type	Percent MC Devices
Micro-Computer	Memory Interface	Digital	44
	Arithmetic Register	Digital	52
	External Register Control	Digital	51
	Serial Channel Interface	Digital	45
	Memory (ROM)	Digital	31
	Power Fault Determinator	Mix, Digital/ Linear	34
	BITE Power Supply	Linear	9
Display Console	Refresh Memory	Digital	32
	Sweep Generator	Mix, Digital/ Linear	65
	Line Generator	Mix, Digital/ Linear	14
General Purpose Computer	Memory Control Timing	Digital	48
	Electrical Memory Card	Digital	33
	Memory Input Switch	Digital	54
	Effective Address Logic	Digital	37
	16 BIT Microprocessor	Digital	49
Communications Terminal	Memory Interface	Digital	55
	Indicator Logic	Digital	37
	Correlator Preamble	Mix, Digital/ Linear	15
Submarine Fire Control System	Test Sensor/Focus Programmer	Linear	6
	Clock Generator	Linear	15
	Counter Digital Rate Multiplier	Linear	77

Table 2.1-1. Systems and Card Configurations Used in Data Base (Continued)

Production Line	Card Function	Type	Percent MC Devices
Submarine Fire Control System (Continued)	Deflection Counter/Monobit Encoder	Digital	80
	Pincushion Correction	Linear	5
	Data Select	Digital	67
	Test Logic	Digital	65
	Display Control A	Digital	79
	Display Control B	Digital	74
	Display Control C	Digital	81
	Edit Control Generator	Digital	69
	Symbol Integrator/Reference Supply	Linear	72
	Stroke Control	Digital	81
	ROM A	Digital	41
	ROM B	Digital	39
	ROM C	Digital	37
	Symbol Address	Digital	78
	Intensity Compensation and Gating	Linear	1
	Digital Logic	Digital	69
	Panel Interface	Digital	79
Test Logic Sensor	Linear	2	
Mortar Locating Radar	Integrated clutter map	Mix, Digital/Linear	55
	Modulated Frequency Shift	Linear	14
	Easting Driver	Digital	36
	Microprocessor Controller	Digital	37
	External Control Register	Digital	50

Table 2.1-1. Systems and Card Configuration Used in Data Base (Continued)

Production Line	Card Function	Type	Percent MC Devices
Mortar Locating Radar (Continued)	Diagnostic Interface	Digital	40
	Doppler Filter	Linear	60
	4K RAM	Digital	34
	MLVL Signal Generator	Linear	53
	ROM Circuit	Digital	46
	Gate	Digital	45
	Data Path Communication	Digital	51
	Dual Channel Control	Digital	49
Artillery Locating Radar	RAM	Digital	51
	Analog-Digital Convertor	Mix, Digital/ Linear	6
	Signal Generator	Linear	52
	Microsequencer	Digital	49
	Synchronizer	Digital	47
	Target/Bite	Digital	50
	Dual Channel Control	Digital	30
	Clock Oscillator	Linear	32
	Multiplexer	Digital	40
	Gate	Digital	67
Canceller	Digital	59	

Program level data could be allocated to a specific program but not to specific cards. Program level data were gathered on this level only when lower level data were inaccessible or statistically meaningless. Sources of program level data include card defect analysis reports for specific product lines.

Card level data consisted of specific cards (by assembly number) with known MC characteristics. Such data had the highest priority during the data collection effort. Sources of card level data consisted of card assembly cost reports, quality control defect analysis reports, system test defect analysis reports and configuration parts lists used in reliability and maintainability predictions.

Device level procurement data account for specific MC device types and was collected from purchase price lists. Data on research, development, test and evaluation (RDT&E) for custom and semi-custom LSI devices was obtained from internal pricing guides and from data in the literature survey (see 3.1.1).

Section 3 contains a detailed description of the data used for each CER. Sources for cost data and factors applicable to the support phase of the life cycle were provided by Government standards. Table 2.1-2 summarizes the sources of data used for developing the MC CER's. The references indicated provide a detailed discussion of MC parameters used and CER development.

2.2 DATA PROCESSING METHODOLOGY

In order to determine which MC parameters had a significant effect on various system costs and to provide accurate CERs, a multiple linear regression technique was employed. The basic assumptions of this technique are:

- 1) The dependent variable Y (cost, labor hours, etc.) is a linear combination of p independent variables (MC characteristics, card characteristics, etc.) This relation is called a regression equation, and in matrix notation the model may be represented in the form:

$$(2-1) \quad Y = XB + e$$

where

Y is a (nX1) vector of observations of the dependent variable.

X is a (nXp) matrix of observations of the independent variables.

B is a (pX1) vector of parameters (CER coefficients) to be estimated.

e is a (nX1) vector of errors

- 2) The elements e_i $1 \leq i \leq n$ of the vector e represent values of a normally distributed random variable. This assumption is reasonable since the error term is most probably the sum of errors from a large number of sources and, therefore, by the Central Limit Theorem their sum will have a distribution that will be approximately normal regardless of the type of probability distribution the separate error components may have.

Table 2.1-2. Summary of Data Sources for CER's

Cost Estimating Relationship		Data Source	Section Reference
Description	Code		
RDT&E for Custom IC's	RCER	Literature Search, Plant Level	3.1.2
Device Procurement	PC ER ₁	Device Level	3.2.2
Device Screening	PC ER ₂	Device Level	3.2.3
Card Assembly	PC ER ₃	Device Level, Card Level	3.2.4
Card-Test-Rework Cycle:	PC ER ₄		
● Card Test Labor	H	Device Level, Card Level, Program Level	3.2.5.1
● Card Test Yield	YC	Device Level, Card Level, Program Level	3.2.5.2
● System Test Yield	YS	Device Level, Card Level, Program Level	3.2.5.4
● System Repair	C2	Plant Level	3.2.5.5
● Card Rework	C3	Program Level, Plant Level	3.2.5.3
Spares	MC ER ₁	Card Level, Government Standards	3.3.2
Support Equipment	MC ER ₂	Plant Level	3.3.3
Inventory Entry and Supply Management	MC ER ₃	Government Standards	3.3.4
Repair Labor	MC ER ₄	Card Level, Government Standards	3.3.5
Repair Materials	MC ER ₅	Government Standards	3.3.6
Maintenance Transportation	MC ER ₆	Government Standards	3.3.7

- 3) $E(e) = 0$, $V(e) = I\sigma^2$, where I is the identity matrix, so the elements of e are uncorrelated. That is, $E(Y) = XB$. The error sum of squares for the system is:

$$\begin{aligned} e'e &= (Y - XB)'(Y - XB) \\ &= Y'Y - 2B'X'Y + B'X'XB \end{aligned}$$

By differentiating this equation with respect to B and setting the resulting equation to zero and replacing B by b , the normal equations result:

$$\begin{aligned} (2.2) \quad (X'X)b &= X'Y \\ b &= (X'X)^{-1} X'Y \end{aligned}$$

This solution b , called the least squares estimate of B , has the property of being the best linear, unbiased, estimate. Further details are given in Draper and Smith.¹

Multi-linear regression analysis is expedited by using the UCLA Health Sciences Bio-Medical multi-linear regression computer program (BMD02R).² This regression analysis computes a sequence of multiple linear equations in a step-wise manner. The procedure moves step by step from one regression to the next, adding a predictor (forward regression) or deleting a predictor (backward regression) at each step. This produces a sequence of regression functions:

$$\begin{aligned} (2.3) \quad y &= b_0 + b_1 x \\ y &= b'_0 + b'_1 x_1 + b'_2 x_2 \\ y &= b''_0 + b''_1 x_1 + \dots + b''_p x_p \end{aligned}$$

Rather than adding predictors in order, the program steers the additions/deletions by three statistical tests:

- The F-to-enter statistic for a predictor is the F-statistic for testing the significance of the regression coefficient the predictor would have if it were added. (A predictor will not be entered if its F-to-enter value is below a specified threshold.)
- The F-to-remove statistic of an entered predictor is simply the value of the F-statistic used to test the significance of its regression coefficient. (If its F-to-remove value is less than a specified threshold, a predictor will be removed.)
- The tolerance of a non-entered predictor is one minus the square of the multiple correlation between this predictor and those predictors currently in the regression function. (The tolerance threshold is used to prevent the entry of highly correlated predictors and to avoid rounding error in the computations.)

Three rules control step operation:

- 1) If there are one or more predictors in the regression equation whose F value is less than the F-to-remove value specified, the one with the smallest F value will be removed.
- 2) If no predictor is removed by (1) and there are one or more independent variables not in the regression equation which pass the tolerance test, the one with the highest F value will be entered.
- 3) If no predictor is added or removed by (1) or (2) the stepwise procedure stops.

The ratio:

$$(2.4) \quad R^2 = \frac{\sum (\hat{Y} - E(Y))^2}{\sum (Y - E(Y))^2}$$

is the square of the multiple correlation coefficient and is a measure of the usefulness of the predictors in the CER model. R^2 measures the percent variation explained by the model. Thus, if the estimated values of the CER (\hat{Y}_i) equals the observed values (Y_i) for all $1 \leq i \leq N$ (i. e., if the prediction is perfect), then $R^2 = 1$. If $b_1 = b_2 = \dots = b_p = 0$ (or a model $Y = B_0 + e$ alone has been fitted), then $R^2 = 0$.

In developing a useful CER for a particular cost area, several of the equations (2.3) may be of value. Each successive step provides an equation which explains more of the variation (higher R^2) but also requires more independent variables for which the user must provide data. Thus, a selection of prediction equations with differing input requirements have been provided for most of the CER's developed from regressions. Section 3 provides a detailed description of the basic CER used in the LCC model and applicable alternate CER's.

2.3 MC FACTORS EFFECTING COST

In formulating the model CER's as many MC factors were considered as could be accommodated by the regression limits and data. Although many candidate cost predictors were considered during the study, only those found to be both physically meaningful and statistically significant were incorporated in each CER.

Table 2.3-1 provides a list of all MC factors (independent variables) which were considered to possibly have some influence on cost (dependent variable). Those MC factors that had significant impacts on cost are identified by an "X". The corresponding CER's in which they are employed are also given. These factors effect the various aspects of system cost directly through device development, procurement and/or testing, and also, indirectly, through their impact on card assembly, test and lifetime support. For example, device quality effects the cost of device procurement but also has an even greater impact on the card production cost through the card test yield. Similarly, since the cost per card

Table 2.3-1. MC Factors Effecting LCC

MC Factors			Applicable CER's
Description	Applicable to CER	Variable	
<u>Technology:</u>			
Linear	X	1-DIG	Device Purchase (PCER ₁ 3.2.2)
Bipolar	X	1-MOS	Device Purchase (PCER ₁ 3.2.2)
ECL	X	ECL	Device Purchase (PCER ₁ 3.2.2)
MOS (PMOS, NMOS & CMOS)	X	MOS	Device Purchase (PCER ₁ 3.2.2)
Digital	X	DIG	Device Purchase (PCER ₁ 3.2.2)
Bipolar	X	1-MOS	Device Purchase (PCER ₁ 3.2.2)
DTL			
TTL			
ECL	X	ECL	Device Purchase (PCER ₁ 3.2.2)
IIL			
MOS (PMOS, NMOS & CMOS)	X	MOS	Device Purchase (PCER ₁ 3.2.2)
Schottky			
Low-power Schottky			
Low-Power			
High Speed			
<u>Function:</u>			
Memory	X	MEM	Device Purchase (PCER ₁ 3.2.2), Device Screen (PCER ₂ 3.2.3)
RAM (QTY on Card)	X	NRAM	Card Assembly (PCER ₃ 3.2.4)
ROM			
PROM			
EPROM			
Decoders			
Counters			
Flip-Flops			
Dividers			
Line Drivers			
<u>Packaging:</u>			
DIP	X	1-FP	Device Purchase (PCER ₁ 3.2.2)
Flatpack	X	FP	Device Purchase (PCER ₁ 3.2.2)
Leadless			
Single Chip			
Beam Lead			
Hermetically Sealed			
<u>Complexity:</u>			
Gates (Qty on Device)	X	NG	RDT&E (RCER 3.1.2), Device Purchase Screen (PCER ₂ 3.2.3)
Digital (Qty on Card)	X	NDG	Card Test Hours (H 3.2.5), Repair Labor (MCER ₄ 3.3.5)
Linear (4-trans = 1 Gate; Qty on Card)	X	NLG	Card Test Hours (H 3.2.5), Card Test Yield (YC 3.2.5), Repair Labor (MCER ₄ 3.3.5)
Pins (Qty on Device)	X	NP	Device Screen (PCER ₂ 3.2.3)
BITS (Qty on Device)	X	NB	Device Purchase (PCER ₁ 3.2.2), Device Screen (PCER ₂ 3.2.3)

Table 2.3-1. MC Factors Effecting LCC (Continued)

MC Factors			Applicable CER's
Description	Applicable to CER	Variable	
<u>Quality/Reliability:</u>			
Quality Grade S			
B			
B-1			
B-2 and Below	X	QB2	Card Test Yield (YC 3.2.5)
Reliability (Weighted/MIL-STD-217C)	X	REL	Device Purchase (PCER ₁ 3.2.2)
<u>Combined MC Characteristics:</u>			
TTL, DTL			
Linear, Beam Lead, ECL			
MOS (Linear or Digital)	X	MOS	Device Purchase (PCER ₁ 3.2.2), Device Screen (PCER ₂ 3.2.3)
Digital Bipolar SSI/MSI, Digital MOS SSI/MSI			
Digital Bipolar LSI, Digital MOS LSI			
ECL (Linear or Digital)	X	ECL	Device Purchase (PCER ₁ 3.2.2)
IIL, Low-power TTL			
MOS Memory, Bipolar Memory			
AVG. Quality Grade/MIL-STD-217C			
<u>Other Considerations:</u>			
MC Devices (Qty on Card)	X	NMC	Card Test Hours (H 3.2.5), Card Test Yield (YC 3.2.5), System Test Yield (YS 3.2.5)
Devices Active and Passive: (Qty on Card)	X	NDEV	Card Assembly (PCER ₃ 3.2.4), Card Test Hours (H 3.2.5), Card Test Yield (YC 3.2.5), System Test Yield (YS 3.2.5)
Ratio Contrl. of MCs to the Card Failure Rate	X	W	Card Test Hours (H 3.2.5), Card Test Yield (YC 3.2.5), Spares (MCER ₁ 3.3.2), Repair Labor (MCER ₄ 3.3.5), Repair Materials (MCER ₅ 3.3.6), Main. Trans. (MCER ₆ 3.3.7)
Card Failure Rate	X	CF	Spares (MCER ₁ 3.3.2), Repair Labor (MCER ₄ 3.3.5), Repair Materials (MCER ₅ 3.3.6), Main. Trans. (MCER ₆ 3.3.7)

and card reliability are effected by device quality so is the cost of spares and maintenance support.

The effects of the MC characteristics on individual CER's are discussed in the appropriate subsections of Section 3.

Section 3.0

DESCRIPTION OF MODEL COST FACTORS

3.1 MC RESEARCH, DESIGN, TEST & EVALUATION (RDT&E)

3.1.1 LITERATURE SEARCH

In order to compare internal cost experience in custom/semi-custom LSI development, a literature search was conducted. The search was restricted to only recent publications going back three years. The data banks included in this search were DOD Documentation Center (DDC), National Technical Information Service (NTIS), the NASA Data Bank, and the Lockheed Dialog Information Retrieval Service. All journals, reports and general technical information on RDT&E costs associated with custom/semi-custom LSI devices were included.

There is a tremendous amount of literature on LSI devices. However, there seems to be a great reluctance to publish RDT&E cost data. Of the items listed in the searches only seventeen required closer review, and of these only three provided any useful information on RDT&E costs. These items are given in the bibliography. Of particular interest to this study is a comprehensive report on the application of LSI technology to military systems including an analysis of LCC.² This report was used to compare the various aspects of costs and trends in technology.

3.1.2 RDT&E (RCER)

The cost to develop an LSI device varies considerably depending on the complexity and the degree to which the device design can utilize standard already-developed functions. When standard gate arrays are employed the development cost per gate can be competitively low because the development of final metallization layers is all that remains, thus minimizing the design layout errors which reduces design, test and evaluation costs considerably. Completely custom LSI's are not cost competitive unless large quantities are procured or developed through functional standardization. How large the procurement must be is subject to tradeoff. As logic designs become more complex, the applications become more unique and, therefore, more costly to develop on a per device basis. On the other hand, microprocessors were developed as a method supplying a sufficiently large number of random logic functions to warrant their economical development. Therefore, functional standardization in LSI is

achievable through the microprocessor, and this appears to be the trend in the future in military electronics.^{5,8}

At the low cost end (i.e., using standard functions), the cost to develop an LSI device starting with the logic design can vary from \$12 to \$30 per gate (1977 dollars). At the high cost end, the cost can vary from \$150 to \$200 per gate (1977 dollars)^{4,7}. If these cost extremes are averaged and brought up to current 1980 dollars*, we can expect a variation of from \$24 per gate to \$203 per gate. Thus, for a 2000 gate device, the RDT&E cost in today's dollars would be:

	<u>K\$</u>
● Complete Custom - - - - -	406
● Standard Functions - - - - -	48

These values are in fairly good agreement with Hughes experience in estimating RDT&E for LSI devices.

The CER for RDT&E is based on the average cost per gate assuming a linear relationship between cost per gate and fraction of standard functions employed. Thus, the total RDT&E for N device types is given by:

$$(3.1) \quad RCER = \sum_{i=1}^N NG(i) \left[\left(C_{MIN} - C_{MAX} \right) \frac{F(i)}{STD} + C_{MAX} \right]$$

where:

$NG(i)$ = Total gate count of i^{th} device type.

C_{MIN} = Cost per gate using standard functions (\$24)

C_{MAX} = Cost per gate for complete custom device (\$203)

$F(i)_{STD}$ = Fraction made from standard functions, i^{th} device type.

Since there are large variances in the cost per gate in (3.1) based on the LSI manufacturer's unique design process, the values of C_{MIN} and C_{MAX} are user inputs in the LCC model. The values given above are provided as defaults when the user has no better information.

The development cost of custom LSI's can also be off-set to some degree by reducing the number of items to be inventoried, documented and spared, and by simplifying system design (e.g., less complex back-plane wiring). In any event, the total cost picture needs to be examined before a clear economic decision can be made.

*A compound rate of 5% is used. Although this rate is low with respect to the inflation of the past few years, it has been off-set by advances in the LSI development technology which have tended to reduce costs.

3.2 PRODUCTION INVESTMENT

3.2.1 MANUFACTURING MODEL

Figure 3.2.1-1 illustrates the flow of MC devices through the manufacturing process. Starting with device procurement (PCER₁) the devices are (possibly) screened to a higher reliability grade (PCER₂) and mounted on circuit boards (PCER₃). The circuit board (cards) are then tested at the card-level and system level (PCER₄) before final acceptance of the "host" system by the contracting agency. During card-level and system testing, MC device failures occur which cause the card to go through a rework-retest cycle indicated by the "feed-back" loops in the figure. Failures other than MC devices, of course, will also occur but we are only considering the impact on LCC of MC device failures. Once the devices have been mounted on cards, it is at this step in the process that the card and, therefore, the devices start accumulating "hidden" costs.

As a quantity of cards of a particular type (i.e., a unique function) is processed through Card Test and System Test (i.e., all higher assembly testing) a portion of these cards fail card test and a portion pass on to the system level. Similarly, at the system level a portion will fail and a portion will become part of the system. Those cards failing at either test are sent to rework after which they must repeat the process at the card and system level. Thus, with yields of Y_c at the card-level and Y_s at the system level, the cumulative effects on the card cost can be computed.

The probability that a card fails card test and is sent to rework is $(1-Y_c)$ and the probability that a card passes card test and fails system test is $Y_c(1-Y_s)$. Thus, the probability that a card is sent to rework, either from the card level or system level is simply: $(1-Y_c) + Y_c(1-Y_s) = 1-Y_cY_s$.

Clearly, the number of cards entering the process at the n^{th} cycle (X_n) is equal to the number of failures of those processed on the previous cycle (X_{n-1}) and so forth, i.e.:

$$(3.2) \quad X_n = X_{n-1}(1-Y_cY_s) = X_{n-2}(1-Y_cY_s)^2 = \dots = X_1(1-Y_cY_s)^{n-1}$$

If C_1 , C_2 and C_3 are the card test cost, system test cost and rework cost, respectively, the total cost of processing X_n cards is:

$$X_n C_1 + X_n Y_c C_2 + X_n (1-Y_c Y_s) C_3$$

or, $X_n [C_1 + C_2 Y_c + C_3 (1-Y_c Y_s)]$

or, $X_1 (1-Y_c Y_s)^{n-1} [C_1 + C_2 Y_c + C_3 (1-Y_c Y_s)]$

Hughes' manufacturing experience indicates that it is rare for cards to be scrapped as a result of cumulative damage incurred during the rework process. Therefore, as a good approximation, the process can be summed up as an infinite geometric series:

$$\sum_{n=1}^{\infty} X_1 [C_1 + C_2 Y_c + C_3 (1-Y_c Y_s)] (1-Y_c Y_s)^{n-1} = X_1 [C_1 + C_2 Y_c + C_3 (1-Y_c Y_s)] / (Y_c Y_s)$$

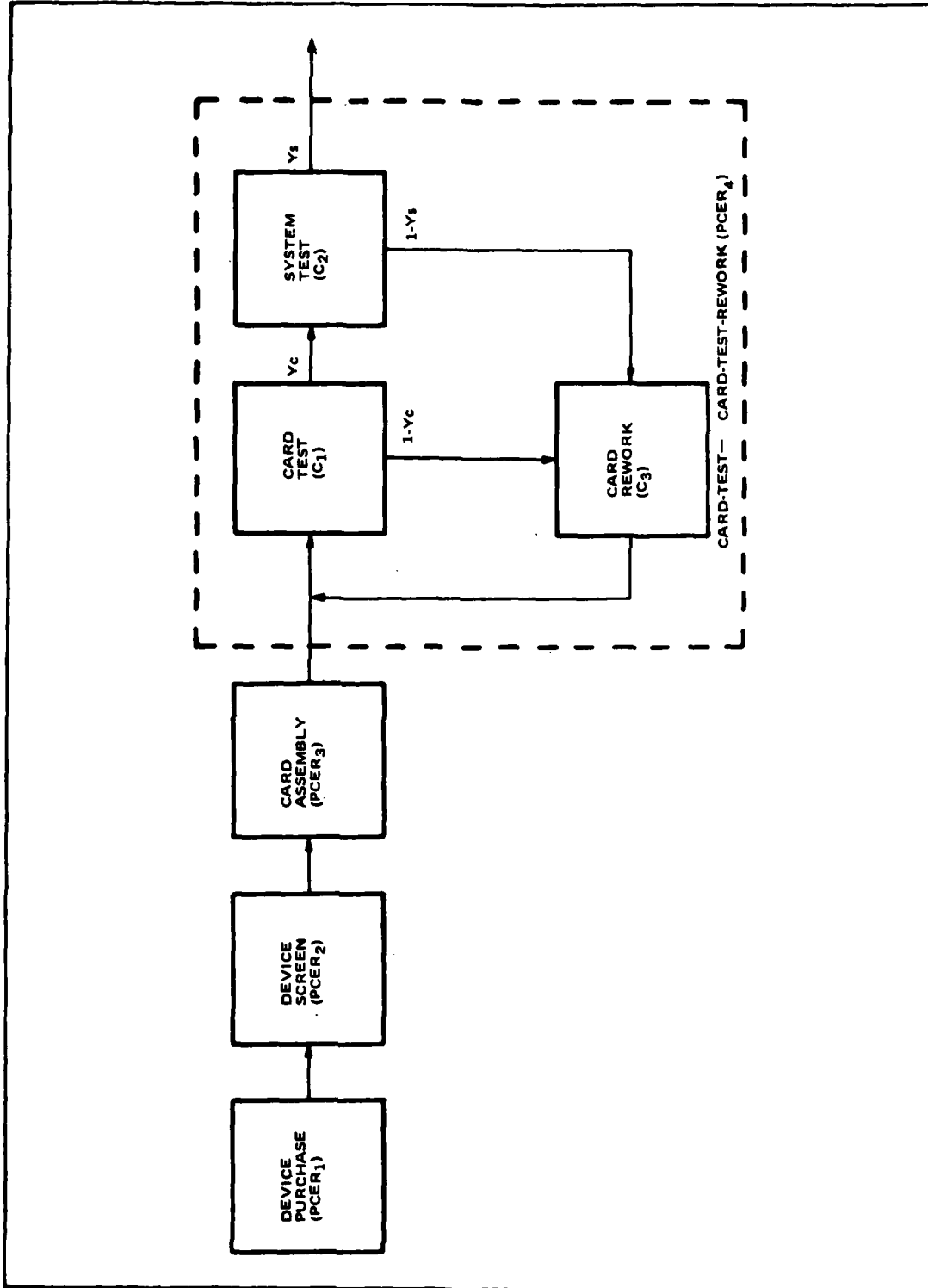


Figure 3.2.1-1. Manufacturing Process Model

where

$$0 < 1 - Y_c Y_s < 1$$

If X_1 represents all the cards required by the production program, then:

$$(3.3) \quad PCER_4 = X_1 \left[C_1 + C_2 Y_c + C_3 (1 - Y_c Y_s) \right] / Y_c Y_s$$

The total production cost (C_{PROD}) with appropriate summation across device types (N) and card types (N_c) is therefore given by:

$$(3.4) \quad C_{PROD} = \sum_{i=1}^N \left[PCER_1(i) + PCER_2(i) \right] DEVQ(i) + \sum_{i=1}^{N_c} \left[PCER_3(i) + PCER_4(i) \right] CARD(i)$$

Formulated CER's have been developed to predict each area of the manufacturing process which is sensitive to differences (either directly or indirectly) in MC characteristics. The details of these developments are provided in Sections 3.2.2 through 3.2.5. The effects of other costs (i.e., device supplier qualification costs, device obsolescence, on-shore versus off-shore procurements, etc.) are discussed in Section 3.4. In the following sections the subscript denoting the i^{th} device or card type will be dropped.

3.2.2 DEVICE PROCUREMENT ($PCER_1$)

Data was collected from two main sources:

- HAC Vendor Integrated Circuits Pricing Agreement
- Linear, Digital, Memory and Interface Integrated Circuits D. A. T. A. Books of the Electronic Information Series

For each MC device according to device number, the Integrated Circuits Pricing Agreement enabled the determination of device technology, packaging (Dual inline package, flat package, etc.) reliability grade, whether or not the device was hermetically sealed and unit cost. The D. A. T. A. books then provided information on the device type and function, number of gates, and number of bits for memory devices. The reliability grades were assigned weightings according to MIL-STD-217.

Table 3.2.2-1 identifies the MC device characteristics that provided significant correlations with purchase cost. Sixty nine data points were used to test nineteen MC characteristics using the stepwise regression procedure. Table 3.2.2-2 provides the applicable CER's for estimating the unit cost of an MC device with given characteristics. The complete regression runs are given in Appendix A-2.

TABLE 3.2.2-1 DEVICE PROCUREMENT VARIABLE DESCRIPTION

VARIABLE	DESCRIPTION	UNITS	RANGE
PCER _i	PROCUREMENT COST PER DEVICE	\$	0.24 - 30.79
MEM	MEMORY DEVICE	Indicator ⁽¹⁾	0, 1
DIG	DIGITAL LOGIC DEVICE	Indicator	0, 1
ECL	ECL DEVICE	Indicator	0, 1
MOS	MOS DEVICE	Indicator	0, 1
FP	FLATPACK DEVICE	Indicator	0, 1
REL	RELIABILITY	(2)	0.0 - 35.
GATES	NUMBER OF GATES	QTY	0 - 68
BITS	NUMBER OF BITS	QTY	0 - 16384

(1) The indicator has value "1" if the characteristic is present, "0" otherwise.

(2) The following weightings were employed for the given quality grades:

QUALITY GRADE	S	B	B-1	B-2	C	C-1	D	D-1
RELIABILITY FACTOR	0.5	1.0	3.0	6.5	8.0	13.0	17.5	35.0

Using the coefficients (C's) in the table, the basic CER is:

$$(3.5) \quad PCER_1 = \text{EXP} (.52165 + 1.38197 \cdot \text{MEM} - .69142 \cdot \text{DIG} + 1.84202 \cdot \text{ECL} \\ - 2.70211 \cdot \text{MOS} + .56445 \cdot \text{FP} - .22443 \cdot (\text{REL}/\text{GATES}) \\ - 9.83248 \cdot (\text{REL}/\text{BITS}))$$

The alternate CER's given in the table can be written in a similar manner. The indicator variable MEM was found to explain most of the variation (approximately 30%) in device cost.

It should be noted that the cost computed by PCERI is for off-the-shelf devices in large quantity procurements. For a new device (eg, a custom LSI), a learning curve should be applied to the CER as follows (see Section 3.4.1 for a discussion of learning curve applications):

$$(3.6) \quad PCER'_1(X) = AX^\alpha$$

TABLE 3.2.2-2 CER's FOR DEVICE PROCUREMENT

CER	CONSTANT	INDEPENDENT VARIABLE								R	VARIABLES REMOVED
		MEM	DIG	ECL	MOS	FP	(REL/ GATES)	(REL/ BITS)			
BASIC	C1 .52165	C2 1.38197	C3 -.69142	C4 1.84202	C5 -2.70211	C6 .56445	C7 -.22443	C8 -9.83248	.85	-----	
1	.02207	1.84461	-----	1.58816	-2.66517	.60918	-.20841	-9.15497	.84	DIG	
2	.29528	1.90967	-----	1.66451	-3.00344	-----	-.23836	-11.35440	.80	DIG, FP	
3	.29312	1.69924	-----	1.66570	-----	-----	-.23799	-9.29049	.76	DIG, FP, MOS	

$$PCER_1 = EXP (C1 + C2 \cdot MEM + C3 \cdot DIG + C4 \cdot ECL + C5 \cdot MOS + C6 \cdot FP + C7 \cdot (REL/GATES) + C8 \cdot (REL/BITS))$$

where:

$PCER'_1(X)$ = Adjusted unit cost for a procurement of X devices.

A = Adjustment factor for converting off-the-shelf unit cost ($PCER_1$) to the theoretical first unit cost

X = Procurement quantity

α = Learning slope factor

3.2.3 DEVICE SCREENING ($PCER_2$)

Data for the Device Screening CER was assembled based on Hughes internal device screening procedures per MIL-STD-883B, Method 5004.4 and MIL-M-38510D for general purpose microelectronic devices. Manpower, labor grades and material costs to perform the screening procedures were considered with respect to the general level of complexity of MC devices. In addition, memory devices are more expensive to test than non-memory devices, primarily because of the extra time spent in electrical test and the burn-in material costs. The average labor hours and costs given in Table 3.2.3-1 were allocated on a per-device basis, although actual estimating was achieved on a lot sizes of 50 - 100 devices.

For interim and final electrical testing, it is assumed that an automatic tester is used. The figures in the table represent labor required using a Sentry Tester. If bench testing is used, however, the labor required could be 3 to 4 times that shown in the table.

It should be noted that when device screening is employed, 100% testing is assumed. Also, destructive physical analysis per MIL-STD-38510D which is sometimes performed on a sampling basis is not included in the CERs since this is an insignificant cost for reasonable procurement quantities.

The resulting quality grade of screened MC devices is B-1. If a device is new, additional Engineering labor hours (non-recurring) is incurred to set up the computer programming for the Sentry Tester as a function of device complexity:

- SSI/MSI Non-Memory Devices - - - - - 20 Hours
- SSI/MSI Memory Devices - - - - - 80 Hours
- LSI Devices - - - - - 180 Hours

The CER data for device screening is summarized in Table 3.2.3-2. The general form of the Device Screening CER is:

$$(3.7) \quad PCER_2 = \left\{ [L_1(j) \cdot RATE4 + L_2(j) \cdot RATE5 + K(j)] \cdot DEVQ + S(j) \cdot RATE4 \right\} / DEVQ$$

where: $PCER_2$ = Total Screening Cost per Device Type

$L_1(j)$ = Engineering labor for device category j (Hrs.)

$L_2(j)$ = Technician labor for device category j (Hrs.)

TABLE 3.2.3-1 DEVICE SCREENING LABOR AND COST FACTORS

DEVICE SCREEN/PROCESSING	METHOD & TEST CONDITION	NON-MEMORY SSI/MSI			MEMORY SSI/MSI			LSI		
		LABOR (HRS.) ENGINEERING	LABOR (HRS.) TECHNICIAN	COST (\$)	LABOR (HRS.) ENGINEERING	LABOR (HRS.) TECHNICIAN	COST (\$)	LABOR (HRS.) ENGINEERING	LABOR (HRS.) TECHNICIAN	COST (\$)
Stabilization Bake (No End point Measurements Required)	1008, 24 Hrs. Min. Test Condition C Min	--	.0005	--	--	.0005	--	--	.0005	--
Temperature Cycle	1010, Test Condition C	--	.0005	--	--	.0005	--	--	.0005	--
Constant Acceleration	2001, Test Condition E (Min) Y1 Orientation only	--	.02	--	--	.02	--	--	.02	--
Seal: A) Fine B) Gross	1014	--	.04 .04	--	--	.04 .04	--	--	.04 .04	--
Interim Electrical	Per Applicable Device Specification	.01	.02	--	.01	.04	--	.04	.24	--
Burn-In:	1015, 160 Hrs. at 125°C Min.	--	.01	--	.02	.01	--	.04	.04	--
A) Sockets B) Components C) Materials		--	--	--	--	--	11.75	--	--	53.00
		--	--	--	--	--	2.00	--	--	12.00
		--	--	--	--	--	--	--	--	7.00
Final Electrical	Per Applicable Device Specification	.00917	.05	--	.02417	.22	--	.04417	.6	--
External Visual	2009	--	.05	--	--	.05	--	--	.05	--
Clerical		--	.02	--	--	.02	--	--	.02	--
Serialization		--	.04	--	--	.04	--	--	.04	--
Data Log Delta Measurements		--	.1	--	--	.1	--	--	.1	--
Marking		--	.02	--	--	.02	--	--	.02	--
Totals Per Device		.01917	.411	--	.05417	.601	13.75	.12417	1.191	72.00

TABLE 3.2.3-2 CER DATA FOR DEVICE SCREENING

CER	ENGINEERING LABOR (HRS.) L ₁ (j)	TECHNICIAN LABOR (HRS.) L ₂ (j)	OTHER CHARGES (\$) K(j)	SENTRY SOFTWARE FOR NEW DEV. S(j)
Non Memory SSI/MSI	0.0192	0.411	--	20
Memory SSI/MSI	0.0542	0.601	13.75	80
LSI	0.1242	1.191	72.00	180

K(j) = Total other costs for device category j(\$)

S(j) = Engineering labor to program the Sentry Tester for new devices for Device category j (Hrs.)

RATE4 = Engineering labor rate (\$/HR)

RATE5 = Technician labor rate (\$/HR)

3.2.4 CARD ASSEMBLY (PCER₃)

The card assembly process consists of 1) card kitting where all devices (MC devices plus supporting non-MC devices) defined for a unique card function are brought together for assembly, 2) card preparation (etch), 3) device lead preparation and tining, 4) axial and DIP insertion, and 5) device mounting (e.g., machine wave solder and/or hand solder). Rather than develop a single CER describing MC device purchase as part of the card assembly cost, separate CERs were developed to take advantage of separate sources of data in which:

- (1) the sample size of device purchase costs could be much larger, and
- (2) a greater number of independent MC characteristic could be considered as variables.

Thus, the card assembly CER does not contain the cost of MC devices but does include the cost of all supporting non-MC devices.

The basic sources of data for the card assembly CER were the Project Assembly Cost Reports. These reports allocate material and over-all assembly costs of specific cards (by part number) with known MC characteristics. MC material costs were deleted from these reports (to avoid "double counting MC procurement cost), and the remaining data (including the cost of supporting non-MC devices) were then regressed against the known MC characteristics of the corresponding card.

Two variables were found which correlated significantly with card assembly cost (see Table 3.2.4-1). Not surprising, the number of devices per card (NDEV) is the most significant single MC factor relating to card assembly costs. The number of

TABLE 3.2.4-1 CARD ASSEMBLY VARIABLE DESCRIPTION

VARIABLE	DESCRIPTION	UNITS	RANGE
CER	Card Assembly Cost Per Card	\$	369.62 - 1627.36
NDEV	Number of Devices Per Card	Qty.	39 - 290
NRAM	Number of RAMS Per Card	Qty.	0 - 24

random access memory devices (NRAM) contained on a card was the only other MC factor that explained any additional cost variation.

Nineteen candidate variables were tested in the step-wise regression procedure using twenty two data points each one of which represented a historical average (i.e., each value of the dependent variables represents the assembly cost per card averaged over all cards of that type produced over a period of time). However, none of these variables had any appreciable correlation with assembly cost over that already explained by NDEV and NRAM.

The applicable CER's and corresponding R-values are given in Table 3.2.4-2. The complete regression runs are given in Appendix A-3. Basic CER for estimating assembly cost per card is given by:

$$(3.8) \quad PCER_3 = 5.91634 \cdot NDEV + 27.57201 \cdot NRAM$$

This CER states that the assembly cost per card is approximately \$6 per device. If RAM devices are used, an additional cost of \$28 per RAM device is incurred.

TABLE 3.2.4-2 CER'S FOR CARD ASSEMBLY

CER	CONSTANT	INDEPENDENT VARIABLE		R	VARIABLES REMOVED
		NDEV	NRAM		
	C1	C2	C3	--	--
BASIC	0	5.91634	27.57201	.98	--
1	0	6.26267	--	.95	NRAM

$$PCER_3 = C_2 \cdot NDEV + C_3 \cdot NRAM$$

3.2.5 TEST-REWORK CYCLE (PCER₄)

3.2.5.1 CARD TEST LABOR CER

Three sources of plant level data were used to derive the CER:

- Card Test Defect Analysis (CTDA) reports,
- Assembly Area Quality Level (AAQL) reports and,
- Card level parts lists used with respect MIL-HDBK 217C for making reliability predictions.

For each program in manufacture the CTDA report lists: 1) the number of cards reworked (distinguished by function as linear or digital but not by part number); 2) the defect distribution $D(d_1, d_2, \dots, d_{10})$ of these cards across ten standard defect codes, $d_i, 1 \leq i \leq 10$; and 3) average test hours per card, H . Using 14 such summaries, regression equations depicting test hours per card as a function of defect distribution were developed, that is, each equation defines a function such that:

$$H = F(D(d_1, d_2, \dots, d_{10}))$$

Regression equations with high correlation ($R > .95$) were found for six systems.

The second source of data (AAQL reports) defined the defect distribution, say $D^*(d_1, d_2, \dots, d_{10})$ of specific card types (by part number) over the same period of time. By selecting card types with various quantities of MCs and using the regression equations, the average number of labor hours expended to test each card type was determined; that is, new values of H were computed according to the equation:

$$H = F(D^*(d_1, d_2, \dots, d_{10}))$$

Thus, H is now a relationship between card average test hours and specific card types (by part number).

Finally, the third source of data, card level parts list data, provided the MC characteristics ie, technology, quality grade, packaging etc of each card type. These MC characteristics were treated as independent variables and H as the dependent variable in the regression.

Table 3.2.5-1 identifies the card characteristics relating to MC devices that were significantly correlated with H . Twenty eight data points representing historical averages were used. The variable representing the product of population times number of digital gates (NDEV.NDG) was found to explain most of the variation (approximately 36%) in card test labor. The applicable card test labor CER's and their corresponding R-values are given in Table 3.2.5-2. The complete regression runs are provided in Appendix A-4.

TABLE 3.2.5-1 CARD TEST LABOR VARIABLE DESCRIPTION

VARIABLE	DESCRIPTION	UNITS	RANGE
H	CARD TEST HOURS PER CARD	HRS	.64 - 12.18
NDEV	NUMBER OF DEVICES PER CARD*	QTY	42 - 524
NMC	NUMBER OF MC DEVICES PER CARD	QTY	12 - 144
NDG	NUMBER OF DIGITAL GATES PER CARD	QTY	0 - 2940
NLG	NUMBER OF LINEAR GATES PER CARD (TRANS/4)	QTY	3.50 - 132.50
W	CONTRIBUTION OF MC DEVICES TO CARD FAILURE RATE	RATIO	.02 - 1.00

*Total active and passive devices.

TABLE 3.2.5-2 CER's FOR CARD TEST LABOR

CER	INDEPENDENT VARIABLE					R	VARIABLES REMOVED
	CONSTANT	NDEV·NDG	1-W	NLG	(NMC/NDEV) ²		
	C1	C2	C3	C4	C5	---	-----
BASIC	-.29669	.00000889	4.99908	.01514	1.98307	.84	-----
1	.37016	.00000891	5.13788	-----	-----	.81	NLG, (NMC/ NDEV) ²

$$H = C1 + C2 \cdot NDEV \cdot NDG + C3 \cdot (1-W) + C4 \cdot NLG + C5 \cdot (NMC/NDEV)^2$$

3.2.5.2 CARD TEST FRACTIONAL YIELD CER (Yc)

The AAQL report described previously provided the fractional yield of tested card types with known MC characteristics. Table 3.2.5-3 identifies the card characteristics relating to MC devices that provided significant correlations with card test yield (Yc). Twenty three data points representing historical averages were used to derive the applicable card test yield CER's. These are given in Table 3.2.5-4 with the corresponding R-values. The completed regression runs are given in Appendix A-5.

TABLE 3.2.5-3 CARD TEST FRACTIONAL YIELD VARIABLE DESCRIPTION:

VARIABLE	VARIABLE DESCRIPTION	UNITS	RANGE
Yc	CARD TEST YIELD	RATIO	.42 - .92
NMC	NUMBER OF MC DEVICES PER CARD	QTY	42 - 524
NDEV	NUMBER OF DEVICES PER CARD	QTY	28 - 255
QB2	NUMBER OF MC DEVICES PER CARD OF QUALITY GRADE B2 OR LOWER	QTY	0 - 144
NLG	NUMBER OF LINEAR GATES PER CARD	QTY	0 - 132
W	CONTRIBUTION OF MC DEVICES TO CARD FAILURE RATE	RATIO	.37 - .99

TABLE 3.2.5-4 CER's FOR CARD TEST FRACTIONAL YIELD

CER	INDEPENDENT VARIABLE					R	VARIABLES REMOVED
	CONSTANT	(NMC/NDEV)	QB2	NLG	1-W		
	C1	C2	C3	C4	C5	---	-----
BASIC	0	-.20504	-.00146	-.00122	-.14842	.90	-----
1	0	-.31298	-----	-----	-----	.78	1-W, QB2, NLG

$$Y_c = 10 \left(C2 \cdot (NMC/NDEV) + C3 \cdot QB2 + C4 \cdot NLG + C5 \cdot (1-W) \right)$$

3.2.5.3 CARD REWORK COST FACTOR (c_1)

The labor required to rework a card (ie, the labor for removing and replacing defective MC Devices once a failure has been isolated with test equipment), TCR, does not appear to vary significantly with changes in MC characteristics on the card except indirectly through card test yield. Based on manufacturing engineering estimates, an average of 0.26 hours is expended for removing/replacing defective devices. Thus, each failed card incurs a rework cost (c_1) of:

$$c_1 = TCR \cdot RATE1$$

where: TCR = 0.26 hours per rework action.

RATE1 = Technician labor rate during card test (\$/hr.)

3.2.5.4 SYSTEM TEST FRACTIONAL YIELD CER (Y_s)

Data for the system (i.e., higher assembly) test fractional yield CER was assembled from two sources before processing. The Indentured Parts Lists (IPL's) of systems give the quantity of cards (by part number) used in a system. By comparing the IPL's with the Abbreviated Failure Reports employed by systems using Hughes' Failure Reporting and Corrective Action System (FRACAS), it was possible to create a data base giving the system yield (Y_s) as the dependent variable for specific cards with known MC characteristics.

Table 3.2.5-4 identifies the card characteristics relating to MC devices that provided significant correlations with system test yield. Thirteen candidate variables were tested in the stepwise regression procedure using twenty two data points. The total number of devices per card (NDEV) explained most of the variation in system test yield (approximately 65%).

Table 3.2.5-5 provides the applicable system test yield CER's and corresponding R-values. Although the alternate CER given in the table provides an alternate for computing system test yield, this CER is not used in the LCC model. This is because other CER's require the number of MC devices as an essential input. The complete regression runs for these CER's are given in Appendix A-6.

TABLE 3.2.5-5 SYSTEM TEST YIELD VARIABLE DESCRIPTION

VARIABLE	DESCRIPTION	UNITS	RANGE
YS	SYSTEM TEST YIELD PER CARD	RATIO	.74 - .96
NMC	NUMBER OF MC DEVICES PER CARD	QTY	3 - 58
NDEV	NUMBER OF DEVICES PER CARD	QTY	30 - 160

TABLE 3.2.5-6 CER's FOR SYSTEM TEST YIELD

CER	INDEPENDENT VARIABLES			R	VARIABLES REMOVED
	CONSTANT	NDEV	NMC		
	C1	C2	C3	---	-----
BASIC	0	-.00094	-.001	.83	-----

$$Y_s = \text{EXP}(C2 \cdot \text{NDEV} + C3 \cdot \text{NMC})$$

3.2.5.5 SYSTEM REWORK COST FACTOR (c_2)

Each failure at the system level necessitates technician time for fault isolation and card replacement. These tasks depend on technician skill level and complexity of the fault isolation process, factors which are independent of MC characteristics and which vary according to system design and complexity. Moreover, these factors cannot be quantized from existing card-level data. In order to account for system repair time when an MC device causes the failure, system test technicians were interviewed. This resulted in an estimated average time from fault detection to resolution and check-out of approximately 0.5 hours per repair action. Thus each card failing system test incurs a rework cost (c_2) of:

$$c_2 = \text{TSR} \cdot \text{RATE2}$$

where:

TSR = 0.5 hours per rework action

RATE2 = composite labor rate at systems test (\$/hour)

3.3 MAINTENANCE AND SUPPORT

3.3.1 MAINTENANCE AND SUPPORT COST MODEL

Microcircuit characteristics are an important contributor to the lifetime maintenance and support costs of modern military systems. The impact of microcircuit alternatives on the lifetime support costs (a major component of LCC) cannot be assessed completely without accounting for the effects on system spares, support equipment, inventory entry and supply management costs, and other support areas where changes in device characteristics affect the next level of assembly (i.e., card, module, assembly, etc.). For example, in comparing alternate methods of system design implementation such as standard SSI/MSI versus custom LSI, the total number of card types needed to implement a given function would be higher for one alternative than for the other. In this case, the inventory entry (i.e., into government inventory) and supply management costs would, of course, be higher for the alternative which required more device and card types. Moreover, initial spares stockage and support equipment costs may also be higher. Thus, if only the microcircuit's impact on system acquisition is considered, an erroneous decision could be made because major maintenance and support cost impacts were ignored.

Figure 3.3.1-1 describes the maintenance support model and identifies the contributing cost factors which are influenced by changes in MC characteristics. The model shows two levels of maintenance: the organizational level where M sites are maintained with on-site spares and supply management and the depot where all card repair actions are performed. The logistics pipeline between sites and depot is supported with an initial spares stockage based on the repair cycle time and spares replenishment due to supply leakages. In this two-level maintenance model, fault isolation to the card or card group takes place on-site and card repair takes place at the depot.

In a three-level maintenance situation where an intermediate repair facility is inserted between the site and the depot, higher assemblies (units) are typically spared on site. Thus, when a failure occurs, the entire unit is removed and sent to the intermediate facility where the failed card is then removed from the unit and sent to the depot for repair. For purposes of estimating MC cost impacts, this three-level maintenance model can be approximated using the two-level model by co-locating the intermediate with the organizational site or depot, as appropriate, and adjusting 1) the false-return rate (i.e., pulling a "unit's" worth of cards for a single card failure), 2) the spares order-ship time and 3) the depot repair cycle time.

Each of the maintenance support cost factors and their relationship to changes in MC characteristics are discussed in Subsections 3.3.2 through 3.3.7.

3.3.2 SPARES (MCER₁)

A change in MC characteristics such as device quality grade, standard SSI/MSI to custom LSI, etc. can have major impacts on partitioning the system design functions into units, assemblies and cards as well as reliability and production cost. On-site system sparing (e.g., cards) is a direct consequence of this partitioning since it defines the numbers and types of cards being utilized.

The Algorithm given below computes initial stockage, pipeline and the lifetime replenishment spares due to pipeline leakages (i.e., losses due to transit damage, condemnation, etc.). This Algorithm computes recurring and the non-recurring

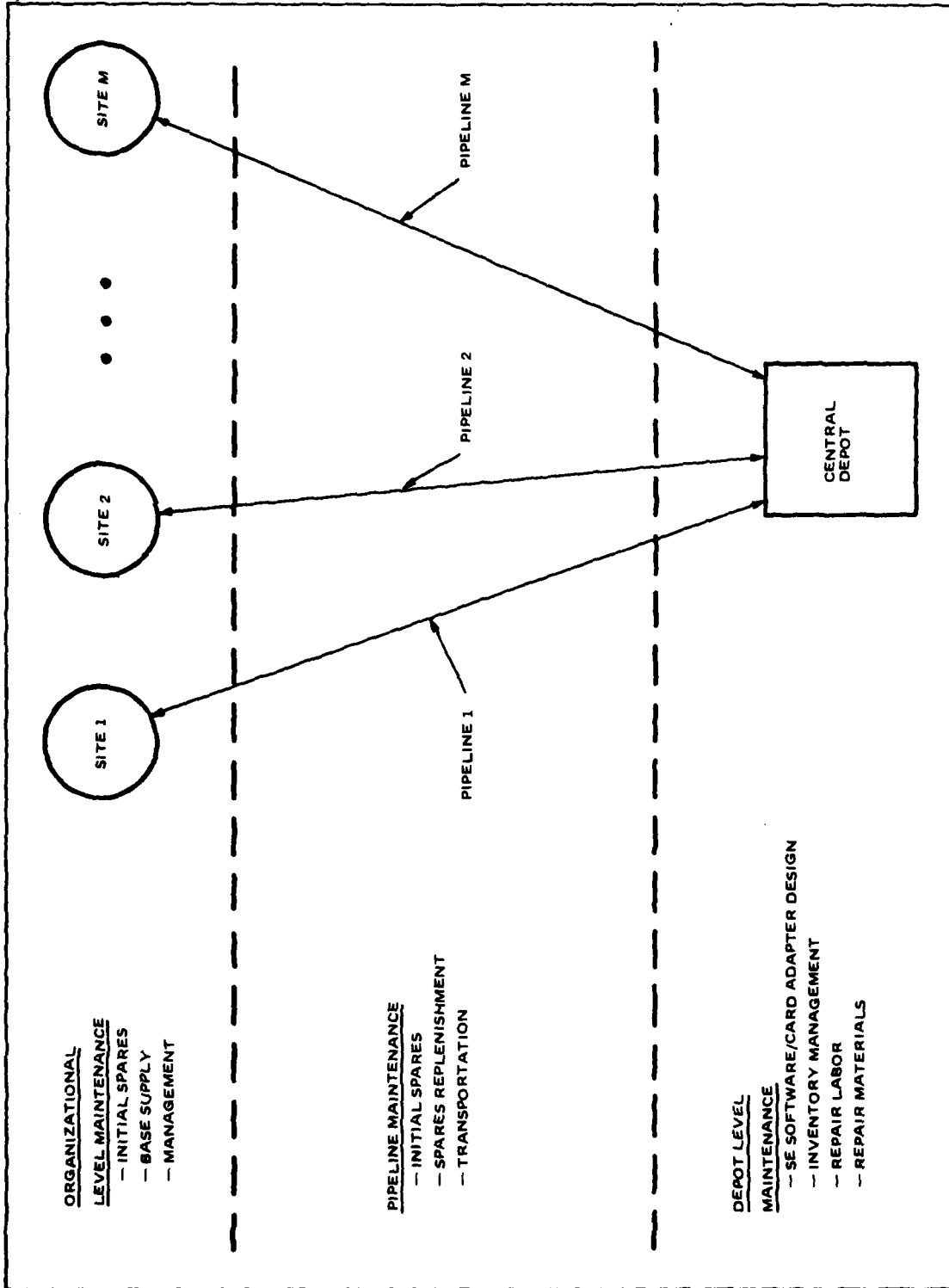


Figure 3.3.1-1. Maintenance Support Model

costs for each card type and then sums the results over N_c distinct card types. The non-recurring costs represented in the algorithm reflect first year spares stockage costs. The recurring costs of replenishment spares are distributed over operating lifetimes of 5, 10 and 15 years. The card failure rate (CF) can be adjusted to account for false returns (Fc). The average stock function (X) is based on the Poisson failure distribution and a minimum site stock safety factor (PL) where the demand (A) is derived from the card failure rate, order-ship time (Ts) and the false return adjustment Factor.

$$(3.9) \quad MCER_1(y) = \sum_{i=1}^{N_c} \left(X(i) + y \cdot \frac{T_o(1+F_c)}{M} \cdot CARD(i) \cdot CF(i) \right) \cdot \left(\frac{T_R}{8760} + W(i) \cdot D \right) \cdot K_c(i)$$

where:

M = Number of sites for spares stockage

$K_c(i)$ = Card Cost of i^{th} card type (see below)

T_R = Repair cycle time (Hours)

T_o = Operating hours per year (Hours)

F_c = False Return Factor (Number of false returns per failure)

$CARD(i)$ = Total quantity of cards used, i^{th} card Type

$CF(i)$ = Failure rate of i^{th} card type

$W(i)$ = Ratio contribution of MC devices to card failure rate

D = Condemnation rate

$X(i)$ = Site spares stockage. Minimum value such that:

$$\sum_{j=0}^{X(i)} e^{-A(i)} \frac{A(i)^j}{j!} \geq P_L^{1/N_c}$$

$A = T_s \cdot (CARD(i)/M) \cdot CF(i) \cdot (1 + F_c)$

P_L = Stock Safety Factor

N_c = Number of distinct card types.

T_s = Order-ship time (Hours)

The unit cost of a spare, $K_c(i)$, is computed based on card type except for the material cost of the MC devices which is averaged:

$$K_c(i) = (PCER_1 + PCER_2) \cdot NMC(i) + MANU\$(i)$$

where:

$PCER_1$ = total MC device procurement cost (See Section 3.2.2)

$PCER_2$ = total MC device screening cost (See Section 3.2.3)

$NMC(i)$ = number of MC devices used on i^{th} card type

$MANU\$(i)$ = manufacturing cost of i^{th} card type (i.e., assembly and test cost)

The spares cost represented by the above algorithm is driven primarily by the number of operating sites (M) and the number of card types (N_c). The number of sites acts as a simple multiplier of the spares cost at a single site. The number of card types, however, plays an even more significant role in that it also affects the assurance spares for each card type (i.e., the factor P_L^{1/N_c} increases causing $X(i)$ to increase as N_c increases). Similarly, the expected number of false returns per failure (F_c) can have a significant impact on spares cost since it multiplies the demand, $A(i)$, as well as the pipeline and replenishment spares. Of course, the other factors in the algorithm can also change resulting in significant cost impacts, but they are not as likely to change as radically as M , N_c or F_c .

3.3.3 SUPPORT EQUIPMENT (MCER₂)

Adapters for circuit card testers (e.g., the General Radio 1796 card tester) are generally required for each new card type or family of card types. Similarly, the diagnostic software used in programmable testers must be developed for each new card type. These costs are clearly a function of the card complexity, packaging and density (devices per card), and, therefore, are valid candidates for microcircuit CERs.

$$(3-10) \quad MCER_2 = \sum_{j=1}^{N_c} (KA(I) + KS(I))$$

where:

N_c = Number of Distinct Card Types

$KA(I)$ = Software equipment adapter cost for card type I.

$KS(I)$ = Software diagnostic development cost for card type I

Table 3.3.3-1 provides a range of factors for software development cost per card and adapter cost per card based on the type of card (digital or linear) and level of complexity. The higher cost values shown in the table, particularly in the case of linear cards, are greatly affected by test complications resulting from unusual signal conditioning requirement, RF problems and security requirements (e.g., COMSEC). Multi-layer circuit boards also complicate testing and thereby increase software and adapter costs.

TABLE 3.3.3-1. SOFTWARE AND ADAPTER DEVELOPMENT COSTS (K\$)

Card Complexity		Software Cost (KS)		Adapter Cost (KA)	
Linear*	Digital**	Linear	Digital	Linear	Digital
15-20	Non Memory	10-25	4-6	3-5	.5-2
20-50	SSI, MSI	20-40	-	5-7	-
50-250	Memory and LSI	40-80	6-10	10-15	.5-2

*Number of linear MC devices per card.

**Independent of the number of devices per card.

3.3.4 INVENTORY ENTRY AND SUPPLY MANAGEMENT (MCER₃)

For a new system, the government incurs an initial cost of entering all new pieceparts, cards, assemblies, etc. into the Federal Stock System and a recurring cost of maintaining these items in inventory for the system's life cycle. In addition, a recurring base supply management cost may also be incurred for every item stocked on-site.

Since a change in device characteristics may also change the number of card types. For example, a change from standard SSI/MSI devices to custom or semi-custom LSI would require a repartitioning of the system into units, assemblies and cards. This would introduce new (LSI) items into inventory but also would likely result in a reduction in card types. Depending on the number of sites, the reduction in card types may result in sufficient reduction in base supply management costs to swing the tradeoff in favor of LSI.

The following algorithm is used to estimate lifetime (y) inventory management costs based on the introduction of new MC devices (D_{NEW}) and cards (N_c) into government inventory and M base supply systems:

$$(3.11) \quad MCER_3(y) = (D_{NEW} + N_c)K_I + y \left[(D_{NEW} + N_c)K_{IR} + M \cdot N_c \cdot K_{SM} \right]$$

where:

D_{NEW} = Number of new MC device types.

N_C = Number of new card types.

K_I = Government Inventory Entry Cost Factor (\$/Item)

K_{IR} = Recurring Government Inventory Management Cost Factor (\$/Item/Year)

K_{SM} = Recurring Government Supply Management Cost (\$/Item/Site/Year)

M = Number of Operating Sites

The cost factors K_I , K_{IR} and K_{SM} are government derived and depend on the type of support system in use. It should be noted that cards only are put in the M base supply systems. Table 3.3.4-1 provides the values (used as defaults) currently employed in the LCC model:

TABLE 3.3.4-1 COST FACTORS FOR INVENTORY MANAGEMENT

FACTOR	VALUE*(\$)
Inventory Entry (K_I)	54
Recurring Inventory Management (K_{IR})	128
Recurring Base Supply Management (K_{SM})	42

*Based on LCC data currently used in cost analyses for the Joint Surveillance System (JSS), Headquarters Electronic Systems Division (AFSC) Hanscom AFB.

3.3.5 REPAIR LABOR (MCER₄)

When a microcircuit device fails, the card that contains the device (and possibly other cards as well, depending on fault isolation capability) is removed from the system and transported to a repair facility where the failure is verified and the failed device is isolated, removed and replaced. The repaired card is then checked out and put back into spares stock. The frequency of repair is determined from the card failure rate (CF), false return adjustment factor (F_C), operating hours per year (T_0) and the card usage population (CARD). The average labor hours to perform the repair action is dependent on whether the card is a false return. A false return incurs L_F labor hours and a failed card incurs L_R labor hours. The repair labor is a function of device complexity, card density and the capability of the Depot support equipment.

The following algorithm is used to estimate depot repair labor cost based on the expected number of returns over the lifetime (y) of the system and data on card repair labor.

$$(3.12) \quad \text{MCER}_4(y) = T_o K_R y \sum_{i=1}^{Nc} \text{CARD}(i) \cdot W(i) \cdot \text{CF}(i) \cdot (L_R(i) + L_F(i) \cdot F_c)$$

where:

T_o = Operating Hours Per Year

K_R = Depot Labor Rate (Depot overhead should be included in this rate in order to reflect "true" cost to the government)

Nc = Number of card types

$\text{CARD}(i)$ = Total quantity of cards of i^{th} type

$W(i)$ = Ratio contribution of MC to card failure rate, i^{th} card type

$\text{CF}(i)$ = Card Failure Rate, i^{th} type

$L_R(i) = T_{CR} + H(i)$

T_{CR} = Card Rework labor (see Section 3.2.5.3)

$H(i)$ = Card Test Labor (See Section 3.2.5.1)

$L_F(i)$ = Average Labor to Verify Fault.

The estimated value for $L_F(i)$ is dependent on card type (i.e., linear or digital) and was derived from Hughes manufacturing test engineering experience:

$$L_F(i) = \begin{cases} 1.5, & \text{Hours For Digital Cards} \\ 3.0, & \text{Hours For Linear and Mixed (Linear-Digital) Cards} \end{cases}$$

The value for the Depot labor rate (K_R) is \$20/hour (used as a program default) and is based on Government data.³

3.3.6 REPAIR MATERIALS (MCER_5)

The average repair materials cost per card (K_M) associated with depot repair actions is based on applying a 5% factor to the estimated card cost. This factor is a government derived standard³. The estimated card cost includes device procurement cost per card, device screening cost, if applicable, assembly cost

per card and the test cost per card. The following algorithm is used to estimate the lifetime (y) depot repair materials cost.

$$(3.13) \quad MCER_5(y) = Y T_o \sum_{i=1}^{N_c} CARD(i) \cdot W(i) \cdot CF(i) \cdot K_M(i)$$

where:

T_o = Operating Hours Per Year

N_c = Number of Card Types

$CARD(i)$ = Total Quantity of Cards Used, i^{th} Card Type.

$W(i)$ = Ratio Contribution of MC Devices to Card Failure Rate, i^{th} Type.

$CF(i)$ = Card Failure Rate, i^{th} Type

$K_M(i) = 0.05 \cdot K_c(i)$, Repair Material Cost

$K_c(i)$ = Card Cost (See Section 3.3.2)

3.3.7 MAINTENANCE TRANSPORTATION ($MCER_6$)

The transportation costs associated with repair actions is based on the average shipping weight of a card (W_c) and an average shipping cost per pound (K_T). The factor W_c is design dependent and, therefore, user furnished data. The factor K_T is a government standard based on TTO-ORT-032-78-V3. False returns (F_c) also incur transportation costs and these are included in the estimate.

The following algorithm estimates the lifetime (y) transportation costs and is based on the two-way transportation of all cards removed (i.e., site-to-depot and return to site supply).

$$MCER_6 = 2 T_o W_c K_T (1 + F_c) y \sum_{i=1}^{N_c} CARD(i) \cdot CF(i) \cdot W(i)$$

T_o = Operating Hours Per Year.

W_c = Average Shipping Weight of a card (lbs).

K_T = Average Shipping Cost (\$/lb).

$CARD(i)$ = Total Quantity of Cards Used, i^{th} Card Type

$CF(i)$ = Card Failure Rate, i^{th} Type.

$W(i)$ = Ratio Contribution of MC Devices to Card Failure Rate.

3.4 OTHER MC COST CONSIDERATIONS

The LCC of MC devices must also take into account perturbations to the "normal" acquisition and support process. The cost of acquisition depend upon purchasing characteristics (i. e., device availability in the desired quality grade, quantities, etc.) standardization status, military qualification, risk of obsolescence and whether the device manufacturer deals in off-shore procurements. When these factors are present, their cost impacts must be taken into account together with the MC characteristics discussed in the previous sections. The following paragraphs discuss the general impact of these considerations on MC devices.

3.4.1 LEARNING CURVE EFFECTS

The cost of most MC devices are generally set by pricing agreements between supplier and contractor on a yearly basis. For low volume, custom or semi-custom devices, learning curves are usually established in RDT&E on a low volume of devices. Learning curve entry points and slopes are then established on the basis of these device specifications and the characteristics of manufacturers' unique production process. For example, if the manufacturer's production process is typified by log-linear learning*:

$$Y(n) = AN^\alpha$$

where: $Y(n)$ = Cost of the n^{th} unit

A = Cost of the theoretical first unit

$$\alpha = \ln S / \ln 2$$

S = Learning curve slope

then A can be determined from the cost of, say, the first K units (i. e., $Y(k)$). With a knowledge of S determined by the manufacturer's production history, prices can be projected for any desired quantities (n) using:

$$Y(n) = Y(k) \left(\frac{n}{k} \right)^\alpha$$

3.4.2 COST OF SPECIFICATIONS, DEVICE QUALIFICATIONS

Documentation and qualification of MC devices to military standards can discourage many suppliers from bidding on military LSI developments. Accordingly, the military purchase typically only represents about 9% of the supplier's total procurement. The cost to develop a device specification and negotiate a procurement with a supplier can range from \$1000 to \$2000 (FY 80) per device, depending on the complexity of the device. The low end represents a simple SSI/MSI and the upper cost represents a custom LSI. Qualifying a device to JANB or space level can be

*Learning curves are discussed in some detail in TTO-ORT-032A-78-V3.

a significant problem. Normally, a supplier will agree to qualify to JANB or higher only on high-volume devices. If the supplier agrees, the cost to qualify is typically \$100K to \$150K for a first-time qualification.

3.4.3 ON-SHORE/OFF-SHORE PROCUREMENTS

Many device suppliers have off-shore facilities due to the substantial differences in labor rates. For example, labor rates of \$22 - \$25 per hour in the U.S. versus rates of \$1.10 - \$1.50 per hour in Taiwan. These differences in labor rates obviously give suppliers with large-off-shore commitments the capability of being more competitive than those with smaller or no off-shore commitments.

Companies with only on-shore commitments, however, tend to have much better lead times than those companies with both on-shore and off-shore. Part of the reason for this is that for devices produced in foreign countries, qualification and final assembly must be conducted in the U.S. in order to qualify as a military standard. Moreover, at the present time all JAN operations must be conducted on shore.

Most military equipment contractors do not deal directly with an off-shore supplier so that the affect on the MC device purchase cost is obscured by multiple sourcing and competition among suppliers.

3.4.4 DEVICE OBSOLESCENCE

When a manufacturer puts out notifications that a device will no longer be produced, the buyer is left with several options. These options are usually never clear cut since many factors must be considered in order to make a decision. The major factors include the number of manufacturers producing these parts, the use of the system(s) involved, the number of systems involved and the extent of the usage of the part in the system.

When a manufacturer discontinues production of a MC device, the buyer is given the option of purchasing a "lifetime" supply of these parts in one last order, thus incurring a large capital investment and a risk in not accurately estimating the quantity of parts needed.

The buyer may also procure parts from other suppliers. But, as the number of suppliers discontinue production, the cost of buying these parts can run up to three or four times the original procurement price. Moreover, the turnaround time for these parts can take up to as long as a year per order.

Normally, substitute devices providing the same function as the previous device may be purchased. These replacements are generally superior (and more costly) to the discontinued part. The problem with this option is that a large expense is sometimes incurred in preparing the paperwork needed to implement this new part into configuration control. Although these redesign changes can be very expensive, they are usually preferred over the other options in high usage situations.

Section 4.0

APPLICATION PROCEDURE AND EXAMPLES

4.1 GENERAL PROCEDURE

4.1.1 INPUT DATA REQUIREMENTS AND PROGRAM DEFAULTS

The data input requirements and default options for the MC LCC Model are described in Tables 4.1.1-1, 4.1.1-2, and 4.1.1-3. These tables describe the input requirements and default options for the three input data sets necessary to run the LCC Model computer program.

The first column of the tables describes variable names for each of the data sets. The names are listed in the order that they must appear in the data sets. The second column gives the description of variable. The third column gives the required units for each variable in the program. The fourth column describes the inputs necessary to exercise the default options. A dash in this column indicates that no default options are available to the user. A "0" or "-1" in this column initiates the default value indicated. The fifth and sixth columns describe what values or conditions are used in the program when a default is exercised. If a default equation is employed, the CER's that are affected are noted. Conditions under which the program will terminate are also provided.

Definition of Input Data Sets - The following general operational description applies to all procedures for processing input data and execution of the LCC Model on an AMDAHL 470 or IBM 360/370 Computer System with a Time Sharing Option (TSO). Information for the LCC Model are created by three data sets noted below. The asterisks denote that the associated parameter has a default value or CER equation supplied in the model.

FILE 01-Program. Data - This data set contains values for the parameters: N, NC, FSTD*, CMAX*, RATE4*, RATE5*, RATE1*, RATE2*, RATE3*, M*, TS*, PL*, TO*, TR*, FC*, D*, KI*, KIR*, KSM*, KR*, KM*, KT*, WC*, RD*, RI*, YRDTE*, TRDTE*, YMANU*, TMANU*, YOAS*. (Refer to Table 4.1.1-1)

FILE 02-Device. Data - This data set contains values for the MC device characteristics found on each MC device type. For each device type, an array

Table 4.1.1-1. INPUT REQUIREMENTS & OPTIONS FOR PROGRAM DATA

VARIABLE	VARIABLE DESCRIPTION	INPUT UNITS	DEFAULT OPTIONS		PROGRAM OPTIONS/COMMENTS
			INPUT	DEFAULT	
N	Number of distinct MC device types	Qty	-	None	Program will terminate for inputs ≤ 0 .
NC	Number of distinct card types	Qty	-	None	Program will terminate for inputs ≤ 0 .
FSTD	Standardization factor for RDT&E	Qty	0	0	See Note
CNAX	Maximum RDT&E Cost	\$	0	203	See Note
CMIN	Minimum RDT&E Cost	\$	0	24	See Note
RATE 4	Hourly burdoned rate for an engineering labor grade	\$/hr.	0	43.75	See Note
RATE 5	Hourly burdoned rate for a technician labor grade	\$/hr.	0	35	See Note
RATE 1	Hourly burdoned rate for the card test	\$/hr.	0	26.90	See Note
RATE 2	Hourly burdoned rate for the system test	\$/hr.	0	26.90	See Note
RATE 3	Hourly burdoned rate for the rework/retest	\$/hr.	0	20.30	See Note
NI	Number of sites for spares stockage	Qty	0	1	
TS	Spares ship time	Hrs	0	336	
PL	Stock safety factor	Qty	0	.9	
TO	Operating hours per year	Hrs/Yr	0	8760	
TR	Turn around time	Hrs	0	1440	
FC	False return factor	Qty	0	0	
D	Condemination rate	Qty	0	-.05	
KI	Government inventory entry rate	\$/item	0,-1	0, 54	See Note
KIR	Government inventory management cost	\$/item/yr	0,-1	0, 128	See Note
KSM	Government supply management cost	\$/item/site/yr	0,-1	0, 42	See Note
KR	Repair labor rate	\$/hr.	0	20	See Note
KM	Repair Materials Cost per Maintenance Action	\$/action	0	.05 Card\$	Card\$-card cost, which is computed internally
KT	Average shipping cost	\$/lb.	0	.5	See Note
WC	Average shipping weight per card	lb	0	1	
RD	Discount rate	Qty	0	.1	
RI	Inflation rate	Qty	0	.06	
YRDTE	Year RDT&E starts	Qty	0	1980	
TRDTE	Number of years RDT&E lasts	Yrs	0	0	
MANU	Year Production starts	Qty	0	YRDTE + TRDTE	
MANU	Number of years Production lasts	Yrs	0	1	
YOAS	Year Operations and Support starts	Qty	0	YMANU + TMANU	

NOTE: Default value incurs an inflation factor

Table 4.1.1-2. INPUT REQUIREMENTS & OPTIONS FOR DEVICE DATA

VARIABLE	VARIABLE DESCRIPTION	INPUT UNITS	DEFAULT OPTIONS		PROGRAM OPTIONS/COMMENTS
			INPUT	DEFAULT	
NEW	MC device type 1 is a new device	1 if, 0 if not	-	None	Program will terminate for inputs < 0.
MEM	MC device type 1 is a memory device	1 if, 0 if not	-	None	Program will terminate for inputs < 0.
MOS	MC device type 1 is a MOS device	1 if, 0 if not	-1	Default Equation Supplied	Device Purchase (PCER1 3.2.2)
DIG	MC device type 1 is a digital device	1 if, 0 if not	-1	Default Equation Supplied	Device Purchase (PCER1 3.2.2)
ECL	MC device type 1 is an ECL device	1 if, 0 if not	-	None	Program will terminate for inputs < 0.
FP	MC device type 1 is a flat-pack	1 if, 0 if not	-1	Default Equation Supplied	Device Purchase (PCER1 3.2.2)
NG	Number of gates on MC device type 1	Qty	-	None	Program will terminate for inputs < 0.
NB	Number of bits on MC device type 1	Qty	-	None	Program will terminate for inputs < 0.
NP	Number of pins on MC device type 1	Qty	-	None	Program will terminate for inputs < 0.
DEVQ	Total number of MC devices for MC device type 1	Qty	-	None	Program will terminate for inputs ≤ 0.
REL	Reliability of MC device type 1	*	-	None	Program will terminate for inputs ≤ 0.
SCRN	Screen MC device type 1 (100% Screening in assumed)	2 if, 1 if not	0	2	Device type 1 will be screened.

* The following reliability weights are used:

REL	0.5	1.0	3.0	6.5	8.0	17.5	35.0
QUALITY GRADE	A	B	B-1	B-2	C	C-1	D

Table 4.1.1-3. INPUT REQUIREMENTS & OPTIONS FOR CARD DATA

VARIABLE	VARIABLE DESCRIPTION	INPUT UNITS	DEFAULT OPTIONS		PROGRAM OPTIONS/COMMENTS
			INPUT	DEFAULT	
CARD	Total number of cards for card type 1	Qty	-	None	Program will terminate for inputs ≤ 0 .
NDEV	Number of active and passive devices on card type 1.	Qty	-	None	Program will terminate for inputs ≤ 0 .
NMC	Number of MC devices on card type 1	Qty	-	None	Program will terminate for inputs ≤ 0 .
NDG	Number of digital gates on card type 1	Qty	-	None	Program will terminate for inputs ≤ 0 .
NLG	Number of linear gates on card type 1	Qty	-1	Default Equation Supplied	Card test hours (H 3.2.5), Card test yield (Yc 3.2.5), Repair Labor (MCER4 3.3.5)
NRAM	Number of rams on card type 1	Qty	-1	Default Equation Supplied	Card Assembly (NCER3 3.2.4)
W	Ratio contribution of MCS to the card failure rate for card type 1.	Qty	0	1	
CF	Card failure rate for card type 1	Qty	-	None	Program will terminate for inputs ≤ 0 .
KA	Support equipment adapter cost for card type 1	\$	0	0	
KS	Software diagnostic development Cost for card type 1.	\$	0	0	

(line) of 12 elements is generated which contains data for the parameters: NEW, MEM, MOS*, DIG*, ECL, FP*, NG, NB, NP, DEVQ, REL, SCRN*. (Refer to Table 4.1.1-2)

FILE 03-Card. Data - This data set contains values for the card characteristics found on each card type. For each card type an array (line) of 10 elements is generated which contains data for the parameters: CARD, NDEV, NMC, NDG, NLG*, NRAM*, W*, CF, KA, KS. (Refer to Table 4.1.1-3)

FILE 06-Output. Text - This data set contains the results of the LCC Model. An empty data set is created as a location for storage for the LCC results.

With the exception of FILE 06, all of the above files must be filled. If the defaults are to be exercised, proper default inputs must be used as specified in the tables. The input form for each of the above data sets is "unformatted" (i.e., the values for each record are simply separated by commas). This will be illustrated in the examples provided in Section 4-2.

Output Report - The output of the LCC program is separated into three sections, or tables. The first table describes the impact of MC devices on LCC in constant dollars (i.e., no inflation indices or discount rates are applied) in the form of a cost breakdown structure. A breakdown into major contributing cost elements is provided for production (device procurement, screening and card manufacture) and maintenance support (spares, inventory management, depot maintenance, etc.), with the recurring costs distributed over life cycles of 5, 10 and 15 years.

The second table describes the impact of MC devices on LCC in constant, escalated and discounted dollars. The costs for each program phase are distributed over the scheduled duration of the phase: the recurring costs of a phase are apportioned equally over the time duration and the nonrecurring costs are incurred during the first year of the phase. The escalation and discount factors applied each year (based on user-provided rates or defaults) are also provided in this table.

The third table consists of three summaries of input data (program level, device level and card level) used to make an LCC estimate, including any default values that were employed.

All costs in the LCC summary tables are given in thousands of dollars. Some errors will occur due to round-off. These errors may be significant in cases where the computations result in annual costs less than \$500, particularly if the program phase is multiple year. However, if annual costs of \$500 are important to the analysis, the units can readily be changed (within the program) to whole dollars.

Diagnostics - If the total quantity of MC devices at the device level does not equal the total quantity of MC devices at the card level, an error message is printed stating the quantity of MC devices at each level. Similarly, if the total quantity of gates at the device level does not equal the total quantity of gates at the card level, an error message is printed stating the quantity of gates at each level.

4.1.2 STEP-BY-STEP GUIDE

The following steps are recommended as guidelines for executing the model program:

STEP 1 - Assemble required data for coding. Using Table 4.1.1-1 as a guide, determine user-unique values, default values, etc. Note that the parameters are ordered in the table according to the input sequence.

STEP 2 - Create the data files (sets) necessary for the model inputs and output.

FILE 01 (PROGRAM.DATA)

Col. No. 1

N, NC, FSTD, CMAX, CMIN,
RATE4, RATE5, RATE1, RATE2, RATE3,
M, TS, PL, TO, TR, FC,
D, KI, KIR, KSM, KR,
KM, KT, WC, RD, RI,
YRDTE, TRDTE, YMANU, TMANU, YOAS

FILE 02 (DEVICE.DATA)

Col. No. 1

NEW, MEM, MOS, DIG, ECL, FP, NG, NB, NP, DEVQ, REL, SCRN

↑
N Rows of Data (one for each device type)
↓

FILE 03 (CARD.DATA)

Col. No. 1

CARD, NDEV, NMC, NDG, NLG, NRAM, W, CF, KA, KS

↑
N_c Rows of Data (one for each card type)
↓

FILE 06 (OUTPUT.TEXT)

(This data set is empty)

STEP 3 - Allocate the data files for program execution:

```
FREE FI(FT06F001)
ALLOF FI(FT01F001) DA(PROGRAM.DATA)
ALLOF FI(FT02F001) DA(DEVICE.DATA)
ALLOF FI(FT03F001) DA(CARD.DATA)
ALLOF FI(FT06F001) DA(OUTPUT.TEXT).
```

STEP 4 - Program Execution. If MCF.MODEL has never been run before, it is necessary to compile and link the program before execution:

```
FORT MCF.MODEL.FORT
LINK MCA.MODEL.OBJ FORTL1B
CALL MCF.MODEL.LOAD
```

If the model has been run previously, it is only necessary to execute:

```
CALL MCF.MODEL
```

STEP 5 - Print the results of the program. If the results are to be printed at a terminal:

```
LIST OUTPUT.TEXT
```

If the results are to be sent to a line printer:

```
PRINTOFF OUTPUT.TEXT
```

4.2 EXAMPLES

4.2.1 DEVICE QUALITY EFFECTS ON LCC

For a population of typical high-density cards, the sensitivity of LCC to changes in device quality grades is examined. The "selected" population consists of 880 cards and is distributed over twenty (20) operating sites which are to be maintained over a 15 year period. With reference to the procedure described in Section 4.1.2 the detailed data is assembled and processed as follows:

STEP 1 - Assemble data for processing.

The data used consists of high-density digital, linear, and memory cards used in a typical Command-Control system. The "system" configuration supported at

each of the 20 sites is summarized in Table 4.2.1-1 and a detailed description of each card type subject to change is given in Table 4.2.1-2.

The input values and assumptions for PROGRAM.DATA are as follows:

- Number of card types and devices types (NC and N) are determined from Tables 4.2.1-1 and 4.2.1-2.
- Program default values are used for CMAX, CMIN, RATE4, RATE5, RATE1, RATE2, RATE3, TS, TO, TR, KI, KIR, KSM, KR, KM, KT, RD, RK, YRDTE and FSTD (see Table 4.1.1-1).
- The number of sites (M) is 20.
- The false return rate FC is 3 returns per failure.
- Condemnation rate is assumed to be 0.05.
- Card weights are all assumed to be 1 lb each.
- Production start (YMANU) is assumed to be 1980 with a duration (TMANU) of 3 years.
- The operations and support phase is assumed to start in 1983.

The input values and assumptions for DEVICE.DATA are as follows:

- All the MC device types are off-the-shelf (i.e.: NEW=0).
- The input values for device characteristics MEM, MOS and DIG are determined from Table 4.2.1-2.
- All the MC devices are flat-packs (i.e.: FP=1)

TABLE 4.2.1-1. SYSTEM DATA FOR EXAMPLE -1

CARD DESCRIPTION	NUMBER OF CARD TYPES	QTY OF CARDS PER TYPE	TOTAL CARDS PER SYSTEM	TOTAL FOR 20 SITES
High Density Memory	1	5	5	100
High Density Digital	6	5	30	600
High Density Linear	3	3	9	180
Totals	$N_c = 10$		44	880

TABLE 4.2.1-2. CARD DATA FOR EXAMPLE -1

CARD TYPE	DEVICE DESCRIPTION	DEVICE TYPES EACH CATEGORY	DEVICE QTY PER TYPE	TOTAL DEVICES PER CARD	TOTAL GATES PER CARD (NG)	TOTAL FAILURE RATE PER CARD* (FAILURE/10 ⁶ HOURS) (CF)				
						B	B-1	B-2	C	
Digital Logic (DIG)	LSI (500 gates/device)	4	1	4	2000	.24	.72	1.56	1.92	
	Digital Support Chips (10 gates/device)	10	5	50	500	.80	2.4	5.2	6.4	
	Bipolar RAMS (1K BITS/device)	1	8	8	--	1.12	3.36	7.28	8.96	
	Passive and Active Devices	--	50	50	--	.5	1.5	3.25	4.0	
Totals for Digital Logic Cards		15		NDEV=112	2500	2.66	7.98	17.29	21.28	
Linear	Linear (19 gates/device)	8	2	16	304	2.08	6.24	13.52	16.64	
	SSI/MSI Digital (20 gates/device)	10	2	20	400	.32	.96	2.08	2.56	
	Passive and Active Devices	--	100	100	--	1.0	3.0	6.5	8.0	
Totals for Linear Cards		18		NDEV=136	704	3.4	10.2	22.1	27.2	
Memory (MEM, MOS)	MOS RAMS (64 K BITS/Device)	1	64	64	--	108.8	326.4	707.2	870.4	
	SSI/MSI MOS Support Chips (20 gates/device)	5	2	10	200	.18	.54	1.17	1.44	
	Passive and Active Devices	--	50	50	--	.5	1.5	3.25	4.0	
Totals for Memory Cards		6		NDEV=124	200	109.48	328.44	711.62	875.84	
Totals for All Cards										N=39

*Per MIL-HDBK-217 assuming a ground-fixed environment.

- The number of gates for each device type is determined from Table 4.2.1-2.
- The number of bits (NB) for the RAMS used on the digital logic and memory cards is determined from Table 4.2.1-2.
- The pin count (NP) for SSI/MSI MC devices is 16 and the pin count for LSI devices is 40.
- The total number of MC devices (DEVQ) is calculated by multiplying the number of cards needed for the 20 sites in Table 4.2.1-1 by the device quantity per type in Table 4.2.1-2.
- The reliabilities are per MIL-HDBK-217 for quality grades B, B-1, B-2 and C (see Table 4.1.1-1).

The input values and assumptions for CARD.DATA are as follows:

- The total number of cards of each type (CARD) is calculated by multiplying the quantity of cards per type (Table 4.2.1) by the number of sites (20).
- The number of devices (NDEV) is determined from Table 4.2.1-2.
- NMC is the sum of the MC devices per card neglecting actives and passives (Table 4.2.1-2).
- NDG and NLG are determined by the device description (digital, linear) and the total number of gates of that type (NG) in Table 4.2.1-2.
- The number of RAMS per card (NRAM) is calculated by multiplying the number of cards needed for the 20 sites in Table 4.2.1-1 by the device quantity per type in Table 4.2.1-2 for RAM devices.
- W is calculated by dividing the sum of the MC device failure rates by the total card failure rate in Table 4.2.1-2.
- CF is calculated per MIL-HDBK-217 assuming a ground-fixed environment (Table 4.2.1-2).
- The support equipment adapter cost (KA) is assumed to be \$1,000 for the total family of logic cards and \$1,000 per card type for the linear and memory cards. Software development cost for support equipment (KS) is assumed to be \$5,000 for the total family of digital logic cards, \$60,000 per type for the linear cards and \$8,000 per type for the Memory cards (see Section 3.3.3).

STEP 2 - CODE INPUT DATA.

The coding for the input data given below is for the effects of quality grade B on LCC. The coding of the input data for the other quality grades require appropriate changes in the reliability (REL) in File 01 and the card failure rate (CF) in File 02 (see Table 4.1.1-1 for REL values and Table 4.2.1-2 for CF values).

FILE 01 (PROGRAM.DATA)

Col. No. 1

↓
39, 10, 0.5, 203, 24, 43.75, 35, 26.9, 26.9, 20.3,
20, 336, 0.95, 8760, 1440, 3, 0.05, 54, 128, 42,
20, 0, 0.5, 1, 0.1, 0.06, 1980, 0, 1980, 3, 1983

FILE 02 (DEVICE.DATA)

Col. No. 1

↓
0, 0, 0, 1, 0, 1, 500, 0, 40, 600, 1.0, 1
0, 0, 0, 1, 0, 1, 500, 0, 40, 600, 1.0, 1
0, 0, 0, 1, 0, 1, 500, 0, 40, 600, 1.0, 1
0, 0, 0, 1, 0, 1, 500, 0, 40, 600, 1.0, 1
0, 0, 0, 1, 0, 1, 10, 0, 16, 3000, 1.0, 1
0, 0, 0, 1, 0, 1, 10, 0, 16, 3000, 1.0, 1
0, 0, 0, 1, 0, 1, 10, 0, 16, 3000, 1.0, 1
0, 0, 0, 1, 0, 1, 10, 0, 16, 3000, 1.0, 1
0, 0, 0, 1, 0, 1, 10, 0, 16, 3000, 1.0, 1
0, 0, 0, 1, 0, 1, 10, 0, 16, 3000, 1.0, 1
0, 0, 0, 1, 0, 1, 10, 0, 16, 3000, 1.0, 1
0, 0, 0, 1, 0, 1, 10, 0, 16, 3000, 1.0, 1
0, 0, 0, 1, 0, 1, 10, 0, 16, 3000, 1.0, 1
0, 0, 0, 1, 0, 1, 10, 0, 16, 3000, 1.0, 1
0, 0, 0, 1, 0, 1, 10, 0, 16, 3000, 1.0, 1
0, 1, 0, 0, 0, 1, 0, 1000, 16, 4800, 1.0, 1
0, 0, 0, 0, 0, 1, 19, 0, 16, 360, 1.0, 1
0, 0, 0, 0, 0, 1, 19, 0, 16, 360, 1.0, 1
0, 0, 0, 0, 0, 1, 19, 0, 16, 360, 1.0, 1
0, 0, 0, 0, 0, 1, 19, 0, 16, 360, 1.0, 1
0, 0, 0, 0, 0, 1, 19, 0, 16, 360, 1.0, 1
0, 0, 0, 0, 0, 1, 19, 0, 16, 360, 1.0, 1
0, 0, 0, 0, 0, 1, 19, 0, 16, 360, 1.0, 1
0, 0, 0, 0, 0, 1, 19, 0, 16, 360, 1.0, 1
0, 0, 0, 1, 0, 1, 20, 0, 16, 360, 1.0, 1
0, 0, 0, 1, 0, 1, 20, 0, 16, 360, 1.0, 1
0, 0, 0, 1, 0, 1, 20, 0, 16, 360, 1.0, 1
0, 0, 0, 1, 0, 1, 20, 0, 16, 360, 1.0, 1
0, 0, 0, 1, 0, 1, 20, 0, 16, 360, 1.0, 1
0, 0, 0, 1, 0, 1, 20, 0, 16, 360, 1.0, 1
0, 0, 0, 1, 0, 1, 20, 0, 16, 360, 1.0, 1
0, 0, 0, 1, 0, 1, 20, 0, 16, 360, 1.0, 1
0, 0, 0, 1, 0, 1, 20, 0, 16, 360, 1.0, 1
0, 0, 0, 1, 0, 1, 20, 0, 16, 360, 1.0, 1

0,1,1,0,0,1,0,64000,16,6400,1.0,1
0,0,1,1,0,1,20,0,16,200,1.0,1
0,0,1,1,0,1,20,0,16,200,1.0,1
0,0,1,1,0,1,20,0,16,200,1.0,1
0,0,1,1,0,1,20,0,16,200,1.0,1
0,0,1,1,0,1,20,0,16,200,1.0,1

FILE 03 (CARD.DATE)

Col. No. 01

↓
100,112,62,2500,0,8,0.81,0.00000266,1000,500
100,112,62,2500,0,8,0.81,0.00000266,0,0
100,112,62,2500,0,8,0.81,0.00000266,0,0
100,112,62,2500,0,8,0.81,0.00000266,0,0
100,112,62,2500,0,8,0.81,0.00000266,0,0
100,112,62,2500,0,8,0.81,0.00000266,0,0
60,136,36,400,304,0,0.7,0.0000034,1000,60000
60,136,36,400,304,0,0.7,0.0000034,1000,60000
60,136,36,400,304,0,0.7,0.0000034,1000,60000
100,124,74,200,0,64,0.99,0.00010948,1000,8000

STEP 3 - Prepare to Run the Program.

free fi(ft06F001)

alloc fi(ft01f001) da(program.data)

alloc fi(ft02f001) da(device.data)

alloc fi(ft03f001) da(card.data)

alloc fi(ft06f001) da(output.text)

STEP 4 - Execute the Program.

CALL MCF.MODEL

STEP 5 - Print the Results of the Program.

PRINTOFF OUTPUT.TEXT

The LCC model output report giving the LCC effects using quality grade B MC devices is given in Table 4.2.1-3a, b, c. A similar set of tables (not shown) provides the LCC impacts using the other quality grades. A comparison of the quality grade effects taken from the model outputs is summarized in Table 4.2.1-4.

TABLE 4.2.1-3a EXAMPLE -1. MC DEVICE IMPACT ON LCC

MC DEVICE IMPACT ON LCC (THOUSANDS OF DOLLARS)			
COST ELEMENT	CONSTANT DOLLARS		
	5 YEARS	10 YEARS	15 YEARS
ADISE	0.	0.	0.
PRODUCTION	1539.	1539.	1539.
DEVICE PROCUREMENT	153.	153.	153.
DEVICE SCREEN	0.	0.	0.
CARD ASSEMBLY	1386.	1386.	1386.
OPERATIONS & SUPPORT	1408.	1893.	2378.
SPARES	1044.	1364.	1684.
SUPPORT EQUIPMENT	198.	198.	198.
INVENTORY ENTRY	51.	101.	151.
REPAIR LABOR	65.	130.	195.
REPAIR MATERIALS	50.	100.	150.
MAIN. TRANSPORTATION	0.	0.	0.
TOTAL COST	2947.	3432.	3917.

TABLE 4.2.1-3b EXAMPLE -1. LCC SUMMARY BY FISCAL YEAR

LCC SUMMARY BY FISCAL YEAR (THOUSANDS OF DOLLARS)								
FISCAL YEAR	PROGRAM PHASE	PROD	O&S	TOTAL DOLLARS	PRICE INDEX	INFLATED DOLLARS	DISC. FACT.	TOTAL COST
1940	0.	513.	0.	513.	1.000	513.	0.954	489.
1981	0.	513.	0.	513.	1.060	544.	0.867	472.
1982	0.	513.	0.	513.	1.124	573.	0.788	454.
1983	0.	0.	1020.	1020.	1.191	1213.	0.717	871.
1984	0.	0.	97.	97.	1.262	122.	0.651	79.
1985	0.	0.	97.	97.	1.338	133.	0.592	77.
1986	0.	0.	97.	97.	1.419	134.	0.538	74.
1987	0.	0.	97.	97.	1.504	140.	0.489	71.
1988	0.	0.	97.	97.	1.594	153.	0.445	69.
1989	0.	0.	97.	97.	1.689	164.	0.405	66.
1990	0.	0.	97.	97.	1.791	174.	0.368	64.
1991	0.	0.	97.	97.	1.898	193.	0.334	62.
1992	0.	0.	97.	97.	2.012	193.	0.304	59.
1993	0.	0.	97.	97.	2.133	207.	0.276	57.
1994	0.	0.	97.	97.	2.261	217.	0.251	55.
1995	0.	0.	97.	97.	2.397	232.	0.228	53.
1996	0.	0.	97.	97.	2.540	243.	0.208	51.
1997	0.	0.	97.	97.	2.693	261.	0.189	49.
TOTAL	0.	1539.	2378.	3917.		5421.		3172.

TABLE 4.2.1-3c EXAMPLE -1. DATA USED IN LCC ESTIMATES

DATA USED IN LCC ESTIMATE:

PROGRAM & O&S DATA					
M	39	M	20.	KR	20.00
MC	10	IS	336.	KM	87.44
FSTO	0.33	PL	0.95	KT	0.50
CMAX	203.33	TO	8760.	JC	1.00
CMIN	24.33	FR	1440.	KD	0.10
RATEA	43.75	FC	3.	KI	0.06
RATEB	35.33	U	0.05	YRDE	1980
RATEC	26.33	KI	54.00	FRDE	0
RATEC	26.33	KIR	128.00	YMANU	1980
RATEC	26.33	KJM	42.00	YMANU	3
				YOAS	1983

MC DEVICE DATA												
1	NEW	MEM	MOS	DIG	ECL	FP	NG	NH	NP	DEL	REL	SCRN
2	0.	0.	0.	1.	0.	1.	300.	0.	40.	6JJ.	1.0	1.
3	0.	0.	0.	1.	0.	1.	300.	0.	40.	6JJ.	1.0	1.
4	0.	0.	0.	1.	0.	1.	300.	0.	40.	6JJ.	1.0	1.
5	0.	0.	0.	1.	0.	1.	10.	0.	16.	30JJ.	1.0	1.
6	0.	0.	0.	1.	0.	1.	10.	0.	16.	30JJ.	1.0	1.
7	0.	0.	0.	1.	0.	1.	10.	0.	16.	30JJ.	1.0	1.
8	0.	0.	0.	1.	0.	1.	10.	0.	16.	30JJ.	1.0	1.
9	0.	0.	0.	1.	0.	1.	10.	0.	16.	30JJ.	1.0	1.
10	0.	0.	0.	1.	0.	1.	10.	0.	16.	30JJ.	1.0	1.
11	0.	0.	0.	1.	0.	1.	10.	0.	16.	30JJ.	1.0	1.
12	0.	0.	0.	1.	0.	1.	10.	0.	16.	30JJ.	1.0	1.
13	0.	0.	0.	1.	0.	1.	10.	0.	16.	30JJ.	1.0	1.
14	0.	0.	0.	1.	0.	1.	10.	0.	16.	30JJ.	1.0	1.
15	0.	0.	0.	1.	0.	1.	10.	0.	16.	30JJ.	1.0	1.
16	0.	0.	0.	1.	0.	1.	10.	0.	16.	30JJ.	1.0	1.
17	0.	0.	0.	1.	0.	1.	19.	0.	16.	30JJ.	1.0	1.
18	0.	0.	0.	1.	0.	1.	19.	0.	16.	30JJ.	1.0	1.
19	0.	0.	0.	1.	0.	1.	19.	0.	16.	30JJ.	1.0	1.
20	0.	0.	0.	1.	0.	1.	19.	0.	16.	30JJ.	1.0	1.
21	0.	0.	0.	1.	0.	1.	19.	0.	16.	30JJ.	1.0	1.
22	0.	0.	0.	1.	0.	1.	19.	0.	16.	30JJ.	1.0	1.
23	0.	0.	0.	1.	0.	1.	19.	0.	16.	30JJ.	1.0	1.
24	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
25	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
26	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
27	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
28	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
29	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
30	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
31	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
32	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
33	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
34	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
35	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
36	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
37	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
38	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
39	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
40	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
41	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
42	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
43	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
44	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
45	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
46	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
47	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
48	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
49	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
50	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
51	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
52	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
53	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
54	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
55	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
56	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
57	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
58	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
59	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
60	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
61	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
62	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
63	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
64	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
65	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
66	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
67	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
68	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
69	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
70	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
71	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
72	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
73	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
74	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
75	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
76	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
77	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
78	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
79	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
80	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
81	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
82	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
83	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
84	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
85	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
86	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
87	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
88	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
89	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
90	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
91	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
92	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
93	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
94	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
95	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
96	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
97	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
98	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
99	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.
100	0.	0.	0.	1.	0.	1.	20.	0.	16.	30JJ.	1.0	1.

* TOTAL QUANTITY OF MC DEVICES.

CARD DATA												
1	CARD	NDEV	NMC	JA	JH	JH1	JH2	QCD	NDJ	46	NRAM	CF
2	100.	112.	62.	J.	52.	0.	0.	0.	250J.	0.	8.	0.000027
3	100.	112.	52.	J.	62.	0.	0.	0.	250J.	0.	8.	0.000027
4	100.	112.	62.	J.	52.	0.	0.	0.	250J.	0.	8.	0.000027
5	100.	112.	52.	J.	62.	0.	0.	0.	250J.	0.	8.	0.000027
6	100.	112.	62.	J.	52.	0.	0.	0.	250J.	0.	8.	0.000027
7	60.	136.	36.	J.	36.	0.	0.	0.	40J.	334.	0.	0.000034
8	60.	136.	36.	J.	36.	0.	0.	0.	40J.	334.	0.	0.000034

TABLE 4.2.1-4. QUALITY GRADE IMPACT ON LCC (K\$)

COST ELEMENT	QUALITY GRADE			
	B	B-1	B-2	C
<u>Production</u>	<u>1539</u>	<u>1533</u>	<u>1566</u>	<u>1656</u>
Device Procurement	153	147	141	138
Card Assembly	1386	1386	1425	1518
<u>Maintenance & Support</u>	<u>2378</u>	<u>5629</u>	<u>11489</u>	<u>14286</u>
Spares	1684	4245	8860	11057
Support Equipment	198	198	198	198
Inventory Entry	151	151	151	151
Repair Labor	195	585	1275	1575
Repair Materials	150	435	960	1245
Main. Transportation	0	15	45	60
Totals	3917	7162	13055	15942

While the procurement cost increases as the quality grade increases, card assembly costs decrease (because of better yields in the factory) producing overall production costs that decrease as the quality grade increases. The most dramatic changes, however, occur in the Maintenance Support Phase. Over an operating life of 15 years significant cost differences occur as the quality grade of MC devices increases. This difference, of course, is driven by the operating profile (assumed 24 hours/day) the number of operating systems.

The results clearly indicate that the total cost to a system decreases as the quality grades of MC devices increase. However, it should be emphasized that in this example all MC devices quality grades are assumed to be available off-the-shelf. The degree to which they are not available greatly affects the procurement cost.

4.2.2 INHOUSE SCREENING TO B-1 VS QUALIFYING TO B

The affects on LCC of upgrading commercial grade devices (C-level) to a quality grade B-1 by inhouse screening versus the alternative of qualifying the vendor and these devices to a JAN B quality grade is analyzed. The digital logic LSI devices employed in the population of high-density cards defined in example 1 are candidates for this analysis.

Case 1 - Screen Commercial Grade LSI Devices to B-1

With reference to the data sets assembled in example 1, the changes necessary to analyze this problem are as follows:

- B quality level for all non-LSI MC devices
- LSI (i.e., 100 or more gates) are commercial grade - REL = 8.0

- LSI are screened (SCRN = 2)
- Card failure rates (CF) are adjusted per MIL-HDBK-217 (see step 1 in Example 1) so that the LSI devices are B-1. The only cards affected are the digital logic cards (CF = 3.14×10^{-6})
- Ratio contribution of LSI MC devices to card failure rate is re-calculated (W=.84)

These changes are made to the input files 02 (DEVICE.DATA) and 03 (CARD.DATA), and the data sets are re-allocated (STEP 3). The LCC model is then executed (STEP 4) and the results of the LCC estimate are provided in Tables 4.2.2-1a and 4.2.2-1b. For this population of cards, therefore, the total LCC impact is \$4,197k in constant dollars.

Case 2 - Qualify LSI Devices to JAN B

The B-level quality grade data is provided in Example 1 Table 4.2.1-3c. In this case, the device manufacturers must qualify the LSI commercial devices to JAN B at a cost of approximately \$150k per device (refer to Section 3.4 for a discussion on device qualification). For the four LSI device types being upgraded this is a total cost of \$600k that must be incurred for qualification. Therefore, the LCC for this case is \$4,517k in constant dollars.

For the card population used in the above cases, it turns out that device qualification is a more expensive solution to the problem. However, this result is clearly a function of card population. By increasing the card population, device screening becomes more expensive and eventually overcomes the cost of qualification at approximately double the original device population in this example. This is illustrated in Figure 4.2.2-1 where the points on the curve were obtained by successive runs of the LCC model with changes in card quantities (CARD) and corresponding changes in the MC device population (DEVQ).

4.2.3 CUSTOM LSI VS STANDARD SSI/MSI

The affects on LCC of implementing digital logic cards with custom LSI devices versus standard SSI/MSI devices into a system is analyzed. The custom digital logic LSI devices employed are assumed to be procured at a commercial grade (C-level) and require screening to a B-1 level. The device and card characteristics for these custom cards are given in Tables 4.2.1-1 and 4.2.1-2 of Example 1. The standard SSI/MSI device and card characteristics for this example are given in Tables 4.2.3-1 and 4.2.3-2.

TABLE 4.2.2-1a EXAMPLE -2. MC DEVICE IMPACT ON LCC

MC DEVICE IMPACT ON LCC (THOUSANDS OF DOLLARS)			
COST ELEMENT	CONSTANT DOLLARS		
	5 YEARS	10 YEARS	15 YEARS
ROUTE	0.	0.	0.
PRODUCTION	1848.	1848.	1848.
DEVICE PROCUREMENT	153.	153.	153.
DEVICE SCREEN	315.	315.	315.
CARD ASSEMBLY	1380.	1380.	1380.
OPERATIONS & SUPPORT	1924.	1924.	2924.
SPARES	1050.	1375.	1700.
SUPPORT EQUIPMENT	198.	198.	198.
INVENTORY ENTRY	51.	101.	151.
REPAIR LABOR	65.	130.	195.
REPAIR MATERIALS	60.	120.	180.
MAIN. TRANSPORTATION	0.	0.	0.
TOTAL COST	3272.	3772.	4272.

TABLE 4.2.2-1b EXAMPLE -2. LCC SUMMARY BY FISCAL YEAR

LCC SUMMARY BY FISCAL YEAR (THOUSANDS OF DOLLARS)								
FISCAL YEAR	ROUTE	PROGRAM PHASE		TOTAL DOLLARS	PRICE INDEX	INFLATED DOLLARS	DISC. FACT.	TOTAL COST
		PROD	O&S					
1980	0.	616.	0.	616.	1.000	616.	0.954	588.
1981	0.	616.	0.	616.	1.060	653.	0.867	566.
1982	0.	616.	0.	616.	1.124	692.	0.788	545.
1983	0.	0.	1024.	1024.	1.191	1222.	0.717	874.
1984	0.	0.	100.	100.	1.262	126.	0.651	82.
1985	0.	0.	100.	100.	1.338	134.	0.592	79.
1986	0.	0.	100.	100.	1.419	142.	0.538	76.
1987	0.	0.	100.	100.	1.504	151.	0.489	73.
1988	0.	0.	100.	100.	1.594	159.	0.445	71.
1989	0.	0.	100.	100.	1.689	167.	0.405	68.
1990	0.	0.	100.	100.	1.791	177.	0.368	66.
1991	0.	0.	100.	100.	1.898	187.	0.334	64.
1992	0.	0.	100.	100.	2.012	201.	0.304	61.
1993	0.	0.	100.	100.	2.133	213.	0.276	59.
1994	0.	0.	100.	100.	2.261	226.	0.251	57.
1995	0.	0.	100.	100.	2.397	240.	0.228	55.
1996	0.	0.	100.	100.	2.540	254.	0.208	53.
1997	0.	0.	100.	100.	2.693	269.	0.189	51.
TOTAL	0.	1848.	2924.	4272.		5833.		3488.

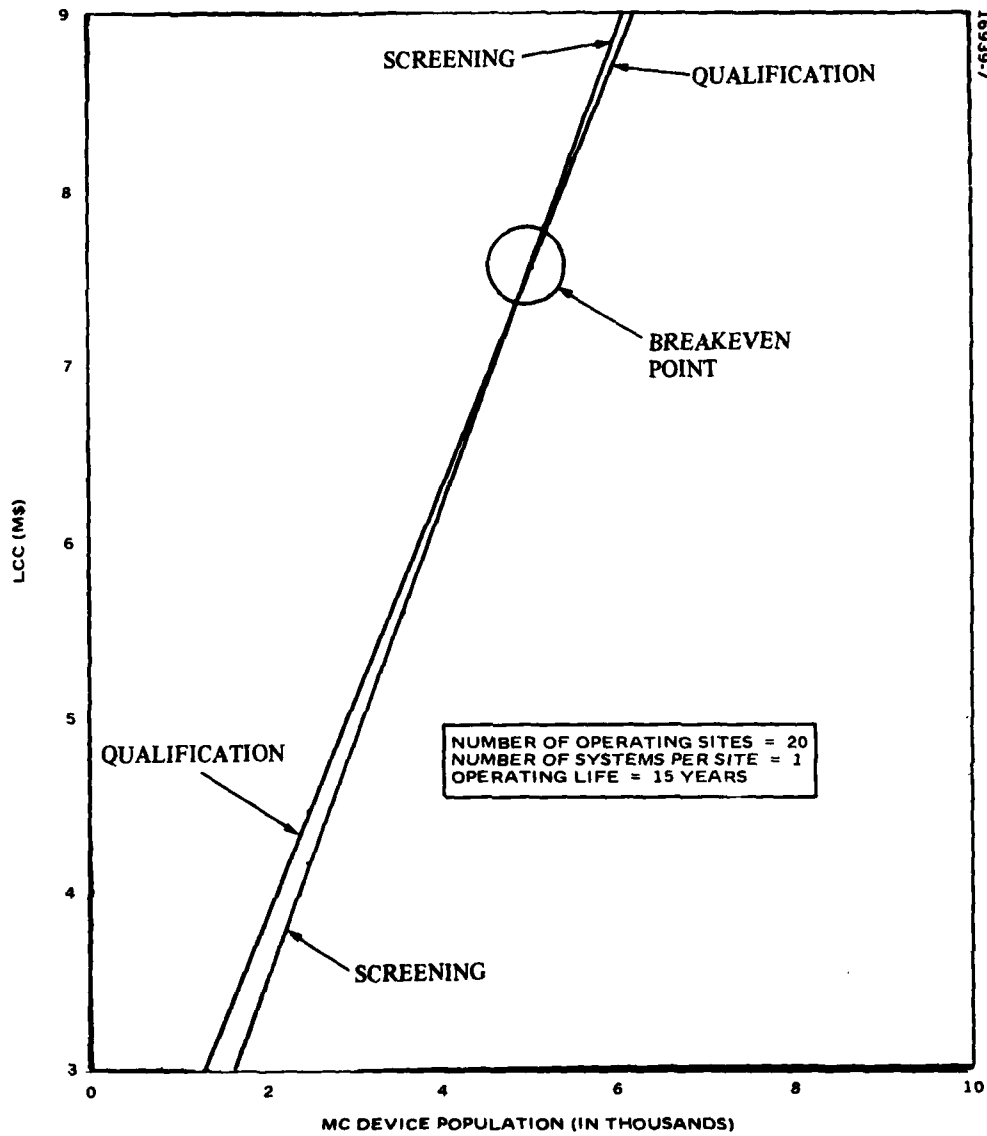


Figure 4.2.2-1. Vendor Qualification vs Inhouse Screening

Case 1 - Implement Digital Logic Functions With Custom LSI Devices

With reference to the data sets in Example 1 (Steps 1 and 2) changes necessary to analyze this problem are as follows:

- RDT&E start (YRDTE) is 1980 with a duration (TRDTE) of 1 year. Production starts (YMANU) in 1981 and Operations and Support starts (YOAS) in 1984.
- B quality level for all non-LSI MC devices.
- LSI devices are commercial grade (REL=8.0), new devices (NEW=1), and are to be screened (SCRN=2).
- The LSI devices are complete custom (FSTD=0) and, with the change to LSI, fault isolation to the card level is assumed (FC=0).
- Card failure rates (CF) are adjusted per MIL-HDBK-217. The only cards affected are the digital logic cards ($CF = 3.14 \times 10^{-6}$).
- The ratio card contribution of LSI MC devices to the card failure rate is re-calculated $W = .84$.
- For new cards, support equipment adapter cost (KA) is \$2,000 per card type and \$10,000 per card type for software development (KS). For all other cards, KA and KS are assumed to be zero.

The changes are made in the input FILE 01 (PROGRAM.DATA), FILE 02 (DEVICE.DATA) and FILE 03 (CARD.DATA). The data sets are re-allocated (Step 3) and the LCC model is executed (Step 4). The results of the model output is given in Tables 4.2.3-3a and b. The LCC estimate for this case is \$3,311K (constant dollars).

Case 2 - Implement Digital Logic Cards With Standard SSI/MSI Devices

For this case, the data needed for the digital logic cards is given in Tables 4.2.3-1 and 4.2.3-2. Card and system data is provided in Tables 4.2.3-1 and 4.2.3-2.

The changes to the data sets necessary to analyze this case are as follows:

- N=35, NC=49 and FC=3 for FILE 01
- Replace the input data for the "custom" digital logic cards with the input data for the "standard" digital logic cards in FILES 02 and 03, recalculating the parameter values from Tables 4.2.3-1, -2 as described previously.
- B quality level for all MC devices (REL=1).

TABLE 4.2.3-1. CARD DATA FOR EXAMPLE -3 (CASE 2)

DEVICE DESCRIPTION	DEVICE TYPE EACH CATEGORY	DEVICE QTY PER TYPE	TOTAL DEVICES PER CARD	TOTAL GATES PER CARD (NG)	TOTAL FAILURE RATE PER CARD (CR)
SSI/MSI Digital Logics @ 16 gates/device 10 gates/device 6 gates/device Active and Passive devices	7	4	28	448	.448
	3	4	12	120	.192
	1	20	20	120	.320
	-	50	50	--	.500
			NDEV=110	NDG=688	1.460

TABLE 4.2.3-2. SYSTEM DATA FOR EXAMPLE -3 (CASE 2)

CARD DESCRIPTION	NUMBER OF CARD TYPES	QTY OF CARDS PER TYPE (CARD)	TOTAL CARDS PER SYSTEM	TOTAL FOR 20 SITES
Digital Logic (SSI/MSI)	45	50	112	2,250

- None of the devices are to be screened (SCRN=1).
- Software and card adapter development costs for the cards is assumed to have been developed (i. e., KA=KS=0).

The results of the model output for this case are given in Tables 4.2.3-4a and b. The LCC estimate for this case is \$6,480 (constant dollars).

Therefore, for the card and device population used in the above cases, the development and implementation of custom LSI devices is less expensive in LCC than standard SSI/MSI devices. However, the most significant determining factor for the outcome of this example tradeoff is the difference in the number of cards necessary for LSI implementation versus those required for the standard SSI/MSI implementation. The total number of digital logic cards using LSI is 600 and the number of cards using SSI/MSI is 2,250. This factor alone has a tremendous impact on the card assembly cost and on maintenance support costs. Obviously, an implementation leading to a smaller card difference could swing this tradeoff the other way.

TABLE 4.2.3-3a EXAMPLE -3. MC DEVICE IMPACT ON LCC (CASE 1)

MC DEVICE IMPACT ON LCC (THOUSANDS OF DOLLARS)			
COST ELEMENT	CONSTANT DOLLARS		
	5 YEARS	10 YEARS	15 YEARS
ROT&E	406.	406.	406.
PRODUCTION	1881.	1881.	1881.
DEVICE PROCUREMENT	153.	153.	153.
DEVICE SCREEN	348.	348.	348.
CARD ASSEMBLY	1380.	1380.	1380.
OPERATIONS & SUPPORT	614.	819.	1024.
SPARES	416.	496.	376.
SUPPORT EQUIPMENT	72.	72.	72.
INVENTORY ENTRY	51.	101.	151.
REPAIR LABOR	15.	30.	45.
REPAIR MATERIALS	63.	120.	183.
MAIN. TRANSPORTATION	0.	0.	0.
TOTAL COST	2901.	3106.	3511.

TABLE 4.2.3-3b EXAMPLE -3. LCC SUMMARY BY FISCAL YEAR (CASE 1)

LCC SUMMARY BY FISCAL YEAR (THOUSANDS OF DOLLARS)								
FISCAL YEAR	ROT&E	PROGRAM PHASE	DIS	TOTAL DOLLARS	PRICE INDEX	INFLATION DOLLARS	DISC. FACT.	TOTAL COST
		PROD						
1980	406.	0.	0.	406.	1.000	406.	0.954	387.
1981	0.	627.	0.	627.	1.360	857.	0.867	577.
1982	0.	627.	0.	627.	1.124	707.	0.788	559.
1983	0.	627.	0.	627.	1.191	747.	0.717	535.
1984	0.	0.	450.	450.	1.262	564.	0.651	370.
1985	0.	0.	41.	41.	1.338	53.	0.592	33.
1986	0.	0.	41.	41.	1.419	53.	0.538	31.
1987	0.	0.	41.	41.	1.504	52.	0.489	30.
1988	0.	0.	41.	41.	1.594	52.	0.445	29.
1989	0.	0.	41.	41.	1.689	52.	0.405	28.
1990	0.	0.	41.	41.	1.791	73.	0.368	27.
1991	0.	0.	41.	41.	1.898	73.	0.334	26.
1992	0.	0.	41.	41.	2.012	83.	0.304	25.
1993	0.	0.	41.	41.	2.133	87.	0.276	24.
1994	0.	0.	41.	41.	2.261	93.	0.251	23.
1995	0.	0.	41.	41.	2.397	93.	0.228	22.
1996	0.	0.	41.	41.	2.540	104.	0.208	22.
1997	0.	0.	41.	41.	2.693	113.	0.189	21.
1998	0.	0.	41.	41.	2.854	117.	0.172	20.
TOTAL	406.	1881.	1024.	3511.		4242.		2785.

TABLE 4.2.3-4a EXAMPLE -3. MC DEVICE
IMPACT ON LCC (CASE 2)

MC DEVICE IMPACT ON LCC (THOUSANDS OF DOLLARS)			
COST ELEMENT	CONSTANT DOLLARS		
	5 YEARS	10 YEARS	15 YEARS
ROUT&E	0.	0.	0.
PRODUCTION	3030.	3030.	3030.
DEVICE PROCUREMENT	267.	267.	267.
DEVICE SCREEN	0.	0.	0.
CARD ASSEMBLY	2763.	2763.	2763.
OPERATIONS & SUPPORT	2110.	2780.	3430.
SPARES	1762.	2087.	2412.
SUPPORT EQUIPMENT	0.	0.	0.
INVENTORY ENTRY	243.	483.	723.
REPAIR LABOR	73.	140.	210.
REPAIR MATERIALS	33.	70.	105.
MAIN. TRANSPORTATION	0.	0.	0.
TOTAL COST	5143.	5810.	6480.

TABLE 4.2.3-4b EXAMPLE -3. LCC SUMMARY BY FISCAL YEAR (CASE 2)

LCC SUMMARY BY FISCAL YEAR (THOUSANDS OF DOLLARS)								
FISCAL YEAR	ROUT&E	PROGRAM PHASE	Q&S	TOTAL DOLLARS	PRICE INDEX	INFLATION DOLLARS	DISC. FACT.	TOTAL COST
1980	C.	1010.	0.	1010.	1.000	1010.	0.954	963.
1981	J.	1010.	0.	1010.	1.060	1071.	0.867	923.
1982	O.	1010.	0.	1010.	1.124	1133.	0.788	895.
1983	J.	0.	1574.	1574.	1.191	1873.	0.717	1544.
1984	O.	0.	134.	134.	1.262	167.	0.631	110.
1985	J.	0.	134.	134.	1.338	173.	0.592	106.
1986	O.	0.	134.	134.	1.419	173.	0.538	102.
1987	J.	0.	134.	134.	1.504	201.	0.489	94.
1988	J.	0.	134.	134.	1.594	214.	0.445	93.
1989	O.	0.	134.	134.	1.689	223.	0.405	91.
1990	O.	0.	134.	134.	1.791	243.	0.368	88.
1991	O.	0.	134.	134.	1.898	254.	0.334	85.
1992	O.	0.	134.	134.	2.012	277.	0.304	82.
1993	O.	0.	134.	134.	2.133	283.	0.276	79.
1994	J.	0.	134.	134.	2.261	303.	0.251	76.
1995	J.	0.	134.	134.	2.397	321.	0.228	73.
1996	J.	0.	134.	134.	2.540	347.	0.208	71.
1997	C.	0.	134.	134.	2.693	361.	0.189	68.
TOTAL	J.	3030.	3450.	6480.		8640.		5355.

Section 5.0

CONCLUSIONS AND RECOMMENDATIONS

A method of assessing the life cycle cost (LCC) impact of microcircuits (MC) on military electronic systems has been developed which uses parametric cost estimating relationships (CER's). The CER's have been combined into a comprehensive computerized LCC model which has been exercised to determine the general effects of MC factors on LCC. These general effects are summarized in Section 1.0 together with the underlying assumptions and ground rules used in the development of the CER's.

MC factors are categorized (see Table 2, 3-1) with respect to technology, function, packaging, complexity, and quality/reliability. The factors that were cost sensitive were found to have effects which extend over the entire operational life cycle of a system. For example, device technology (i. e., linear, digital, bipolar MOS, ECL, etc) has an effect on device purchase price which determines the bulk of the circuit card assembly (CCA) material and cost and, therefore, effects the cost of spares needed for maintenance support. Similarly, MC device complexity (i. e., number of gates or memory bits) can have an effect on design partitioning and, therefore, on the cost, numbers and types of CCA's employed in the system. Device complexity can, therefore, result in a direct impact on system spares, and on inventory entry and supply management.

Although the LCC model structure is general, the CER's used in the model should be updated periodically to reflect significant changes in MC technology. Specifically, changes with regard to availability of new technologies (i. e., ECL, IIL, etc) at the higher complexity levels. As more data becomes available on these devices, the appropriate CER's should be expanded. As stated earlier in this report, the CER's are not generally applicable to hybrid technology. Because of the fabrication techniques unique to hybrids, it is recommended that separate CER's be developed for these devices. An independent study of hybrid fabrication techniques and costs was conducted by Hughes⁶ and could be used as a starting point for this development.

Finally, those costs which are insensitive to differences in MC characteristics have not been included in the CER's. The LCC model should, therefore, be used only for comparative analyses and not for estimating total cost.

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Appendix A
Regression Analysis Results

Each of the regression runs in this appendix provide the following information:

- a) The data sets necessary to execute the regression analysis. The data sets variable names and format codes are provided at the top of each data set.
- b) A list of the means and standard deviations for the variables considered in the regression analysis.
- c) A correlation matrix for each of the independent variables showing the individual correlations with the dependent variables.
- d) The stepwise regression equations for the CER. At each step the multiple R, the standard error of estimate, and an Analysis-of-variance table is provided. For the independent variables in the equation regression coefficients, standard error, and F-to-remove values are given. For the variables not in the equation, partial correlations, Tolerances and F-to-enter values are given. (Section 2.2.)
- e) A summary table of the regression analysis. Included in this table is a summary of the regression steps, the step at which variables were entered into the equation, the multiple R and R^2 values, the increase in the R^2 value, the F-value to enter or remove, and the number of independent variables included in the CER.
- f) A list of residuals and plots of the residuals against the observations and against the computed values of the dependent variable.

REGRESSION ANALYSIS RESULTS FOR DEVICE PROCUREMENT
(PCER1)

A-3

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LABELS	1S	2LS	3L	4H	5MEM	6LNPUR
LABELS	7DIG	8LIN	9OTHER	10ECL	11CMOS	12MOS
LABELS	13NG	14HERMET	15FP	16REL	17NB	1816/13
LABELS	1916/17	56PURCH				
(5F2.0,12X,F6.4,6F2.0,F3.0,2F2.0,F5.1,F5.0/F8.4,F7.5)						
0 0 0 0	54/74193	- 1997	1 0 1 0	0 0 0 48	1 0	80 0
1667 0						
0 1 0 0	54/74LS113	3365	1 0 0 0	0 0 0 16	1 1	10 0
0625 0						
0 1 0 0	54/74LS257	- 0222	1 0 0 0	0 0 0 15	1 0	30 0
2000 0						
0 0 0 1	54/74H00	- 6733	1 0 0 0	0 0 0 4	1 0	65 0
16250 0						
0 0 0 1	54/74H72	- 2319	1 0 0 0	0 0 0 8	1 1	10 0
1250 0						
0 0 0 1	54/74H101	3920	1 0 0 0	0 0 0 10	1 1	10 0
1000 0						
0 0 0 0	9093	3001	1 0 1 0	0 0 0 16	1 0	30 0
1875 0						
0 0 0 0	9614	3436	1 0 1 0	0 0 0 6	1 0	30 0
5000 0						
0 0 0 0	9311	7324	1 0 1 0	0 0 0 25	1 1	80 0
3200 0						
0 0 0 0	LM101A	0276	0 1 1 0	0 0 0 21	1 0	65 0
3095 0						
0 0 0 0	711	2271	0 1 1 0	0 0 0 4	1 1	30 0
7500 0						
0 0 0 0	723	9933	0 1 1 0	0 0 0 5	1 0	10 0
2000 0						
0 0 0 0	7815	6663	0 1 1 0	0 0 0 4	1 1	30 0
7500 0						
0 0 0 0	9615	- 1985	0 1 1 0	0 0 0 9	1 0	80 0
8889 0						
0 0 0 0	9301	4606	1 0 1 0	0 0 0 18	1 1	65 0
3611 0						
0 0 0 0	710	- 3638	0 1 1 0	0 0 0 2	1 1	65 0
32500 0						
0 0 0 0	54/74365	-13665	1 0 1 0	0 0 0 7	0 0	350 0
50000 0						
0 0 0 0	LM106	-12040	0 1 1 0	0 0 0 3	0 0	350 0
116667 0						
0 0 0 0	54/7492	-14397	1 0 1 0	0 0 0 26	0 0	350 0
13462 0						
1 0 0 0	54/74S03	-13744	1 0 0 0	0 0 0 4	1 0	175 0
43750 0						
0 0 0 0	4001	- 5534	1 0 0 0	1 0 4	1 0	65 0
16250 0						
0 0 0 0	4025	19459	1 0 0 0	1 0 3	1 1	10 0
3333 0						
0 0 0 0	4075	-18972	1 0 0 0	1 0 3	1 0	175 0
58333 0						
0 0 0 0	10101	10818	1 0 0 1	0 0 4	1 0	80 0
20000 0						
0 0 0 0	10104	21401	1 0 0 1	0 0 4	1 1	30 0
7500 0						
0 0 0 0	10106	- 3567	1 0 0 1	0 0 3	1 0	175 0
58333 0						
1 0 0 0	1 82S16	14540	0 0 0 0	0 0 0	0 1 1	65 256
0 02539	3938462					
1 0 0 0	1 82S126	22513	0 0 0 0	0 0 0	0 1 0	10 1024
0 00098	1024					
0 1 0 0	1 27LS00	5878	0 0 0 0	0 0 0	0 0 0	350 256
0 18672	731429					
1 0 0 0	1 82S184	34012	0 0 0 0	0 0 0	0 1 1	80 8192
0 00098	1024					
0 0 1 0	1 93L425	28034	0 0 0 0	0 0 0	0 1 1	65 1024
0 00635	15753844					
0 1 0 0	1 74LS207	24204	0 0 0 0	0 0 0	0 0 0	350 1024
0 03418	2925714					

1	0	0	0	1	74S188	- 5961	0	0	0	0	0	0	0	0	1	0	80	256
0					03125 32													
1	0	0	0	1	74S476	16409	0	0	0	0	0	0	0	0	1	0	175	4096
0					00427 23405714													
1	0	0	0	1	82S191	29857	0	0	0	0	0	0	0	0	1	0	8016384	
0					00049 2048													
1	0	0	0	1	54S89	14351	0	0	0	0	0	0	0	0	1	1	65	256
0					02539 3938462													
1	0	0	0	1	82S09	34275	0	0	0	0	0	0	0	0	1	1	30	576
0					00521 192													
0	1	0	0	1	74LS314	18795	0	0	0	0	0	0	0	0	1	0	175	1024
0					01709 5851429													
1	0	0	0	1	82S23	11474	0	0	0	0	0	0	0	0	1	1	30	256
0					01172 8533333													
1	0	0	0	1	74S477	16409	0	0	0	0	0	0	0	0	1	0	175	4096
0					00427 23405714													
1	0	0	0	1	74S387	1823	0	0	0	0	0	0	0	0	0	0	350	1024
0					03418 2925714													
0	0	0	0	1	93448	25533	0	0	1	0	0	0	0	0	1	1	65	4096
0					00159 63015385													
0	0	0	1	0	54/74H50	-10642	1	0	0	0	0	0	0	6	1	0	80	0
13333	0																	
0	0	0	0	0	78M12	5247	0	1	1	0	0	0	0	4	1	1	30	0
7500	0																	
0	0	0	0	0	10016	22246	1	0	0	1	0	0	59	1	1	1	30	0
0508	0																	
0	0	0	0	0	741A	9933	0	1	1	0	0	0	0	6	1	1	65	0
10833	0																	
0	0	0	0	0	555	3485	0	1	1	0	0	0	0	6	1	0	30	0
5000	0																	
0	0	0	0	0	9614	4055	1	0	1	0	0	0	0	6	1	1	80	0
13333	0																	
0	0	0	0	1	4050	- 7985	0	0	0	0	0	1	0	1	0	0	30	0
0																		
0	0	0	0	0	711	22354	0	1	1	0	0	0	0	4	1	0	10	0
25	0																	
0	0	0	1	0	54/74H04	- 0030	1	0	0	0	0	0	0	6	1	0	10	0
1667	0																	
0	0	0	1	0	54/74H103	5008	1	0	0	0	0	0	12	1	0	0	10	0
0833	0																	
0	1	0	0	0	54/74LS00	- 8989	1	0	0	0	0	0	0	4	1	0	65	0
16250	0																	
0	0	0	0	0	9601	- 7700	1	0	0	0	0	0	0	8	1	0	80	0
1																		
1	0	0	0	1	82S129	8671	0	0	1	0	0	0	0	0	1	0	80	256
0					03125 32													
1	0	0	0	1	82S10	30564	0	0	1	0	0	0	0	0	1	1	30	256
0					01172 8533333													
0	0	0	1	0	54/74H40	- 3467	1	0	0	0	0	0	0	2	1	1	30	0
15	0																	
0	1	0	0	0	54/74LS00	- 8989	1	0	0	0	0	0	0	4	1	1	30	0
75	0																	
0	1	0	0	0	54/74LS166	5008	1	0	0	0	0	0	68	1	0	0	65	0
0956	0																	
0	0	0	0	0	10116	17047	1	0	0	1	0	0	0	4	1	0	30	0
75	0																	
0	0	0	0	0	10124	20541	1	0	0	1	0	0	0	4	1	1	30	0
75	0																	
0	0	0	0	0	10125	0583	1	0	0	1	0	0	0	4	0	0	350	0
875	0																	
0	0	0	0	0	10109	16390	1	0	0	1	0	0	0	2	1	1	80	0
4																		
0	0	0	0	0	10131	14469	1	0	0	1	0	0	10	1	0	0	80	0
8																		
0	0	0	0	0	4011	3646	1	0	0	0	1	0	0	4	1	1	30	0
75	0																	
0	0	0	0	0	4066	13900	0	1	0	0	1	0	0	4	1	1	65	0
16250	0																	


```

0 0 0 0 0 4555 - 7133 0 1 0 0 1 0 13 1 0 175 0
13462 0
0 0 0 0 0 40192 - 4943 1 0 0 0 1 0 47 0 0 350 0
7447 0
0 0 0 0 0 4040 - 2984 1 0 0 0 1 0 29 1 0 80 0
2759 0

```

VARIABLE	MEAN	STANDARD DEVIATION
S	0.18841	0.39390
LS	0.26087	1.23255
L	0.01449	0.12039
H	0.10145	0.30413
MEM	0.26087	0.44233
LNPUR	0.62332	1.27848
DIG	0.53623	0.50234
LIN	0.18841	0.39390
OTHER	0.31384	0.46944
ECL	0.13043	0.33925
CHOS	0.11594	0.32250
MOS	0.01449	0.12039
NG	8.52174	13.59453
HERMET	0.80406	0.32250
FP	0.40580	0.49464
REL	9.59620	10.29603
RD	642.78247	2311.72314
16/13	1.14307	2.08363
16/17	0.00628	0.02376
20	86.68942	305.97314
21	254.75362	779.74268
22	1.55072	6.77264
23	1.36232	7.22123
24	1.37621	5.23730
25	1.28261	4.91955
26	0.05797	0.48154
27	520.34766	2275.78467
28	7.26087	12.70784
29	5.53623	4.91668
30	0.17391	0.38181
31	0.01449	0.12039
32	0.0	0.0
33	1.55797	4.05797
34	0.18841	0.39390
35	0.08696	0.28384
36	0.04348	0.20542
37	0.07246	0.26115
38	0.0	0.0
39	6.63043	42.41353
40	0.08696	0.28383
41	0.02899	0.16899
42	1.55072	8.55006
43	181.79709	1241.08350
44	0.01449	0.12039
45	0.0	0.0
46	0.0	0.0
47	0.09620	0.78251
48	0.01449	0.12039
49	0.01449	0.12039
50	0.0	0.0
51	14.84058	123.27504
52	2.80435	6.95374
53	0.23128	0.42513
54	627.94189	2312.52568
55	0.11594	0.32250
56	4.23464	6.38981

CORRELATION MATRIX

VARIABLE NUMBER	1	2	3	4	5	7	8	9	10
1	1.000	-0.103	-0.058	-0.162		-0.444	-0.232	-0.171	-0.187
2		1.000	-0.026	-0.072		-0.110	-0.103	-0.146	-0.083
3			1.000	-0.041		-0.130	-0.058	-0.083	-0.047
4				1.000		0.312	-0.162	-0.230	-0.138
5					1.000	-0.639	-0.286	-0.194	-0.230
6						-0.397	-0.093	-0.092	0.216
7						1.000	-0.518	-0.237	0.340
8							1.000	0.545	-0.187
9								1.000	-0.265
10									1.000

VARIABLE NUMBER	11	12	13	14	15	16	17	18	19	20
1	-0.174	-0.058	-0.293	0.174	0.055	-0.062	0.445	-0.188	0.112	0.481
2	-0.077	-0.026	-0.041	-0.367	-0.128	0.350	0.005	-0.102	0.234	-0.046
3	-0.044	-0.015	-0.077	0.044	0.147	-0.037	0.020	-0.067	0.000	0.028
4	-0.122	-0.041	-0.041	0.122	0.016	-0.214	-0.194	-0.071	-0.089	-0.076
5	-0.215	0.204	-0.375	0.009	0.047	0.067	0.457	-0.328	0.400	0.477
6	-0.187	-0.136	-0.175	0.223	0.383	-0.279	0.432	-0.432	0.074	0.463
7	0.155	-0.130	0.404	0.026	-0.060	-0.063	-0.391	0.186	-0.286	-0.307
8	0.057	-0.058	-0.071	0.059	0.055	-0.088	-0.135	0.152	-0.128	-0.138
9	-0.248	-0.083	0.075	-0.044	0.068	-0.032	-0.129	0.067	-0.123	-0.119
10	-0.140	-0.047	0.055	0.006	0.030	0.009	-0.108	0.279	-0.103	-0.111
11	1.000	-0.044	0.130	-0.010	-0.023	0.081	-0.101	0.074	-0.096	-0.103
12		1.000	-0.077	0.044	-0.100	-0.078	-0.034	-0.267	-0.032	-0.035
13			1.000	-0.063	-0.108	0.032	-0.177	-0.124	-0.138	-0.180
14				1.000	0.299	-0.900	0.056	-0.402	-0.393	0.094
15					1.000	-0.418	-0.040	-0.190	-0.109	-0.017
16						1.000	0.036	0.487	0.373	-0.061
17							1.000	-0.155	-0.011	0.917
18								1.000	-0.147	-0.158
19									1.000	-0.039
20										1.000

VARIABLE NUMBER	21	22	23	24	25	26	27	28	29	30
1	-0.158	-0.111	-0.092	-0.128	-0.127	0.252	0.478	-0.266	0.270	0.952
2	0.003	-0.049	-0.041	-0.054	-0.056	-0.026	-0.049	-0.022	-0.151	-0.098
3	-0.040	-0.028	-0.023	-0.032	-0.032	-0.015	-0.023	-0.070	0.014	-0.056
4	-0.086	-0.077	-0.064	-0.089	-0.089	-0.041	-0.077	-0.011	-0.170	-0.154
5	-0.196	-0.137	-0.113	-0.157	-0.156	-0.072	0.588	-0.342	0.161	0.772
6	-0.040	-0.175	0.187	-0.255	-0.004	-0.191	0.374	-0.071	-0.073	0.459
7	0.373	0.141	0.177	0.112	0.244	0.113	-0.248	0.346	-0.070	-0.493
8	-0.116	-0.017	-0.092	0.043	-0.127	-0.058	-0.111	-0.036	-0.049	-0.221
9	-0.024	-0.158	-0.130	-0.181	-0.180	-0.083	-0.151	0.060	-0.167	-0.150
10	0.077	-0.089	0.491	-0.103	0.678	-0.047	-0.089	0.394	0.032	-0.178
11	0.073	0.637	-0.069	0.731	-0.095	-0.044	-0.083	0.007	0.146	-0.166
12	-0.040	-0.028	-0.023	-0.032	-0.032	-0.015	-0.028	-0.070	-0.063	-0.056
13	0.942	0.379	0.430	0.292	-0.049	-0.041	-0.145	0.931	-0.078	-0.290
14	-0.054	-0.233	0.064	-0.209	-0.229	0.044	0.083	0.208	0.411	0.186
15	-0.079	-0.142	0.127	-0.159	-0.114	-0.100	-0.062	-0.033	-0.187	0.088
16	0.037	0.253	-0.073	0.296	0.264	0.094	0.035	-0.214	0.028	-0.094
17	-0.092	-0.065	-0.053	-0.074	-0.074	-0.034	0.972	-0.161	0.203	0.470
18	-0.128	-0.028	-0.019	0.093	0.529	0.189	-0.127	-0.174	0.098	-0.254
19	-0.028	-0.061	-0.051	-0.070	-0.070	-0.032	-0.037	-0.153	-0.122	0.126
20	-0.074	-0.066	-0.054	-0.076	-0.075	-0.035	0.637	-0.154	0.087	0.507
21	1.000	0.288	0.477	0.228	-0.039	-0.037	-0.076	0.860	-0.046	-0.151
22		1.000	-0.044	0.861	-0.061	-0.028	-0.053	0.051	-0.006	-0.106
23			1.000	-0.050	0.171	-0.023	-0.044	0.477	-0.053	-0.087
24				1.000	-0.070	-0.032	-0.061	-0.024	0.140	-0.122
25					1.000	-0.032	-0.060	-0.059	0.027	-0.121
26						1.000	-0.028	-0.031	0.297	-0.056
27							1.000	-0.133	0.201	0.502
28								1.000	0.030	-0.264
29									1.000	0.185
30										1.000

VARIABLE NUMBER	31	32	33	34	35	36	37	38	39	40
1	0.282	0.0	0.803	1.000	0.641	-0.103	-0.135	0.0	-0.076	-0.149
2	-0.026	0.0	-0.032	-0.103	-0.066	0.129	0.159	0.0	0.991	0.186
3	-0.015	0.0	-0.047	-0.038	-0.037	-0.024	-0.034	0.0	-0.019	-0.037
4	-0.041	0.0	-0.130	-0.162	-0.104	-0.072	-0.094	0.0	-0.053	-0.104
5	-0.072	0.0	0.568	0.727	0.519	0.359	-0.164	0.0	-0.225	-0.066
6	-0.191	0.0	0.180	0.336	0.413	0.169	-0.181	0.0	-0.024	-0.115
7	0.113	0.0	-0.290	-0.444	-0.332	-0.229	0.260	0.0	-0.156	0.184
8	-0.053	0.0	-0.186	-0.232	-0.149	-0.103	-0.135	0.0	-0.074	-0.149
9	-0.023	0.0	-0.180	-0.171	-0.101	-0.166	-0.191	0.0	-0.108	-0.211
10	-0.047	0.0	-0.150	-0.187	-0.120	-0.083	-0.108	0.0	-0.061	-0.120
11	-0.044	0.0	-0.140	-0.174	-0.112	-0.077	-0.101	0.0	-0.057	-0.112
12	-0.015	0.0	-0.047	-0.058	-0.037	-0.024	-0.034	0.0	-0.019	-0.037
13	-0.041	0.0	-0.226	-0.293	-0.195	-0.135	0.267	0.0	-0.036	0.213
14	0.044	0.0	0.140	0.174	0.112	-0.367	0.101	0.0	-0.393	0.112
15	-0.100	0.0	-0.100	0.033	0.373	-0.176	-0.003	0.0	-0.127	-0.044
16	0.074	0.0	0.099	-0.062	-0.139	0.408	-0.153	0.0	0.361	-0.101
17	-0.054	0.0	0.443	0.445	0.133	0.012	-0.078	0.0	0.019	-0.063
18	0.159	0.0	-0.081	-0.168	-0.171	-0.113	-0.081	0.0	-0.083	-0.103

19	-0.012	0.0	0.052	0.112	0.093	0.660	-0.074	0.0	0.250	-0.045
20	-0.035	0.0	0.315	0.431	0.160	-0.039	-0.090	0.0	-0.031	-0.078
21	-0.037	0.0	-0.126	-0.158	-0.102	-0.079	0.279	0.0	-0.038	0.240
22	-0.008	0.0	-0.029	-0.111	-0.071	-0.049	-0.054	0.0	-0.036	-0.071
23	-0.023	0.0	-0.073	-0.092	-0.059	-0.061	-0.053	0.0	-0.030	-0.059
24	-0.032	0.0	-0.102	-0.128	-0.082	-0.056	-0.074	0.0	-0.042	-0.082
25	-0.032	0.0	-0.102	-0.127	-0.081	-0.056	-0.073	0.0	-0.041	-0.081
26	1.000	0.0	0.430	0.252	-0.037	-0.025	-0.034	0.0	-0.019	-0.037
27	-0.020	0.0	0.471	0.478	0.152	-0.049	-0.064	0.0	-0.036	-0.071
28	-0.031	0.0	-0.003	-0.256	-0.173	-0.123	0.313	0.0	-0.076	0.259
29	0.227	0.0	0.510	0.270	-0.034	0.013	-0.088	0.0	-0.150	0.045
30	-0.056	0.0	0.677	0.952	0.573	-0.098	-0.128	0.0	-0.072	-0.142
31	1.000	0.0	0.420	0.252	-0.037	-0.026	-0.034	0.0	-0.019	-0.037
32		0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
33			1.000	0.803	0.264	-0.082	-0.108	0.0	-0.061	-0.119
34				1.000	0.641	-0.133	-0.135	0.0	-0.076	-0.149
35					1.000	-0.066	-0.086	0.0	-0.049	-0.093
36						1.000	-0.060	0.0	0.114	0.186
37							1.000	0.0	-0.017	0.006
38								0.0	0.0	0.0
39								1.000	0.0	-0.003
40									1.000	1.000

VARIABLE NUMBER	41	42	43	44	45	46	47	48	49	50
1	-0.083	-0.088	-0.071	-0.058	0.0	0.0	-0.058	-0.058	-0.058	0.0
2	0.104	0.110	0.075	-0.026	0.0	0.0	-0.026	-0.026	-0.026	0.0
3	-0.021	-0.022	-0.018	1.000	0.0	0.0	1.000	1.000	1.000	0.0
4	-0.053	-0.061	-0.050	-0.041	0.0	0.0	-0.041	-0.041	-0.041	0.0
5	-0.103	-0.109	-0.026	0.204	0.0	0.0	0.204	0.204	0.204	0.0
6	-0.123	-0.047	-0.013	0.208	0.0	0.0	0.208	0.208	0.208	0.0
7	0.161	0.170	-0.159	-0.130	0.0	0.0	-0.130	-0.130	-0.130	0.0
8	-0.023	-0.028	-0.071	-0.058	0.0	0.0	-0.058	-0.053	-0.058	0.0
9	-0.113	-0.125	-0.101	-0.083	0.0	0.0	-0.083	-0.083	-0.083	0.0
10	-0.057	-0.071	-0.057	-0.047	0.0	0.0	-0.047	-0.047	-0.047	0.0
11	-0.063	-0.066	-0.053	-0.044	0.0	0.0	-0.044	-0.044	-0.044	0.0
12	-0.021	-0.022	-0.018	-0.015	0.0	0.0	-0.015	-0.015	-0.015	0.0
13	0.019	0.035	-0.093	-0.077	0.0	0.0	-0.077	-0.077	-0.077	0.0
14	0.053	0.066	-0.070	0.044	0.0	0.0	0.044	0.044	0.044	0.0
15	0.009	-0.031	-0.122	0.147	0.0	0.0	0.147	0.147	0.147	0.0
16	-0.118	-0.051	0.346	-0.037	0.0	0.0	-0.037	-0.037	-0.037	0.0
17	-0.048	-0.051	0.024	0.020	0.0	0.0	0.020	0.020	0.020	0.0
18	-0.052	-0.084	-0.082	-0.067	0.0	0.0	-0.067	-0.067	-0.067	0.0
19	-0.046	-0.049	0.185	0.000	0.0	0.0	0.000	0.000	0.000	0.0
20	-0.049	-0.052	-0.027	0.028	0.0	0.0	0.028	0.028	0.028	0.0
21	-0.027	0.050	-0.049	-0.040	0.0	0.0	-0.040	-0.040	-0.040	0.0
22	-0.040	-0.042	-0.034	-0.028	0.0	0.0	-0.028	-0.028	-0.028	0.0
23	-0.033	-0.035	-0.023	-0.023	0.0	0.0	-0.023	-0.023	-0.023	0.0
24	-0.046	-0.048	-0.037	-0.032	0.0	0.0	-0.032	-0.032	-0.032	0.0
25	-0.045	-0.048	-0.037	-0.032	0.0	0.0	-0.032	-0.032	-0.032	0.0
26	-0.021	-0.022	-0.018	-0.015	0.0	0.0	-0.015	-0.015	-0.015	0.0
27	-0.040	-0.042	-0.034	-0.028	0.0	0.0	-0.028	-0.028	-0.028	0.0
28	0.033	0.040	-0.035	-0.030	0.0	0.0	-0.030	-0.030	-0.030	0.0
29	-0.025	-0.013	-0.124	0.024	0.0	0.0	0.024	0.024	0.024	0.0
30	-0.079	-0.084	-0.068	-0.056	0.0	0.0	-0.056	-0.056	-0.056	0.0
31	-0.021	-0.022	-0.018	-0.015	0.0	0.0	-0.015	-0.015	-0.015	0.0
32	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
33	-0.047	-0.071	-0.057	-0.047	0.0	0.0	-0.047	-0.047	-0.047	0.0
34	-0.003	-0.028	-0.071	-0.058	0.0	0.0	-0.058	-0.058	-0.058	0.0
35	-0.053	-0.056	-0.046	-0.037	0.0	0.0	-0.037	-0.037	-0.037	0.0
36	-0.037	-0.039	0.101	-0.026	0.0	0.0	-0.026	-0.026	-0.026	0.0
37	0.019	0.054	-0.041	-0.034	0.0	0.0	-0.034	-0.034	-0.034	0.0
38	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
39	-0.019	-0.007	0.096	-0.019	0.0	0.0	-0.019	-0.019	-0.019	0.0
40	0.060	0.052	-0.003	-0.037	0.0	0.0	-0.037	-0.037	-0.037	0.0
41	1.000	0.172	-0.025	-0.021	0.0	0.0	-0.021	-0.021	-0.021	0.0
42		1.000	-0.027	-0.022	0.0	0.0	-0.022	-0.022	-0.022	0.0
43			1.000	-0.018	0.0	0.0	-0.018	-0.018	-0.018	0.0
44				1.000	0.0	0.0	1.000	1.000	1.000	0.0
45					0.0	0.0	0.0	0.0	0.0	0.0
46					0.0	0.0	0.0	0.0	0.0	0.0
47						0.0	0.0	0.0	0.0	0.0
48							1.000	1.000	1.000	0.0
49								1.000	1.000	0.0
50									1.000	0.0

VARIABLE NUMBER	51	52	53	54	55	56
1	-0.058	0.287	0.789	0.448	0.520	0.476
2	-0.026	0.064	-0.089	-0.046	-0.077	-0.074
3	1.000	0.065	0.221	0.021	0.335	0.234
4	-0.041	-0.137	-0.165	-0.092	-0.122	-0.175
5	0.204	0.684	0.925	0.460	0.610	0.569
6	0.203	0.338	0.519	0.434	0.510	0.822
7	-0.130	-0.437	-0.501	-0.294	-0.389	-0.365
8	-0.053	-0.196	-0.263	-0.132	-0.174	-0.156
9	-0.031	-0.199	-0.155	-0.125	-0.053	-0.113
10	-0.047	-0.157	-0.213	-0.106	-0.140	0.048
11	-0.044	-0.147	-0.199	-0.099	-0.131	-0.135
12	-0.015	0.003	0.221	-0.033	-0.044	-0.072
13	-0.077	-0.257	-0.347	-0.173	-0.229	-0.200
14	0.044	-0.312	0.199	0.074	0.131	0.122
15	0.147	-0.132	0.165	-0.034	0.438	0.306
16	-0.037	0.406	-0.101	0.020	-0.149	-0.147
17	0.003	0.296	0.475	0.999	0.193	0.548
18	-0.067	-0.224	-0.304	-0.151	-0.200	-0.256
19	0.000	0.707	0.113	-0.018	0.073	0.001
20	0.028	0.194	0.512	0.418	0.232	0.586
21	-0.040	-0.134	-0.181	-0.090	-0.119	-0.074
22	-0.023	-0.074	-0.127	-0.063	-0.084	-0.119
23	-0.023	-0.077	-0.104	-0.052	-0.069	0.097
24	-0.032	-0.108	-0.145	-0.072	-0.096	-0.142
25	-0.032	-0.107	-0.144	-0.072	-0.095	-0.062
26	-0.015	-0.049	-0.067	-0.033	-0.044	-0.076
27	-0.028	0.233	0.419	0.973	0.113	0.503
28	-0.070	-0.234	-0.316	-0.157	-0.203	-0.155
29	0.124	0.133	0.246	0.211	-0.012	-0.026
30	-0.024	0.312	0.835	0.472	0.550	0.515
31	-0.015	-0.049	-0.067	-0.033	-0.044	-0.076
32	0.0	0.0	0.0	0.0	0.0	0.0
33	-0.047	0.354	0.555	0.445	0.197	0.217
34	-0.023	0.287	0.789	0.448	0.520	0.476
35	-0.057	0.079	0.562	0.135	0.852	0.554
36	-0.026	0.014	0.051	0.013	-0.077	0.077
37	-0.054	-0.114	-0.154	-0.076	-0.101	-0.144
38	0.0	0.0	0.0	0.0	0.0	0.0
39	-0.019	0.073	-0.072	-0.034	-0.057	-0.050
40	-0.037	0.005	-0.048	-0.061	-0.112	-0.114
41	-0.021	-0.070	-0.095	-0.067	-0.063	-0.091
42	-0.022	-0.074	-0.103	-0.050	-0.066	-0.081
43	-0.019	0.047	-0.153	-0.029	-0.053	-0.041
44	1.000	0.065	0.221	0.021	0.335	0.234
45	0.0	0.0	0.0	0.0	0.0	0.0
46	0.0	0.0	0.0	0.0	0.0	0.0
47	1.000	0.065	0.221	0.021	0.335	0.234
48	1.000	0.065	0.221	0.021	0.335	0.234
49	1.000	0.065	0.221	0.021	0.335	0.234
50	0.0	0.0	0.0	0.0	0.0	0.0
51	1.000	0.065	0.221	0.021	0.335	0.234
52		1.000	0.371	0.298	0.135	0.257
53			1.000	0.479	0.657	0.567
54				1.000	0.155	0.551
55					1.000	0.636
56						1.000

SUB-PROBLEM 1
DEPENDENT VARIABLE 5
MAXIMUM NUMBER OF STEPS 7
F-LEVEL FOR INCLUSION 0.010000
F-LEVEL FOR DELETION 0.005000
TOLERANCE LEVEL 0.001000

STEP NUMBER 1
VARIABLE ENTERED 19

MULTIPLE R 0.0739
STD. ERROR OF EST. 1.2845

ANALYSIS OF VARIANCE

	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	1	0.608	0.608	0.368
RESIDUAL	57	110.539	1.939	

VARIABLES IN EQUATION				VARIABLES NOT IN EQUATION			
VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE	VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
(CONSTANT	0.21896			S	-0.07320	0.4341	0.3501 (2)
MEM 5	1.77146	0.31935	30.6817 (2)	LS	0.02138	0.9219	0.0297 (2)
16/17 19	-3.21194	5.95342	2.3942 (8)	L	0.10363	0.9505	0.7056 (2)
				H	-0.13242	0.9400	1.2735 (2)

VARIABLES IN EQUATION				VARIABLES NOT IN EQUATION			
VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE	VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
(CONSTANT	0.59835			S	0.38161	0.9874	11.2495 (2)
16/17 19	5.97757	6.55463	0.3682 (3)	LS	-0.07074	0.9451	0.3319 (2)
				L	0.20084	1.0000	3.0099 (2)
				H	-0.21190	0.9920	3.1613 (2)
				MEM	0.56334	0.8400	30.6816 (2)
				DIG	-0.39239	0.9122	12.9473 (2)
				LIN	-0.38421	0.9336	0.4713 (2)
				OTHER	-0.08364	0.9848	0.4649 (2)
				ECL	0.22585	0.9994	3.5477 (2)
				CMOS	-0.18120	0.9937	2.2407 (2)
				MDS	-0.13390	0.9990	1.2050 (2)
				HG	-0.16526	0.9728	1.8532 (2)
				HERMET	0.27450	0.6485	5.3783 (2)
				FP	0.39477	0.9881	12.1846 (2)
				REL	-0.33116	0.8610	8.1295 (2)
				'S	0.43395	0.9999	15.3122 (2)
				16/13	-0.42704	0.9784	14.7371 (2)
				20	0.46775	0.9935	18.4847 (2)
				21	-0.03396	0.9923	3.0763 (2)
				22	-0.17102	0.9942	1.9826 (2)
				23	0.17166	0.9974	2.5158 (2)
				24	-0.25111	0.9950	4.4418 (2)
				25	0.00131	0.9951	0.0001 (2)
				26	-0.18911	0.9990	2.4473 (2)
				27	0.37007	0.9926	11.0069 (2)
				28	-0.36094	0.9756	0.2460 (2)
				29	-0.06450	0.9852	0.2753 (1)
				30	0.45442	0.9342	17.1752 (2)
				31	-0.18911	0.9990	2.4478 (2)
				32	0.0	0.0	0.0 (2)
				33	0.17643	0.9962	2.1205 (2)
				34	0.53161	0.9874	11.2495 (2)
				35	0.40862	0.9913	13.2289 (2)
				36	0.19043	0.5641	1.7435 (2)
				37	-2.17503	0.9945	2.1104 (2)
				38	0.0	0.0	0.0 (2)
				39	-0.04390	0.9376	0.1274 (2)
				40	-0.11232	0.9980	0.8433 (2)
				41	-0.12019	0.9979	0.9674 (2)
				42	-0.04337	0.9976	0.1244 (2)
				43	-0.02720	0.9657	0.0489 (2)
				44	0.29884	1.0000	3.0099 (2)
				45	0.0	0.0	0.0 (2)
				46	0.0	0.0	0.0 (2)
				47	0.20885	1.0000	3.0100 (2)
				48	0.20784	1.0000	3.0099 (2)
				49	0.20384	1.0000	3.0099 (2)
				50	0.0	0.0	0.0 (2)
				51	0.20385	1.0000	3.0100 (2)
				52	0.40584	0.5003	13.0141 (2)
				53	0.51519	0.9373	23.8470 (2)
				54	0.42667	0.9997	15.5499 (2)
				55	0.50700	0.9946	22.8442 (2)
				56	0.82391	1.0000	139.4934 (1)

STEP NUMBER 2
VARIABLE ENTERED 5

MULTIPLE R 0.5966
STD. ERROR OF EST. 1.0693

ANALYSIS OF VARIANCE				
	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	2	35.687	17.843	15.607
RESIDUAL	63	75.460	1.193	

DIG	7	-0.13527	0.5908	0.4761 (2)
LIN	8	0.07595	0.9178	0.1372 (2)
OTHER	9	0.00733	0.9599	0.0035 (2)
ECL	10	-0.2381	0.7459	14.2314 (2)
CMOS	11	-0.00900	0.9536	0.5190 (2)
MCS	12	-0.33303	0.9429	8.1111 (2)
HG	13	0.03442	0.8589	0.0771 (2)
HERMET	14	0.20173	0.8126	2.7574 (2)
FP	15	0.42312	0.9733	13.3987 (2)
REL	16	-0.32670	0.5331	8.3111 (2)
NB	17	0.21087	0.7469	3.0247 (2)
16/13	18	-0.32929	0.6919	7.9054 (2)
	20	0.23648	0.7095	3.2494 (2)
	21	0.07997	0.9617	0.4184 (2)
	22	-0.10410	0.9812	1.3157 (2)
	23	0.00256	0.9372	0.5475 (2)
	24	-0.00971	0.9752	2.4902 (2)
	25	0.09803	0.9756	0.9511 (2)
	26	-0.10525	0.9943	2.3099 (2)
	27	0.17592	0.5359	2.0758 (2)
	28	0.14466	0.8328	1.2893 (2)
	29	-0.04194	0.9327	4.0413 (1)
	30	0.01410	0.3459	0.0129 (2)
	31	-0.16525	0.9948	2.3099 (2)
	32	0.0	0.0	0.0 (2)
	33	-0.17244	0.7185	1.9920 (2)
	34	-0.07320	0.4361	0.3501 (2)
	35	0.15818	0.7143	1.6601 (2)
	36	0.10123	0.5534	0.6730 (2)
	37	-0.11262	0.9724	0.3350 (2)
	38	0.0	0.0	0.0 (2)
	39	0.04324	0.9190	0.1218 (2)
	40	-0.10014	0.9952	0.6594 (2)
	41	-0.03307	0.9894	0.4517 (2)
	42	0.01394	0.9992	0.0126 (2)
	43	0.04303	0.9538	0.1239 (2)
	44	0.10363	0.9505	0.7056 (2)
	45	0.0	0.0	0.0 (2)
	46	0.0	0.0	0.0 (2)
	47	0.10363	0.9505	0.7057 (2)
	48	0.10363	0.9505	0.7056 (2)
	49	0.10363	0.9505	0.7056 (2)
	50	0.0	0.0	0.0 (2)
	51	0.10363	0.9505	0.7057 (2)
	52	0.03225	0.3256	0.5103 (2)
	53	-0.13571	0.0660	1.2196 (2)
	54	0.20998	0.7392	2.9453 (2)
	55	0.23410	0.5933	3.7426 (2)
	56	0.73209	0.6148	75.0721 (1)

STEP NUMBER 3
VARIABLE ENTERED 10

MULTIPLE R 0.6656
STD. ERROR OF EST. 0.9759

ANALYSIS OF VARIANCE

	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	3	49.241	16.414	17.234
RESIDUAL	65	61.706	0.952	

VARIABLES IN EQUATION

VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE
CONSTANT	-0.01987		
MEM 5	2.00489	0.29840	45.1436 (2)
ECL 10	1.39240	0.35849	14.2314 (2)
16/17 19	-0.95905	0.43304	2.7182 (8)

VARIABLES NOT IN EQUATION

VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
S 1	-0.06497	0.4336	0.2713 (2)
LS 2	0.06889	0.9174	0.3052 (2)
L 3	0.11494	0.9505	0.8568 (2)
M 4	-0.06774	0.9273	0.2951 (2)
DIG 7	-0.23706	0.5430	3.3109 (2)
LIN 8	0.21999	0.8504	3.2580 (2)
OTHER 9	0.10956	0.9583	1.8746 (2)
CMOS 11	-0.00405	0.9155	0.0015 (2)
MCS 12	-0.36700	0.9429	9.9619 (2)
HG 13	0.23432	0.8579	0.1894 (2)
HERMET 14	0.20128	0.8126	3.2980 (2)
FP 15	0.43314	0.9767	15.3339 (2)
REL 16	-0.36706	0.8922	11.2789 (2)
NB 17	0.23611	0.7468	3.7785 (2)
16/13 18	-0.47372	0.6484	19.0273 (2)

20	0.26320	0.7095	4.7634 (2)
21	0.07080	0.3506	0.3610 (2)
22	-0.07392	0.3557	0.4012 (2)
23	0.12450	0.7592	1.0076 (2)
24	-0.16566	0.9548	1.8059 (2)
25	-0.27460	0.5402	5.2193 (2)
26	-0.17425	0.9905	2.0040 (2)
27	0.19557	0.8059	2.5452 (2)
28	0.15705	0.8527	1.6186 (2)
29	-0.30125	0.9279	6.3580 (1)
30	0.01749	0.3636	0.0196 (2)
31	-0.17424	0.9905	2.0039 (2)
32	0.0	0.0	0.0 (2)
33	-0.17077	0.7172	1.9224 (2)
34	-0.06497	0.4736	0.2713 (2)
35	0.17550	0.7145	2.0337 (2)
36	0.10740	0.5534	0.7468 (2)
37	-0.05350	0.9497	0.1837 (2)
38	0.0	0.0	0.0 (2)
39	0.07969	0.9148	0.4091 (2)
40	-0.04594	0.9760	0.1353 (2)
41	-0.04813	0.9808	0.1436 (2)
42	0.06293	0.9785	0.2472 (2)
43	0.07753	0.9499	0.3370 (2)
44	0.11494	0.9505	0.8568 (2)
45	0.0	0.0	0.0 (2)
46	0.0	0.0	0.0 (2)
47	0.11494	0.9505	0.8569 (2)
48	0.11494	0.9505	0.8568 (2)
49	0.11494	0.9505	0.8568 (2)
50	0.0	0.0	0.0 (2)
51	0.11494	0.9505	0.8569 (2)
52	0.09253	0.3085	0.5527 (2)
53	-0.14354	0.0660	1.3444 (2)
54	0.23321	0.7392	3.6310 (2)
55	0.25835	0.5938	4.9344 (2)
56	0.71982	0.5822	68.8172 (1)

STEP NUMBER 4
VARIABLE ENTERED 18

MULTIPLE R 0.7554
STD. ERROR OF EST. 0.8635

ANALYSIS OF VARIANCE

	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	4	63.423	15.857	21.267
RESIDUAL	54	47.719	0.746	

VARIABLES IN EQUATION				VARIABLES NOT IN EQUATION			
VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE	VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
(CONSTANT	0.29312			S	-0.02735	0.4304	0.0472 (2)
MEM 5	1.69924	0.27316	38.6969 (2)	LS	0.02285	0.9031	0.0276 (2)
ECL 10	1.66570	0.32523	25.2316 (2)	L	0.13013	0.9505	1.0852 (2)
14/13 13	-0.23799	0.05456	19.0273 (2)	M	-0.12398	0.9157	1.2409 (2)
15/17 19	-9.29049	4.80865	3.7328 (8)	DIG 7	-0.32827	0.5372	7.6091 (2)
				LIN 8	0.32598	0.3355	7.4701 (2)
				OTHER 9	0.23305	0.8526	3.7649 (2)
				CHOS 11	0.02175	0.9132	0.0298 (2)
				MOS 12	-0.01911	0.9429	23.4245 (2)
				NG 13	-0.00593	0.7996	0.5840 (2)
				HERMET 14	-0.01743	0.6174	0.0191 (2)
				FP 15	0.39914	0.9404	11.9388 (2)
				REL 16	-0.14254	0.5461	1.3066 (2)
				NS 17	0.25432	0.7468	4.7205 (2)
				20	0.29160	0.7095	6.0756 (2)
				21	-0.03333	0.9138	0.0927 (2)
				22	-0.11876	0.3631	0.9012 (2)
				23	0.03701	0.7308	0.2964 (2)
				24	-0.14013	0.9489	1.3747 (2)
				25	-0.04533	0.4042	0.1297 (2)
				26	-0.00357	0.9326	0.5565 (2)
				27	0.22074	0.8559	3.2271 (2)
				28	-0.00284	0.7249	0.0505 (2)
				29	-0.26450	0.9072	4.7390 (1)
				30	0.01706	0.3636	0.0183 (2)
				31	-0.00357	0.9326	0.5565 (2)
				32	0.0	0.0	0.0 (2)
				33	-0.13186	0.7075	1.1147 (2)

34	-0.02735	0.4304	0.0472 (2)
35	0.17061	0.7148	2.5072 (2)
36	0.12856	0.5533	1.0633 (2)
37	-0.12435	0.9370	0.9976 (2)
38	0.3	0.0	0.0 (2)
39	0.04486	0.9083	0.1270 (2)
40	-0.11029	0.9652	0.7758 (2)
41	-0.10055	0.9740	0.6434 (2)
42	0.01109	0.9669	0.0077 (2)
43	0.04236	0.9435	0.1214 (2)
44	0.13013	0.9505	1.0852 (2)
45	0.0	0.0	0.0 (2)
46	0.0	0.0	0.0 (2)
47	0.11013	0.9505	1.0853 (2)
48	0.11013	0.9505	1.0852 (2)
49	0.11013	0.9505	1.0852 (2)
50	0.0	0.0	0.0 (2)
51	0.13013	0.9505	1.0853 (2)
52	0.11274	0.9305	0.8110 (2)
53	-0.17293	0.0560	1.9421 (2)
54	0.26341	0.7392	4.6972 (2)
55	0.29389	0.5437	5.9557 (2)
56	0.74285	0.5675	77.5717 (2)

STEP NUMBER 5
VARIABLE ENTERED 12

MULTIPLE R 0.8039
STD. ERROR OF EST. 0.7902

ANALYSIS OF VARIANCE				
	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	5	71.0	14.362	23.001
RESIDUAL	63	39.33	0.624	

VARIABLES IN EQUATION				VARIABLES NOT IN EQUATION			
VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE	VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
(CONSTANT)	0.29523			S	-0.21182	0.3739	2.9126 (2)
MEM 5	1.90367	0.25648	55.4362 (2)	LS	0.03167	0.9028	0.0423 (2)
ECL 10	1.66451	0.29762	31.2792 (2)	L	0.11074	0.9457	0.7693 (2)
MOS 12	-3.00344	0.81973	13.4245 (2)	H	-0.15396	0.9157	1.5053 (2)
15/13 13	-0.23336	0.04003	22.7918 (2)	SIG	-0.35413	0.5371	9.4774 (2)
16/17 19	-11.35440	4.43636	6.5505 (8)	LIN	0.25755	0.8355	9.0631 (2)
				OTHER	0.23687	0.8500	3.6035 (2)
				CMOS	0.02316	0.9132	0.3333 (2)
				MS	-0.10715	0.7896	0.7201 (2)
				HERMET	-0.22680	0.6172	0.3446 (2)
				FP	0.30265	0.9231	10.5055 (2)
				REL	-0.10553	0.5441	2.2117 (2)
				MB	0.20992	0.7218	2.8580 (2)
					0.23939	0.6912	3.7691 (2)
					-0.04304	0.9138	0.1150 (2)
					-0.13137	0.9630	1.0838 (2)
					0.04058	0.7308	0.1023 (2)
					-0.16148	0.9439	1.6600 (2)
					-0.04938	0.4042	0.1516 (2)
					-0.10315	0.9526	0.6663 (2)
					0.17409	0.7871	1.9517 (2)
					-0.00464	0.7949	0.0013 (2)
					-0.35463	0.8917	8.2120 (2)
					-0.13495	0.3034	2.1958 (2)
					-0.10315	0.9526	0.6668 (2)
					0.0	0.0	0.0 (2)
					-0.24443	0.6770	4.0035 (2)
					-0.21182	0.3739	2.9126 (2)
					0.13193	0.6877	1.3766 (2)
					0.12348	0.5524	0.7600 (2)
					-0.13226	0.9370	1.0083 (2)
					0.0	0.0	0.0 (2)
					0.05988	0.9078	0.2232 (2)
					-0.13451	0.7644	1.1424 (2)
					-0.11121	0.9740	0.7764 (2)
					0.01170	0.9658	0.0085 (2)
					0.05501	0.5433	0.1882 (2)
					0.11074	0.9457	0.7698 (2)
					0.0	0.0	0.0 (2)
					0.0	0.0	0.0 (2)
					0.11075	0.9457	0.7699 (2)

48	0.11074	0.9457	0.7698 (2)
49	0.11074	0.9457	0.7698 (2)
50	0.0	0.0	0.0 (2)
51	0.11075	0.9457	0.7699 (2)
52	0.05859	0.3021	0.2136 (2)
53	-0.19592	0.0660	2.4749 (2)
54	0.21323	0.7133	2.8101 (2)
55	0.21263	0.5549	2.9359 (2)
56	0.71259	0.5166	63.9601 (1)

STEP NUMBER 6
VARIABLE ENTERED 15

MULTIPLE R 0.8351
STD. ERROR OF EST. 0.7366

ANALYSIS OF VARIANCE				
	OF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	6	77.509	12.918	23.811
RESIDUAL	62	33.637	0.543	

VARIABLES IN EQUATION				VARIABLES NOT IN EQUATION			
VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE	VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
(CONSTANT	0.02207			S	-0.21104	0.3731	2.8434 (2)
MEM 5	1.34461	0.23792	59.1106 (2)	LS	0.09004	0.8919	0.3933 (2)
ECL 10	1.52816	0.27842	32.5373 (2)	L	0.06941	0.9312	0.2953 (2)
MCS 12	-2.00517	0.77120	11.3430 (2)	H	-0.17102	0.9156	1.8378 (2)
EP 15	0.60918	0.19795	19.5056 (2)	DIG 7	-0.15066	0.5334	9.1213 (2)
15/13 13	-0.00841	0.04745	19.2923 (2)	LIN 8	0.15222	0.8248	8.0915 (2)
16/17 19	-2.15497	4.19064	4.7725 (3)	OTHER 9	0.21521	0.8411	2.9525 (2)
				CHOS 11	0.22537	0.9132	0.0343 (2)
				NS 13	-0.04782	0.7676	0.1398 (2)
				HERMET 14	-0.11446	0.5921	0.8098 (2)
				REL 16	-0.04755	0.4552	0.1383 (2)
				NB 17	0.22447	0.7091	5.4533 (2)
				20	0.21161	0.6710	6.5599 (2)
				21	1.00443	0.3998	0.0012 (2)
				22	-0.03105	0.9412	0.4014 (2)
				23	0.00326	0.7259	0.0009 (2)
				24	-0.11745	0.9283	0.3533 (2)
				25	-0.00791	0.3997	0.0060 (2)
				26	-0.03641	0.7490	0.4587 (2)
				27	0.25376	0.7603	4.1984 (2)
				28	0.31390	0.7779	3.0732 (2)
				29	-0.29432	0.8416	5.7853 (1)
				30	-0.19328	0.3034	2.3672 (2)
				31	-0.33641	0.9490	0.4589 (2)
				32	0.0	0.0	0.0 (2)
				33	-0.19295	0.6533	2.3538 (2)
				34	-0.21104	0.3731	2.8434 (2)
				35	-0.01903	0.5337	0.0221 (2)
				36	0.22537	0.5376	2.5371 (2)
				37	-0.14409	0.7368	1.2932 (2)
				38	0.0	0.0	0.0 (2)
				39	0.15075	0.8977	0.7300 (2)
				40	-0.11822	0.9601	0.8647 (2)
				41	-0.21235	0.9302	2.8815 (2)
				42	0.05333	0.9572	0.1773 (2)
				43	0.10493	0.9321	0.6797 (2)
				44	0.06941	0.9312	0.2953 (2)
				45	0.0	0.0	0.0 (2)
				46	0.0	0.0	0.0 (2)
				47	0.06942	0.9312	0.2954 (2)
				48	0.06941	0.9312	0.2953 (2)
				49	0.06941	0.9312	0.2953 (2)
				50	0.0	0.0	0.0 (2)
				51	0.06942	0.9312	0.2954 (2)
				52	0.16728	0.2846	1.7561 (2)
				53	-0.24937	0.3654	4.0444 (2)
				54	0.29255	0.7012	5.2924 (2)
				55	0.22816	0.4165	0.0484 (2)
				56	0.68527	0.3794	54.0130 (1)

STEP NUMBER 7
 VARIABLE ENTERED 7

MULTIPLE R 0.8583
 STD. ERROR OF EST. 0.5925

ANALYSIS OF VARIANCE

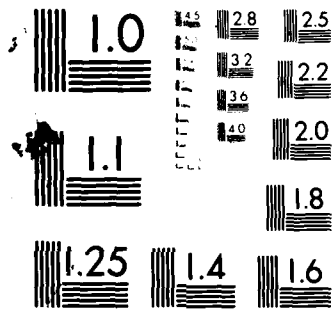
	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	7	31.395	4.485	24.386
RESIDUAL	61	29.262	0.480	

VARIABLES IN EQUATION				VARIABLES NOT IN EQUATION			
VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE	VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
(CONSTANT	0.52165			S	-0.20873	0.3704	2.7332 (2)
MEM 5	1.58177	0.27049	25.6833 (2)	LS	0.21634	0.2629	3.0150 (2)
DIG 7	-0.29142	0.22893	9.1213 (2)	L	0.27374	0.2312	0.3576 (2)
ECL 10	1.84092	0.27437	44.3779 (2)	M	-0.20578	0.2276	0.2623 (2)
MOS 12	-2.7171	0.72527	13.8805 (2)	LN	0.21252	0.2330	0.2009 (2)
FP 15	0.53445	0.17735	10.1303 (2)	OTHER	0.27526	1.6927	3.3413 (2)
16/13 18	-0.22443	0.24433	24.9495 (2)	CNCS	0.25125	0.2056	0.2250 (2)
16/17 19	-2.93248	3.74668	0.2061 (8)	NG	0.23537	0.7029	0.2752 (2)
				HERMET	-0.12760	0.5929	0.2930 (2)
				PEL	-0.04221	0.4650	0.1071 (2)
				NS	0.23456	0.7071	5.6161 (2)
				20	0.32337	0.6705	7.0067 (2)
				21	0.07100	0.8742	0.3040 (2)
				22	-0.05033	0.7327	0.1524 (2)
				23	-0.02071	0.7233	0.0000 (2)
				24	-0.10415	0.7268	0.6579 (2)
				25	0.00552	0.3796	0.0054 (2)
				26	-0.14295	0.7331	0.1109 (2)
				27	0.06205	0.7638	4.4532 (2)
				28	0.02577	0.7602	0.5554 (2)
				29	-0.31127	0.8415	6.4378 (2)
				30	-0.021487	0.5032	2.7043 (2)
				31	-0.04294	0.7331	0.1108 (2)
				32	0.0	0.0	0.0 (2)
				33	-0.18443	0.6911	2.1127 (2)
				34	-0.20873	0.3704	2.7332 (2)
				35	-0.00995	0.5333	0.0059 (2)
				36	0.22520	0.5374	3.2236 (2)
				37	-0.05949	0.3780	0.2131 (2)
				38	0.0	0.0	0.0 (2)
				39	0.02793	0.8497	0.6463 (2)
				40	-0.04179	0.9126	0.1050 (2)
				41	-0.15331	0.9024	1.6440 (2)
				42	0.11732	0.9335	0.8374 (2)
				43	0.02157	0.8793	0.2279 (2)
				44	0.07676	1.9312	0.3556 (2)
				45	0.0	0.0	0.0 (2)
				46	0.0	0.0	0.0 (2)
				47	0.07676	1.9312	0.3556 (2)
				48	0.07676	1.9312	0.3556 (2)
				49	0.07676	1.9312	0.3556 (2)
				50	0.0	0.0	0.0 (2)
				51	0.07676	0.9312	0.3556 (2)
				52	0.12568	0.2946	2.1479 (2)
				53	-0.23322	0.0653	5.2325 (2)
				54	0.29301	0.7008	5.6683 (2)
				55	0.04337	0.4160	0.1131 (2)
				56	0.70137	0.4751	58.0930 (2)

SPECIFIED STEP REACHED

SUMMARY TABLE

STEP NUMBER	VARIABLE ENTERED	VARIABLE REMOVED	MULTIPLE R	RSQ	INCREASE IN RSQ	F VALUE TO ENTER OR REMOVE
1	16/17	19	0.0739	0.0055	0.0055	0.3662
2	MEM	5	0.5666	0.3211	0.3156	30.6817
3	ECL	10	0.6656	0.4430	0.1219	14.2314
4	16/13	18	0.7554	0.5707	0.1276	19.0273
5	MOS	12	0.8038	0.6461	0.0754	13.4245
6	FP	15	0.8331	0.6974	0.0513	10.8056
7	DIG	7	0.8583	0.7367	0.0394	9.1213



MICROCOPY RESOLUTION TEST CHART
NATIONAL BUREAU OF STANDARDS-1963-A

LIST OF RESIDUALS

CASE NUMBER	Y X(6)	Y COMPUTED	RESIDUAL	X(19)	X(5)	X(10)	X(18)	X(12)
1	-0.1997	-0.2072	0.0075	0.0	0.0	0.0	0.1667	0.0
2	0.3255	0.3227	-0.0442	0.0	0.0	0.0	0.0625	0.0
3	-0.2222	-0.2147	0.1925	0.0	0.0	0.0	0.2000	0.0
4	-0.9733	-0.5345	-0.1338	0.0	0.0	0.0	1.6250	0.0
5	-0.2319	0.3656	-0.5985	0.0	0.0	0.0	0.1250	0.0
6	0.3923	0.3722	0.0198	0.0	0.0	0.0	0.1000	0.0
7	0.2001	-0.2118	0.5119	0.0	0.0	0.0	0.1875	0.0
8	0.3436	-0.2823	0.6256	0.0	0.0	0.0	0.5000	0.0
9	0.7524	0.3229	0.4095	0.0	0.0	0.0	0.3200	0.0
10	0.2276	0.4522	-0.4246	0.0	0.0	0.0	0.3075	0.0
11	0.2271	0.9178	-0.6907	0.0	0.0	0.0	0.7500	0.0
12	0.9933	0.4768	0.5165	0.0	0.0	0.0	0.2000	0.0
13	0.6663	0.9178	-0.2515	0.0	0.0	0.0	0.7500	0.0
14	-0.1995	0.3222	-0.5207	0.0	0.0	0.0	0.8333	0.0
15	0.4606	0.3156	0.1470	0.0	0.0	0.0	0.3611	0.0
16	-0.3638	0.3567	-0.7205	0.0	0.0	0.0	3.2500	0.0
17	-1.2665	-1.2919	-0.0746	0.0	0.0	0.0	5.0000	0.0
18	-1.2213	-2.0957	0.8927	0.0	0.0	0.0	11.6667	0.0
19	-1.3797	-0.4719	-0.9678	0.0	0.0	0.0	1.3462	0.0
20	-1.3744	-1.1516	-0.2228	0.0	0.0	0.0	4.3750	0.0
21	-0.5534	-0.5345	-0.0139	0.0	0.0	0.0	1.6250	0.0
22	1.7459	0.3199	1.6260	0.0	0.0	0.0	0.3133	0.0
23	-1.2972	-1.4789	-0.4183	0.0	0.0	0.0	5.8333	0.0
24	1.2310	1.2234	-0.1416	0.0	0.0	1.0000	2.9000	0.0
25	2.1431	2.0984	0.0717	0.0	0.0	1.0000	0.7500	0.0
26	-0.2597	0.3631	-0.7198	0.0	0.0	1.0000	5.8333	0.0
27	1.4540	2.2184	-0.7644	0.0254	1.0000	0.0	0.0	0.0
28	2.2513	1.8940	0.3573	0.0010	1.0000	0.0	0.0	0.0
29	0.5378	0.0677	0.5201	0.1857	1.0000	0.0	0.0	0.0
30	3.4012	2.4584	0.9428	0.0010	1.0000	0.0	0.0	0.0
31	2.0034	2.4056	0.3978	0.0063	1.0000	0.0	0.0	0.0
32	2.4204	1.5575	0.8529	0.0342	1.0000	0.0	0.0	0.0
33	-0.5761	1.5764	-2.1925	0.0513	1.0000	0.0	0.0	0.0
34	1.4409	1.2616	-0.2207	0.0043	1.0000	0.0	0.0	0.0
35	2.4237	1.8728	1.0869	0.0005	1.0000	0.0	0.0	0.0
36	1.4351	2.2184	-0.7833	0.0254	1.0000	0.0	0.0	0.0
37	3.4275	2.4168	1.0107	0.0052	1.0000	0.0	0.0	0.0
38	1.8795	1.7336	0.1439	0.0171	1.0000	0.0	0.0	0.0
39	1.1474	2.3523	-1.2654	0.0117	1.0000	0.0	0.0	0.0
40	1.6409	1.2516	-0.2207	0.0043	1.0000	0.0	0.0	0.0
41	0.1323	0.1256	-0.0033	0.0342	0.0	0.0	0.0	0.0
42	2.5533	2.4524	0.1009	0.0016	1.0000	0.0	0.0	0.0
43	-1.2642	-0.4690	-0.5952	0.0	0.0	0.0	1.3333	0.0
44	0.5247	0.9178	-0.3931	0.0	0.0	0.0	0.7500	0.0
45	2.2246	2.2253	-0.0007	0.0	0.0	1.0000	0.0508	0.0
46	0.4733	0.6450	-0.1503	0.0	0.0	0.0	1.0333	0.0
47	0.2425	0.4044	-0.0609	0.0	0.0	0.0	0.5000	0.0
48	0.4028	0.0955	0.3100	0.0	0.0	0.0	1.3333	0.0
49	-0.7215	-0.7025	-0.0000	0.0	1.0000	0.0	0.0	1.0000
50	2.2354	0.4655	1.7699	0.0	0.0	0.0	0.2500	0.0
51	-0.2030	-0.2072	0.2042	0.0	0.0	0.0	0.1667	0.0
52	0.5206	-0.1835	0.6893	0.0	0.0	0.0	0.0833	0.0
53	-0.3989	-0.5345	-0.3644	0.0	0.0	0.0	1.6250	0.0
54	-0.7730	-0.3942	-0.3758	0.0	0.0	0.0	1.0000	0.0
55	0.6671	1.5964	-0.7293	0.0313	1.0000	0.0	0.0	0.0

CASE NUMBER	Y X(6)	Y COMPUTED	RESIDUAL	X(19)	X(5)	X(10)	X(18)	X(12)
56	3.0564	2.3528	0.7036	0.0117	1.0000	0.0	0.0	0.0
57	-0.3467	0.0580	-0.4047	0.0	0.0	0.0	1.5000	0.0
58	-0.8939	0.2264	-1.1253	0.0	0.0	0.0	0.7500	0.0
59	0.5035	-0.1912	0.6920	0.0	0.0	0.0	0.0954	0.0
60	1.7347	1.5039	0.2008	0.0	0.0	1.0000	0.7500	0.0
61	2.0541	2.0644	-0.0143	0.0	0.0	1.0000	0.7500	0.0
62	0.0523	-0.2915	0.3439	0.0	0.0	1.0000	8.7500	0.0
63	1.6370	1.3390	0.3000	0.0	0.0	1.0000	0.8000	0.0
64	1.4469	1.4927	-0.0458	0.0	0.0	1.0000	0.8000	0.0
65	0.3646	0.2264	0.1382	0.0	0.0	0.0	0.7500	0.0
66	1.2700	0.7214	0.6668	0.0	0.0	0.0	1.6250	0.0
67	-0.7133	0.2195	-0.9328	0.0	0.0	0.0	1.3462	0.0
68	-0.4943	-0.3369	-0.1574	0.0	0.0	0.0	0.7447	0.0
69	-0.2984	-0.2317	-0.0667	0.0	0.0	0.0	0.2750	0.0

REGRESSION ANALYSIS RESULTS FOR CARD ASSEMBLY
(PCER2)

PRECEDING PAGE BLANK-NOT FILMED

LABELS	1CASSY	2NDEV	3NMC	4QA	5QB	6GBI	7QB2																		
0																									
LABELS	12TTLOTL	13ECL	14MOS	15IIL	18DIGLSI	19BIPMEM	20PINS																		
0																									
LABELS	21NOG	22NLG	23BITS	24NROM	25NRAM	26MC/DEV	27MC**2																		
0																									
LABELS	38RA																								
0																									
(8X,F6.2,2X,18F3.0,2F6.0,F6.2,F6.0,2F3.0)																									
47562	77	50	0	9	41	0	0	0	0	0	1	0	0	49	50	0	0	0	1069	1000	0	0	0	0	
41597	75	40	0	13	27	0	0	0	0	0	3	0	0	37	40	0	0	0	803	871	0	0	0	0	0
38609	41	24	0	4	20	0	0	0	0	0	1	0	0	23	24	0	0	0	516	404	0	0	0	0	0
44627	88	49	0	15	34	0	0	0	0	0	5	0	0	44	46	0	0	3	992	1080	0	5120	2	1	0
62954	92	47	0	3	44	0	0	0	0	0	18	0	0	29	31	0	0	16	1054	781	0	32768	16	0	0
50418	106	37	0	24	13	0	0	0	0	0	8	14	0	15	23	14	0	0	439	423	12250	0	0	0	0
49145	86	48	0	9	36	3	0	0	0	0	7	3	0	38	40	0	0	8	1023	939	0	13312	5	3	0
49356	138	12	0	5	1	6	0	0	0	0	0	7	0	5	5	7	0	0	70	16	4550	0	0	0	0
39282	82	42	0	11	31	0	0	0	0	0	2	0	0	40	42	0	0	0	867	1259	0	0	0	0	0
39059	42	28	0	20	8	0	0	0	0	0	1	0	0	27	28	0	0	0	464	284	0	0	0	0	0
46101	39	22	0	9	13	0	0	0	0	0	4	0	0	18	18	0	0	4	425	194	0	8192	4	0	0
168118	290	17	0	6	7	4	0	0	0	0	3	13	1	0	2	15	0	0	28	8	5600	0	0	0	0
107286	149	33	0	8	25	0	0	0	0	0	15	4	0	14	31	2	0	0	474	754	150	0	0	0	0
162736	226	15	2	2	5	8	0	0	0	0	3	7	2	3	6	7	0	0	134	56	1425	0	0	0	0
110347	82	42	0	8	34	0	0	0	0	0	25	0	0	17	18	0	0	24	894	195	0	24576	0	24	0
36962	67	43	0	8	35	0	0	0	0	0	1	0	0	42	43	0	0	0	917	970	0	0	0	0	0
102244	83	47	0	12	35	0	0	0	0	0	31	0	0	16	27	0	0	20	973	410	0	24576	4	16	0
39931	84	49	0	13	36	0	0	0	0	0	3	0	0	46	49	0	0	0	1010	1227	0	0	0	0	0
56006	52	31	0	10	21	0	0	0	0	0	7	0	0	24	24	0	0	7	623	278	0	14336	7	0	0
48024	134	43	0	18	23	2	0	0	0	0	32	3	0	8	41	1	1	0	760	777	525	0	0	0	0
37970	62	37	0	14	23	0	0	0	0	0	2	0	0	35	36	0	0	1	725	778	0	2048	1	0	0
50938	76	45	0	5	40	0	0	0	0	0	1	0	0	44	45	0	0	0	990	939	0	0	0	0	0

VARIABLE	MEAN	STANDARD DEVIATION
CASSY 1	649.66821	754.83984
NDEV 2	98.68181	114.80081
NMC 3	36.40909	30.23471
QA 4	0.09091	0.42640
QB 5	10.27273	11.62677
QJ1 6	23.09090	20.01135
QJ2 7	1.04545	2.42149
8	0.0	0.0
9	0.0	0.0
10	0.0	0.0
11	0.0	0.0
TTLOTL 12	7.86364	12.45172
ECL 13	2.31818	4.75299
NDS 14	0.13636	0.67633
IIL 15	26.09090	30.04080
16	30.40909	33.48065
17	2.09091	4.83039
DIGLSX 18	0.04545	0.21320
BIFHEM 19	3.77273	7.89419
PIHS 20	693.18184	764.82671
HGG 21	620.13623	750.06685
NLG 22	11.13636	30.48900
BITS 23	5670.94297	11204.6016
NRCM 24	1.77273	4.03434
NRAM 25	2.00000	4.18849
MC/DEV 26	0.46949	0.50645
XMC**2 27	0.25649	0.29124
28	0.04545	0.21320
29	10.27273	11.62677
30	78.27272	84.03409
31	6.79545	15.73972
32	10.31818	11.63654
33	85.59090	93.32274
34	92.36363	97.10217
35	10.36364	11.65020
36	10.36364	11.65020
37	11.40909	12.45537
RA 38	10.80125	14.08543
39	6.35031	6.36713

CORRELATION MATRIX

VARIABLE NUMBER	1	2	3	4	5	6	7	8	9	10
1	1.000	0.952	0.756	0.468	0.665	0.702	0.625	0.0	0.0	0.0
2		1.000	0.749	0.420	0.694	0.673	0.707	0.0	0.0	0.0
3			1.000	0.084	0.884	0.977	0.241	0.0	0.0	0.0
4				1.000	0.037	0.038	0.704	0.0	0.0	0.0
5					1.000	0.773	0.215	0.0	0.0	0.0
6						1.000	0.153	0.0	0.0	0.0
7							1.000	0.0	0.0	0.0
8								1.000	0.0	0.0
9									1.000	0.0
10										1.000

VARIABLE NUMBER	11	12	13	14	15	16	17	18	19	20
1	0.0	0.646	0.646	0.623	0.583	0.644	0.614	0.136	0.522	0.678
2	0.0	0.567	0.783	0.616	0.589	0.644	0.715	0.249	0.333	0.654
3	0.0	0.679	0.333	0.117	0.937	0.975	0.261	0.240	0.538	0.987
4	0.0	0.051	0.314	0.894	0.021	0.038	0.306	0.0	0.0	0.037
5	0.0	0.614	0.476	0.082	0.794	0.864	0.408	0.330	0.355	0.825
6	0.0	0.657	0.202	0.080	0.939	0.958	0.154	0.175	0.582	0.991
7	0.0	0.182	0.652	0.787	0.115	0.161	0.615	0.176	0.057	0.152
8	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
9	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
10	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
11	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
12		1.000	0.268	0.069	0.407	0.566	0.180	0.548	0.761	0.657
13			1.000	0.542	0.146	0.224	0.988	0.135	0.029	0.190
14				1.000	0.019	0.040	0.567	0.0	0.0	0.037
15					1.000	0.949	0.894	0.057	0.345	0.953
16						1.000	0.140	0.261	0.379	0.974
17							1.000	0.044	0.0	0.118
18								1.000	0.0	0.212
19									1.000	0.578
20										1.000

VARIABLE NUMBER	21	22	23	24	25	26	27	28	29	30
1	0.578	0.406	0.507	0.349	0.436	0.668	0.406	0.460	0.465	0.782
2	0.626	0.515	0.348	0.290	0.233	0.624	0.553	0.420	0.694	0.673
3	0.937	0.254	0.564	0.472	0.375	0.956	0.917	0.084	0.884	0.977
4	0.014	0.100	0.0	0.0	0.0	0.829	0.803	1.000	0.837	0.838
5	0.794	0.467	0.360	0.279	0.269	0.863	0.818	0.037	1.000	0.773
6	0.938	0.120	0.615	0.522	0.398	0.935	0.966	0.038	0.773	1.000
7	0.127	0.383	0.067	0.069	0.027	0.134	0.086	0.704	0.215	0.153
8	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
9	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
10	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
11	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
12	0.498	0.165	0.724	0.468	0.662	0.563	0.486	0.051	0.614	0.657
13	0.191	0.904	0.034	0.035	0.014	0.193	0.108	0.314	0.474	0.202
14	0.016	0.264	0.0	0.0	0.0	0.034	0.004	0.894	0.082	0.058
15	0.755	0.128	0.413	0.400	0.201	0.952	0.949	0.021	0.794	0.939
16	0.978	0.156	0.413	0.390	0.226	0.949	0.924	0.038	0.864	0.958
17	0.112	0.911	0.0	0.0	0.0	0.140	0.065	0.306	0.408	0.134
18	0.224	0.037	0.0	0.0	0.0	0.135	0.075	0.0	0.130	0.178
19	0.311	0.0	0.957	0.632	0.859	0.511	0.403	0.0	0.355	0.582
20	0.943	0.127	0.600	0.504	0.395	0.960	0.334	0.037	0.825	0.991
21	1.000	0.120	0.363	0.371	0.152	0.886	0.857	0.016	0.794	0.938
22		1.000	0.0	0.0	0.0	0.156	0.083	0.100	0.467	0.120
23			1.000	0.829	0.474	0.544	0.514	0.0	0.368	0.618
24				1.000	0.146	0.479	0.449	0.0	0.279	0.522
25					1.000	0.342	0.320	0.0	0.269	0.398
26						1.000	0.991	0.028	0.863	0.954
27							1.000	0.003	0.818	0.906
28								1.000	0.037	0.038
29									1.000	0.773
30										1.000

VARIABLE NUMBER	31	32	33	34	35	36	37	38	39
1	0.625	0.673	0.716	0.789	0.680	0.680	0.758	0.637	0.895
2	0.707	0.701	0.694	0.781	0.708	0.703	0.799	0.603	0.806
3	0.241	0.885	0.940	0.990	0.885	0.885	0.875	0.808	0.942
4	0.704	0.055	0.041	0.154	0.073	0.073	0.205	0.088	0.248
5	0.215	1.000	0.821	0.823	0.999	0.999	0.976	0.523	0.863
6	0.153	0.773	0.947	0.982	0.773	0.773	0.753	0.871	0.886
7	1.000	0.227	0.164	0.321	0.240	0.240	0.419	0.183	0.463
8	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
9	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
10	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
11	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
12	0.182	0.615	0.668	0.671	0.615	0.615	0.610	0.562	0.651
13	0.682	0.479	0.242	0.338	0.484	0.484	0.580	0.181	0.516
14	0.787	0.098	0.064	0.189	0.115	0.115	0.260	0.115	0.133
15	0.115	0.794	0.944	0.924	0.794	0.794	0.765	0.765	0.842
16	0.161	0.844	0.970	0.958	0.844	0.844	0.839	0.743	0.837
17	0.618	0.413	0.172	0.245	0.418	0.418	0.511	0.141	0.459
18	0.174	0.330	0.199	0.219	0.329	0.329	0.342	0.076	0.207
19	0.057	0.355	0.568	0.555	0.154	0.154	0.343	0.588	0.308
20	0.152	0.325	0.994	0.981	0.825	0.825	0.801	0.831	0.892
21	0.127	0.704	0.944	0.927	0.793	0.793	0.767	0.749	0.821
22	0.383	0.468	0.167	0.222	0.449	0.449	0.515	0.099	0.377
23	0.067	0.360	0.599	0.586	0.359	0.359	0.349	0.692	0.523
24	0.049	0.278	0.585	0.496	0.278	0.278	0.273	0.719	0.438
25	0.027	0.269	0.392	0.381	0.269	0.269	0.257	0.275	0.350
26	0.134	0.263	0.949	0.933	0.662	0.662	0.833	0.773	0.907
27	0.063	0.817	0.916	0.899	0.616	0.616	0.779	0.748	0.857
28	0.704	0.055	0.041	0.154	0.073	0.073	0.205	0.088	0.248
29	0.215	1.000	0.821	0.823	0.999	0.999	0.976	0.523	0.863
30	0.153	0.773	0.947	0.982	0.773	0.773	0.753	0.871	0.886
31	1.000	0.227	0.164	0.321	0.240	0.240	0.419	0.183	0.463
32		1.000	0.821	0.823	1.000	1.000	0.979	0.524	0.872
33			1.000	0.987	0.821	0.821	0.800	0.849	0.906
34				1.000	0.827	0.827	0.836	0.845	0.948
35					1.000	1.000	0.982	0.525	0.875
36						1.000	0.952	0.525	0.875
37							1.000	0.527	0.908
38								1.000	0.765
39									1.000

SUB-PROBLEM 1
DEPENDENT VARIABLE 1
MAXIMUM NUMBER OF STEPS 2
F-LEVEL FOR INCLUSION 0.010000
F-LEVEL FOR DELETION 0.005000
TOLERANCE LEVEL 0.001000

STEP NUMBER 1
 VARIABLE ENTERED 2

MULTIPLE R 0.9525
 STD. ERROR OF EST. 235.3682

ANALYSIS OF VARIANCE

	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	1	11371968.0	11371968.0	205.275
RESIDUAL	21	1163362.00	55398.187	

VARIABLES IN EQUATION

VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE
(CONSTANT	0.0		
NDEV 2	6.26267	0.43711	205.2752 (9)

VARIABLES NOT IN EQUATION

VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
MPC 3	0.21218	0.4392	0.9429 (9)
QA 4	0.21655	0.8238	0.9840 (2)
QB 5	0.01831	0.5187	0.0067 (2)
QB1 6	0.27056	0.5468	1.5797 (2)
QB2 7	-0.22238	0.5006	1.0405 (2)
8	0.0	0.0	0.0 (2)
9	0.0	0.0	0.0 (2)
10	0.0	0.0	0.0 (2)
11	0.0	0.0	0.0 (2)
TYLDTL 12	0.42260	0.4784	4.3834 (2)
ECL 13	-0.36506	0.4306	3.0783 (2)
HOS 14	0.15215	0.6202	0.4740 (2)
YIL 15	0.08738	0.6530	0.1539 (2)
16	0.04520	0.5569	0.0409 (2)
17	-0.31580	0.4887	2.2154 (2)
DIGLSZ 18	-0.34361	0.9381	2.6775 (2)
BIPHEM 19	0.71383	0.8893	20.7439 (2)
PINS 20	0.24083	0.5722	1.2314 (2)
NDG 21	-0.07592	0.6086	0.1159 (2)
NLG 22	-0.32253	0.7348	2.3221 (2)
BYS 23	0.61267	0.8787	12.0187 (2)
NROM 24	0.24872	0.9189	1.3189 (9)
NRAM 25	0.72133	0.9457	21.6947 (9)
MC/DEV 26	0.30034	0.6079	1.9829 (2)
MCM*2 27	0.30906	0.6937	2.1121 (2)
28	0.21654	0.8238	0.9840 (2)
29	0.01831	0.5187	0.0067 (2)
30	0.27056	0.5468	1.5797 (2)
31	-0.22238	0.5006	1.0405 (2)
32	0.02353	0.5007	0.0111 (2)
33	0.25300	0.5189	1.3677 (2)
34	0.23919	0.3908	1.2137 (2)
35	0.02882	0.4991	0.0166 (2)
36	0.02882	0.4991	0.0166 (2)
37	-0.01922	0.3610	0.0074 (2)
RA 38	0.25902	0.6361	1.4384 (2)
39	0.36234	0.2157	3.8226 (2)

STEP NUMBER 2
 VARIABLE ENTERED 25

MULTIPLE R 0.9775
 STD. ERROR OF EST. 167.0387

ANALYSIS OF VARIANCE

	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	2	11977191.0	5988595.00	214.630
RESIDUAL	20	55038.375	2790.918	

VARIABLES IN EQUATION

VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE
(CONSTANT	0.0		
NDEV 2	5.91634	0.31900	343.9717 (9)
NRAM 25	27.57201	5.91959	21.6947 (9)

VARIABLES NOT IN EQUATION

VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
MPC 3	-0.01897	0.3966	0.0068 (9)
QA 4	0.43075	0.8137	4.3286 (2)
QB 5	-0.13801	0.5044	0.3827 (2)
QB1 6	0.04377	0.4853	0.0365 (2)
QB2 7	-0.11840	0.4804	0.2544 (2)
8	0.0	0.0	0.0 (2)
9	0.0	0.0	0.0 (2)
10	0.0	0.0	0.0 (2)
11	0.0	0.0	0.0 (2)
TYLDTL 12	-0.10468	0.3817	0.2104 (2)
ECL 13	-0.27168	0.4029	1.5138 (2)

MOS	14	0.40253	0.5984	4.1294 (2)
IIL	15	0.04183	0.6487	0.0333 (2)
	16	-0.03663	0.5516	0.0255 (2)
	17	-0.20692	0.4593	0.0499 (2)
DIGLSX	18	-0.43281	0.9345	4.3795 (2)
BIPMEM	19	0.07267	0.2434	1.5261 (2)
PINS	20	0.00689	0.5101	0.0005 (2)
NOG	21	-0.11742	0.6086	0.2656 (2)
NLG	22	-0.31903	0.7195	2.1533 (2)
BITS	23	0.07268	0.5068	1.5262 (2)
KROM	24	0.07268	0.9094	1.5262 (2)
MC/DEV	26	0.16794	0.5672	0.5650 (2)
ZMC#2	27	0.20688	0.6553	0.0495 (2)
	28	0.43075	0.8137	4.3286 (2)
	29	-0.13501	0.5064	0.3527 (2)
	30	0.04377	0.4893	0.0365 (2)
	31	-0.11540	0.4806	0.2564 (2)
	32	-0.12307	0.4969	0.3069 (2)
	33	0.02407	0.4628	0.0110 (2)
	34	0.00468	0.3489	0.0004 (2)
	35	-0.11693	0.4677	0.2634 (2)
	36	-0.11693	0.4677	0.2634 (2)
	37	-0.15414	0.3557	0.4624 (2)
RA	38	0.19600	0.6169	0.7591 (2)
	39	0.20151	0.1935	0.8041 (2)

SPECIFIED STEP REACHED

SUMMARY TABLE

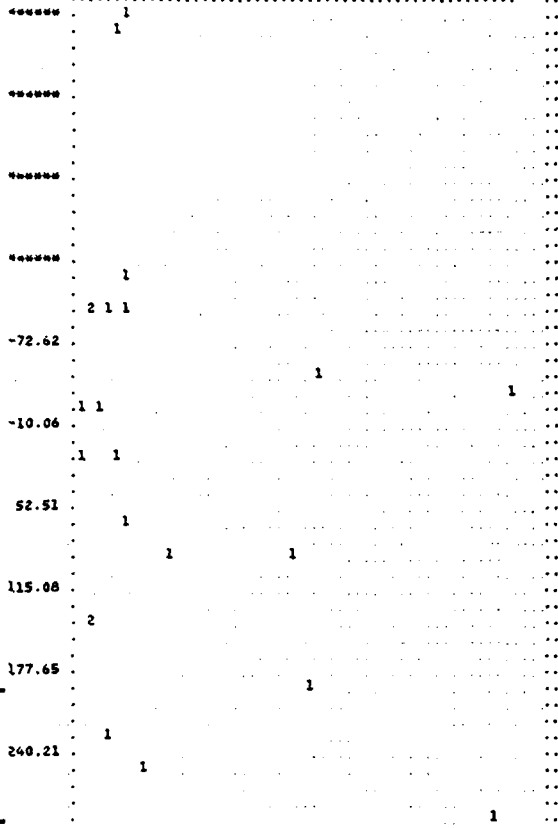
STEP NUMBER	VARIABLE ENTERED	VARIABLE REMOVED	MULTIPLE R	MULTIPLE RSQ	INCREASE IN RSQ	F VALUE TO ENTER OR REMOVE
1	NOEV	2	0.9525	0.9072	0.9072	205.2752
2	KRAM	25	0.9775	0.9555	0.0483	21.6947

LIST OF RESIDUALS

CASE NUMBER	Y (1)	Y COMPUTED	RESIDUAL	X(2)	X(25)
1	1103.4700	1146.8474	-43.3775	82.0000	24.0000
2	369.6201	396.3943	-26.7742	67.0000	0.0
3	1022.4399	932.2078	90.2322	83.0000	16.0000
4	399.3101	496.9722	-97.6621	84.0000	0.0
5	840.0601	307.6494	532.4106	52.0000	0.0
6	480.2400	792.7888	-312.5488	134.0000	0.0
7	379.7000	366.8127	12.8872	62.0000	0.0
8	509.3799	449.6414	59.7385	76.0000	0.0
9	475.6201	455.5579	20.0623	77.0000	0.0
10	415.9700	443.7251	-27.7551	75.0000	0.0
11	304.0901	242.5698	161.5203	41.0000	0.0
12	444.2700	548.2092	-101.9392	68.0000	1.0000
13	629.5400	544.3927	85.1473	92.0000	0.0
14	504.1799	627.1316	-122.9517	106.0000	0.0
15	491.4500	391.5205	100.0706	86.0000	3.0000
16	493.5601	816.4843	-322.8943	138.0000	0.0
17	392.8201	485.1394	-92.3193	82.0000	0.0
18	390.5901	248.4861	142.1040	42.0000	0.0
19	461.0100	230.7371	230.2729	39.0000	0.0
20	1681.1799	1715.7373	-34.5574	290.0000	0.0
21	1072.8601	881.5339	191.3262	149.0000	0.0
22	1627.3401	1337.0918	290.2483	226.0000	0.0

PLOT OF RESIDUALS (Y-AXIS)
VS. VARIABLE 1 (X-AXIS)

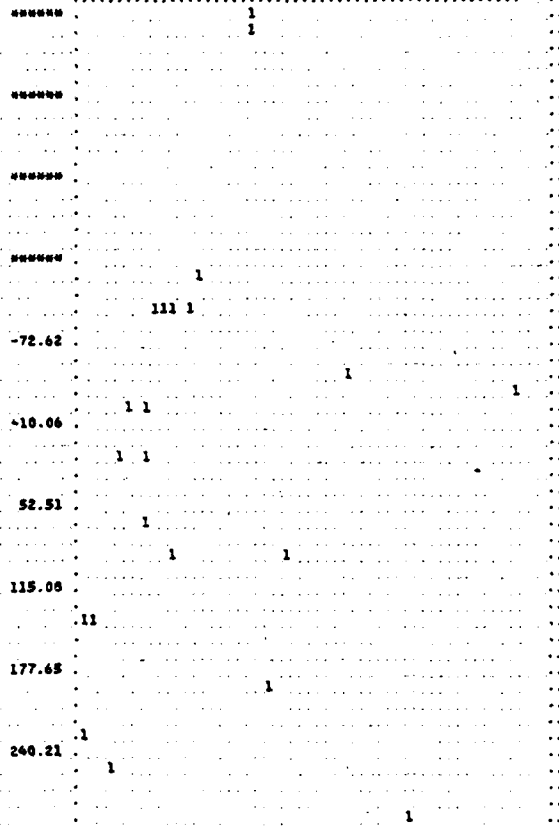
369.620 637.285 904.950 1172.616 1440.281 1707.946...
503.453 771.118 1038.783 1306.448 1574.114



369.620 637.285 904.950 1172.616 1440.281 1707.946...
503.453 771.118 1038.783 1306.448 1574.114

PLOT OF RESIDUALS (Y-AXIS)
VS. COMPUTED Y (X-AXIS)

230.737 533.798 836.859 1139.921 1442.982 1746.043...
382.268 685.329 988.390 1291.451 1594.512



230.737 533.798 836.859 1139.921 1442.982 1746.043...
382.268 685.329 988.390 1291.451 1594.512

REGRESSION ANALYSIS RESULTS FOR CARD TEST HOURS (H)

LABELS	1H	2P#NDG	31-W	4NLG	5RA#NMC	6#MC#2
(F4.2,1X,F7.3,1X,F2.2,1X,F5.2,1X,F3.0,4X,F4.4)						
64	19370 05		31	2275		
237	18200 12	13250	43	1094		
97	26044 03		37	2961		
79	56274 01		46	3072		
198	133600 07	1000	32	1916		
64	15990 04		42	2623		
234	2208 71	4550	12	0076		
252	2320 80	5600	17	0034		
119	80127 07	075	45	2675		
127	12348 41	4075	20	0185		
154	28552 51		31	1299		
124	135675 06		28	1394		
274	49179 38		48	2348		
103	44581 15		49	2021		
356	97125 56	350	42	1600		
718	31920 74		42	1357		
761	480 98	1000	20	0225		
920	40386 73	19250	37	1218		
109	50505 78		49	1949		
130	200592 01		44	2744		
109	39592 04		50	2603		
108	145848 01	9250	53	2017		
101	139997 07	1275	44	0947		
602	260163 0		127	0955		
1218	1208880 26		144	4174		
79	103238 11		42	2623		
343	71022 04		49	3031		
100	45540 08	4900	24	1159		

VARIABLE	MEAN	STANDARD DEVIATION
H	1	2.77857
P#NDG	2	109.27690
1-W	3	0.27929
NLG	4	23.06250
RA#NMC	5	44.57143
#MC#2	6	0.16062

CORRELATION MATRIX

VARIABLE NUMBER	1	2	3	4	5	6
1	1.000					
2		1.000				
3			1.000			
4				1.000		
5					1.000	
6						1.000

SUB-PROG. 1
 DEPENDENT VARIABLE 1
 MAXIMUM NUMBER OF STEPS 12
 F-LEVEL FOR INCLUSION 0.010000
 F-LEVEL FOR DELETION 0.205000
 TOLERANCE LEVEL 0.201000

STEP NUMBER 1
 VARIABLE ENTERED 2
 MULTIPLE R 0.5981
 STD. ERROP OF EST. 2.4047

ANALYSIS OF VARIANCE

	OF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	1	83.741	83.741	14.401
RESIDUAL	26	150.353	5.783	

VARIABLES IN EQUATION				VARIABLES NOT IN EQUATION			
VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE	VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
(CONSTANT	1.92192)						
PNDC 2	0.03784	0.00006	14.4810 (2)	1-M 3	0.67197	0.6777	20.7956 (2)
				NLG 4	0.40332	0.4793	4.6567 (2)
				RAMMC 5	3.10612	0.3543	0.2047 (1)
				ZMC#2 6	-0.39675	0.7728	4.6705 (2)

STEP NUMBER 2
VARIABLE ENTERED 3

MULTIPLE R 0.8055
STD. ERROR OF EST. 1.8119

ANALYSIS OF VARIANCE				
	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	2	152.016	76.008	23.191
RESIDUAL	25	82.078	3.283	

VARIABLES IN EQUATION				VARIABLES NOT IN EQUATION			
VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE	VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
(CONSTANT	0.37316)						
PNDC 2	0.00591	0.00157	32.0028 (2)	NLG 4	0.36399	0.9369	3.6653 (2)
1-M 3	5.13765	1.12667	20.7957 (2)	RAMMC 5	0.42231	0.3250	5.2074 (1)
				ZMC#2 6	-0.02929	0.5226	0.2226 (2)

STEP NUMBER 3
VARIABLE ENTERED 4

MULTIPLE R 0.8342
STD. ERROR OF EST. 1.7825

ANALYSIS OF VARIANCE				
	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	3	162.640	54.213	18.301
RESIDUAL	24	71.204	2.967	

VARIABLES IN EQUATION				VARIABLES NOT IN EQUATION			
VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE	VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
(CONSTANT	0.12963)						
PNDC 2	3.00924	0.00150	37.8147 (2)	RAMMC 5	0.47473	0.3241	6.6917 (1)
1-M 3	4.70147	1.09501	18.4344 (2)	ZMC#2 6	0.08783	0.4825	0.1788 (2)
NLG 4	0.01416	0.00739	3.6653 (2)				

STEP NUMBER 4
VARIABLE ENTERED 6

MULTIPLE R 0.8355
STD. ERROR OF EST. 1.7527

ANALYSIS OF VARIANCE				
	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	4	163.439	40.860	13.301
RESIDUAL	23	70.655	3.072	

VARIABLES IN EQUATION				VARIABLES NOT IN EQUATION			
VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE	VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
(CONSTANT	-0.29829)						
PNDC 2	0.00059	0.00173	26.3558 (2)	RAMMC 5	0.47439	0.3233	6.3687 (1)
1-M 3	4.39003	1.31789	14.3367 (2)				
NLG 4	0.01514	0.00733	3.6953 (2)				
ZMC#2 6	1.93307	4.68953	0.1783 (2)				

F-LEVEL OR TOLERANCE INSUFFICIENT FOR FURTHER COMPUTATION

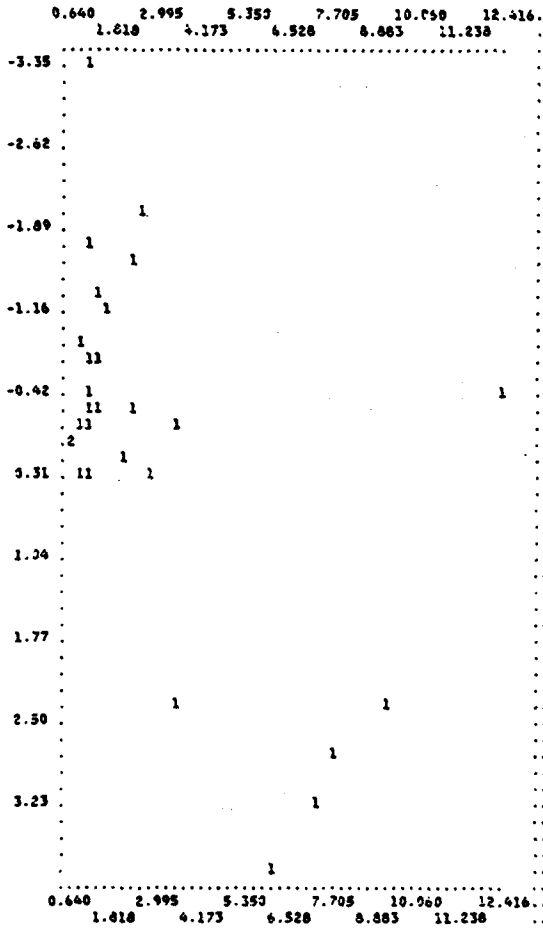
SUMMARY TABLE

STEP NUMBER	VARIABLE		MULTIPLE		INCREASE IN RSQ	F VALUE TO ENTER OR REMOVE
	ENTERED	REMOVED	R	RSQ		
1	P-HDG	2	0.5311	0.3577	0.3577	14.4610
2	L-W	3	0.3023	0.4496	0.2217	20.7957
3	NLS	4	0.2322	0.6558	0.0465	3.6653
4	INCW*2	6	0.9356	0.6582	0.0023	0.1788

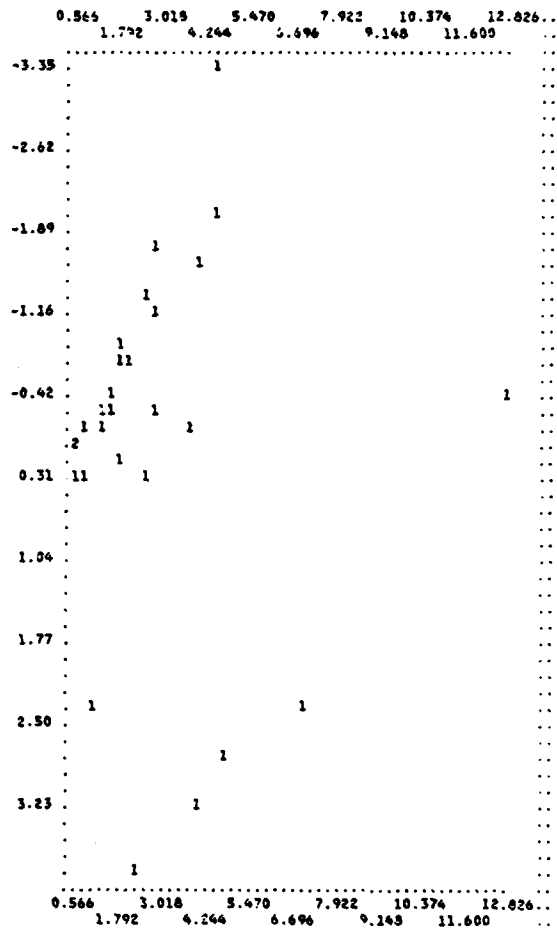
LIST OF RESIDUALS

CASE NUMBER	Y X(1)	Y COMPUTED	RESIDUAL	X(2)	X(3)	X(4)	X(6)
1	0.6400	0.5757	0.0633	19.3700	0.0500	0.0	0.2275
2	2.3700	2.6379	-0.3179	13.2000	0.1200	132.5000	0.1094
3	0.9700	0.6721	0.2979	25.0440	0.5300	0.0	0.2961
4	0.7900	0.8629	-0.3729	56.2740	0.0100	0.0	0.3072
5	1.4900	1.7726	0.2074	133.6000	0.0700	10.0000	0.1916
6	0.6400	0.5156	0.0744	15.9900	0.0400	0.0	0.2523
7	2.3400	3.9752	-1.6362	2.2050	0.7100	45.5000	0.0076
8	2.5200	4.5777	-2.0577	2.3200	0.6000	56.0000	0.0034
9	1.1400	1.3074	-0.1174	30.1270	0.0700	0.7500	0.2675
10	1.2700	2.5163	-1.2463	12.3460	0.4100	40.7500	0.0185
11	1.5400	2.7643	-1.2243	28.5520	0.5100	0.0	0.1299
12	1.2400	1.4952	-0.2552	135.6750	0.0600	0.0	0.1394
13	2.7400	2.5957	0.2341	49.1790	0.3800	0.0	0.2346
14	1.0200	1.2524	-0.2204	44.5810	0.1500	0.0	1.2021
15	3.5600	3.7553	-0.1760	97.1250	0.5400	3.5000	0.1600
16	7.1200	3.9356	3.2244	31.9200	0.7400	0.0	0.1357
17	7.5100	4.3027	2.8073	0.4830	0.9300	10.0000	0.0225
18	9.2000	6.3976	2.3324	40.3660	0.7300	192.5000	0.1218
19	1.2400	4.4352	-3.3482	50.5050	0.7800	0.0	0.1949
20	1.3000	2.0312	-0.7812	206.5920	0.0100	0.0	0.2744
21	1.0400	0.7715	0.3185	39.5420	0.0400	0.0	0.2603
22	1.0500	1.8525	-1.7706	145.2430	0.0100	92.5000	0.2017
23	1.3100	1.6740	-0.6640	139.9970	0.0700	12.7500	0.0947
24	6.0200	2.2062	3.8138	269.1631	0.0	0.0	0.0955
25	12.1800	12.9205	-0.4405	1208.8799	0.2600	0.0	0.4174
26	0.7900	1.0914	-0.4014	153.2330	0.1100	0.0	0.2523
27	3.4300	1.1359	2.2941	71.0220	0.3400	0.0	0.3031
28	1.0000	1.4799	-0.4799	45.5400	0.6800	49.0000	0.1159

PLOT OF RESIDUALS (Y-AXIS)
VS. VARIABLE 1 (X-AXIS)



PLOT OF RESIDUALS (Y-AXIS)
VS. COMPUTED Y (X-AXIS)



REGRESSION ANALYSIS RESULTS FOR CARD TEST YIELD (Yc)

PRECEDING PAGE BLANK-NOT FILLED

LABELS 1LOGYC 2MC/DEV 3Q82 4NLG 51-W 6YC
(F7.4,1X,F4.4,1X,F3.0,1X,F5.2,1X,F2.2)

-0.0362	4769	31	05			
-0.3372	3308	43	13250	12		
-0.3665	5542	46		01		
-0.2518	1415	74	9900	18		
-0.2924	4865	144		03		
-0.3010	4651	5		65		
-0.0605	5968			02		
-0.0915	3359	31		01		
-0.1487	5250			02		
-0.0809	4643	4		03		
-0.0362	5055			07		
-0.1249	5208	5		03		
-0.0555	4909			13		
-0.1249	5000			02		
-0.0809	3209	2	525	63		
-0.0809	5921			13		
-0.0655	5581	3		01		
-0.3768	6667			27		
-0.1135	4909			53		

VARIABLE	MEAN	STANDARD DEVIATION
LOGYC 1	-0.15925	0.19700
MC/DEV 2	3.47489	0.48912
Q82 3	20.42105	41.15312
NLG 4	12.46053	37.96454
1-W 5	0.15474	0.25807
YC 6	0.71634	0.73649

CORRELATION MATRIX

VARIABLE NUMBER	1	2	3	4	5	6
1	1.000	-0.777	-0.642	-0.493	-0.562	-0.650
2		1.000	0.404	0.169	0.542	0.949
3			1.000	0.439	0.148	0.385
4				1.000	0.199	0.227
5					1.000	0.551
6						1.000

SUB-PROBLEM 1
DEPENDENT VARIABLE 1
MAXIMUM NUMBER OF STEPS 12
F-LEVEL FOR INCLUSION 0.010000
F-LEVEL FOR DELETION 0.005000
TOLERANCE LEVEL 0.301000

STEP NUMBER 1
VARIABLE ENTERED 2

MULTIPLE R 0.7771
STD. ERROR OF EST. 0.1274

ANALYSIS OF VARIANCE

	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	1	0.445	0.445	27.440
RESIDUAL	18	0.292	0.016	

VARIABLES IN EQUATION

VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE
(CONSTANT	0.0		
MC/DEV 2	-0.31298	0.05975	27.4397 (2)

VARIABLES NOT IN EQUATION

VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
Q82 3	-0.56944	0.0367	8.1576 (2)
NLG 4	-0.58309	0.0715	8.7874 (2)
1-W 5	-0.26641	0.7050	1.2988 (2)
YC 6	0.44278	0.0989	4.1456 (1)

STEP NUMBER 2
VARIABLE ENTERED 4

MULTIPLE R 0.8594
STD. ERROR OF EST. 0.1065

ANALYSIS OF VARIANCE				
	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	2	0.548	0.272	24.021
RESIDUAL	17	0.193	0.011	

VARIABLES IN EQUATION				VARIABLES NOT IN EQUATION			
VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE	VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
(CONSTANT	0.0						
MC/DEV 2	-0.20768	0.05067	32.2294 (2)	QB2 3	-0.44807	0.6981	3.9823 (2)
NLG 4	-0.00193	0.00065	8.7574 (2)	1-M 5	-0.23605	0.6939	0.9509 (2)
				YC 6	0.71756	0.0942	16.9827 (1)

STEP NUMBER 3
VARIABLE ENTERED 3

MULTIPLE R 0.8890
STD. ERROR OF EST. 0.0983

ANALYSIS OF VARIANCE				
	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	3	0.583	0.194	20.105
RESIDUAL	16	0.155	0.010	

VARIABLES IN EQUATION				VARIABLES NOT IN EQUATION			
VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE	VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
(CONSTANT	0.0						
MC/DEV 2	-0.25034	0.05041	24.6656 (2)	1-M 5	-0.34910	0.6759	2.0010 (2)
QB2 3	-0.00151	0.00066	3.9523 (2)	YC 6	0.75010	0.0934	20.2000 (1)
NLG 4	-0.00139	0.00066	4.4280 (2)				

STEP NUMBER 4
VARIABLE ENTERED 5

MULTIPLE R 0.9033
STD. ERROR OF EST. 0.0951

ANALYSIS OF VARIANCE				
	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	4	0.602	0.150	16.619
RESIDUAL	15	0.136	0.009	

VARIABLES IN EQUATION				VARIABLES NOT IN EQUATION			
VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE	VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
(CONSTANT	0.0						
MC/DEV 2	-0.20504	0.05001	12.4017 (2)	YC 6	0.84935	0.0985	36.2492 (1)
QB2 3	-0.00144	0.00064	5.1064 (2)				
NLG 4	-0.00122	0.00065	3.4982 (2)				
1-M 5	-0.14042	0.10267	2.0010 (2)				

F-LEVEL OR TOLERANCE INSUFFICIENT FOR FURTHER COMPUTATION

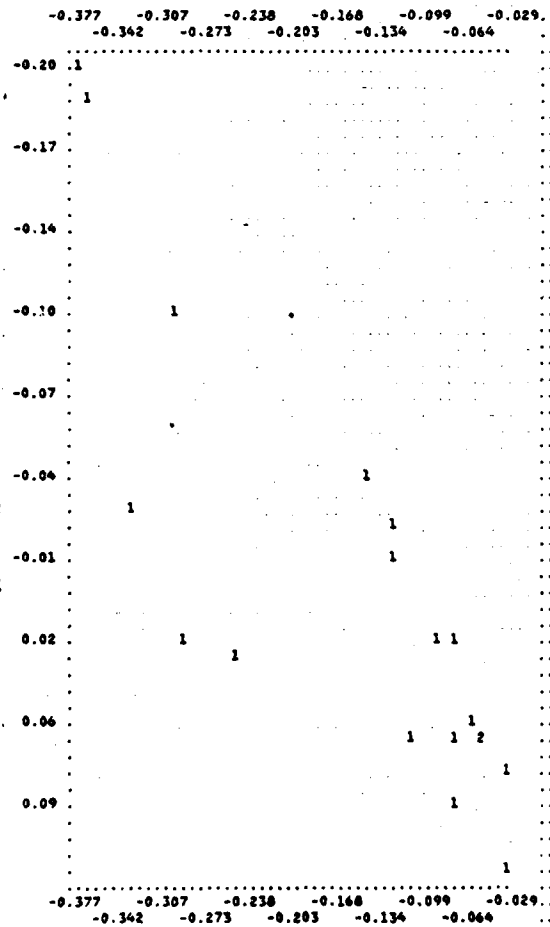
SUMMARY TABLE

STEP NUMBER	VARIABLE		MULTIPLE		INCREASE IN RSQ	F VALUE TO ENTER OR REMOVE
	ENTERED	REMOVED	R	RSQ		
1	MC/DEV 2		0.7771	0.6039	0.6039	27.4397
2	NLG 4		0.8594	0.7306	0.1347	8.7574
3	QB2 3		0.8890	0.7903	0.0510	3.9523
4	1-M 5		0.9033	0.8159	0.0296	2.0010

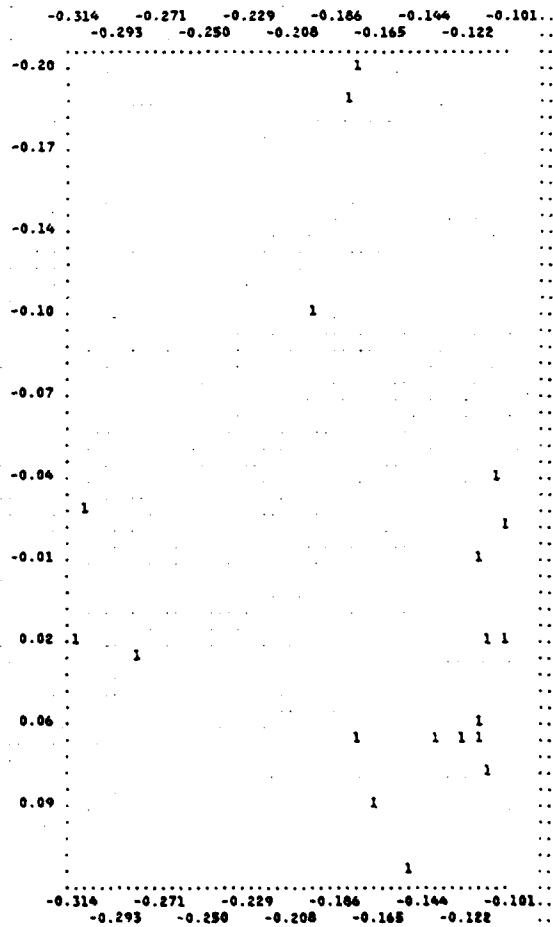
LIST OF RESIDUALS

CASE NUMBER	Y X(1)	Y COMPUTED	RESIDUAL	X(2)	X(4)	X(3)	X(5)
1	-0.0362	-0.1504	0.1142	0.4769	0.0	31.0000	0.0500
2	-0.3372	-0.3096	-0.0276	0.3308	132.5000	43.0000	0.1200
3	-0.3665	-0.1821	-0.1844	0.5542	0.0	46.0000	0.0100
4	-0.2510	-0.2841	0.0323	0.1415	99.0000	74.0000	0.1800
5	-0.2924	-0.3139	0.0215	0.4865	0.0	144.0000	0.0300
6	-0.3010	-0.1991	-0.1019	0.4651	0.0	5.0000	0.6500
7	-0.0605	-0.1253	0.0648	0.5968	0.0	0.0	0.0200
8	-0.0915	-0.1153	0.0240	0.3359	0.0	31.0000	0.0100
9	-0.1487	-0.1106	-0.0381	0.5250	0.0	0.0	0.0200
10	-0.0809	-0.1055	0.0246	0.4643	0.0	4.0000	0.0300
11	-0.0362	-0.1140	0.0778	.5055	0.0	0.0	0.0700
12	-0.1249	-0.1185	-0.0064	0.5208	0.0	5.0000	0.0300
13	-0.0555	-0.1199	0.0644	0.4909	0.0	0.0	0.1300
14	-0.1249	-0.1055	-0.0194	0.5000	0.0	0.0	0.0200
15	-0.0809	-0.1666	0.0877	0.3209	5.2500	2.0000	0.6300
16	-0.0209	-0.1407	0.0598	0.5921	0.0	0.0	0.1300
17	-0.0655	-0.1203	0.0548	0.5581	0.0	3.0000	0.0100
18	-0.3768	-0.1768	-0.2000	0.6667	0.0	0.0	0.2700
19	-0.1135	-0.1793	0.0658	0.4909	0.0	0.0	0.5300

PLOT OF RESIDUALS (Y-AXIS)
VS. VARIABLE 1 (X-AXIS)



PLOT OF RESIDUALS (Y-AXIS)
VS. COMPUTED Y (X-AXIS)



REGRESSION ANALYSIS RESULTS FOR SYSTEM TEST YIELD (Ys)

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LABELS 1YS      2NDEV  3NMC   4QA    5QB    6QB1   7QB2
0
LABELS 12TTLOTL 13ECL  14MOS  15IIL  18DIGLSI 19BIPHEM 20PINS
0
LABELS 21NDG   22NLG   23BITS  24NROM  25NRAM  26MC/DEV 27XMC**2
0
LABELS 38RA   39LNYS
0
(7X,F5.2,2X,18F3.0,2F6.0,F6.2,F6.0,2F3.0)

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96 149 9 0 0 9 0 0 0 0 0 0 9 0 0 0 9 0 0 0 0 0 3750 0 0 0
94 81 51 0 0 51 0 0 0 0 0 51 0 0 0 51 0 0 0 714 449 0 0 0 0
87 129 19 0 0 19 0 0 0 0 0 19 0 0 0 19 0 0 0 266 173 0 0 0 0
74 73 56 0 0 56 0 0 0 0 0 56 0 0 0 56 0 0 0 784 308 0 0 0 0
91 64 51 0 0 51 0 0 0 0 0 51 0 0 0 51 0 0 0 714 270 0 0 0 0
93 128 7 0 0 7 0 0 0 0 0 5 2 0 0 5 2 0 0 70 48 975 0 0 0
81 54 37 0 0 37 0 0 0 0 0 37 0 0 0 37 0 0 0 522 184 0 0 0 0
94 30 20 0 0 20 0 0 0 0 0 20 0 0 0 20 0 0 0 296 106 0 0 0 0
89 40 26 0 0 26 0 0 0 0 0 26 0 0 0 26 0 0 0 364 238 0 0 0 0
95 137 7 0 0 7 0 0 0 0 0 1 6 0 0 1 6 0 0 14 6 3525 0 0 0
72 153 3 0 0 3 0 0 0 0 0 1 2 0 0 1 2 0 0 14 4 975 0 0 0
96 73 58 0 0 58 0 0 0 0 0 58 0 0 0 58 0 0 0 816 397 0 0 0 0
89 73 54 0 0 54 0 0 0 0 0 54 0 0 0 54 0 0 0 756 446 0 0 0 0
91 54 44 0 0 44 0 0 0 0 0 44 0 0 0 44 0 0 0 616 242 0 0 0 0
91 59 41 0 0 41 0 0 0 0 0 41 0 0 0 41 0 0 0 582 146 0 0 0 0
89 58 47 0 0 47 0 0 0 0 0 47 0 0 0 47 0 0 0 660 319 0 0 0 0
91 68 28 0 0 28 0 0 0 0 0 28 0 0 0 8 0 0 20 446 32 0 5120 20 0
93 66 26 0 0 26 0 0 0 0 0 26 0 0 0 8 0 0 18 407 32 0 4608 18 0
93 63 23 0 0 23 0 0 0 0 0 23 0 0 0 8 0 0 15 352 32 0 3840 15 0
98 36 28 0 0 28 0 0 0 0 0 28 0 0 0 28 0 0 0 408 261 0 0 0 0
83 160 1 0 0 1 0 0 0 0 0 0 1 0 0 0 1 0 0 0 0 0 550 0 0 0
96 67 53 0 0 53 0 0 0 0 0 53 0 0 0 53 0 0 0 742 300 0 0 0 0

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VARIABLE	MEAN	STANDARD DEVIATION
YS	0.89818	0.90066
NDEV	82.50000	91.34326
NPC	31.31618	36.31992
QA	0.0	0.0
QB	0.0	0.0
QB1	31.31618	36.31992
QB2	0.0	0.0
8	0.0	0.0
9	0.0	0.0
10	0.0	0.0
11	0.0	0.0

TTLDL	12	30.40909	34.21840
ECL	13	0.90909	2.39317
MCS	14	0.0	0.0
IIL	15	0.0	0.0
	16	28.00000	35.07265
	17	0.90909	2.39317
DIGLSI	18	0.0	0.0
BIPHEM	19	2.40909	6.56783
PINS	20	433.77271	513.43579
NOG	21	181.50000	233.81665
NLG	22	4.44318	11.42005
BITS	23	616.72705	1461.36377
NROM	24	2.40909	6.56783
NRAM	25	0.0	0.0
MC/DEV	26	0.50585	0.59001
ZMC**2	27	0.34811	0.43353
	28	0.0	0.0
	29	0.0	0.0
	30	93.95454	105.95975
	31	0.0	0.0
	32	0.0	0.0
	33	93.95454	105.95975
	34	93.95454	105.95975
	35	0.0	0.0
	36	31.31818	36.31992
	37	31.31818	36.31992
RA	38	3.00000	3.00000
LNYS	39	-0.11037	0.13566

CORRELATION MATRIX

VARIABLE NUMBER	1	2	3	4	5	6	7	8	9	10
1	1.000	0.892	0.863	0.0	0.0	0.863	0.0	0.0	0.0	0.0
2		1.000	0.640	0.0	0.0	0.640	0.0	0.0	0.0	0.0
3			1.000	0.0	0.0	1.000	0.0	0.0	0.0	0.0
4				1.000	0.0	0.0	0.0	0.0	0.0	0.0
5					1.000	0.0	0.0	0.0	0.0	0.0
6						1.000	0.0	0.0	0.0	0.0
7							1.000	0.0	0.0	0.0
8								1.000	0.0	0.0
9									1.000	0.0
10										1.000

VARIABLE NUMBER	11	12	13	14	15	16	17	18	19	20
1	0.0	0.840	0.390	0.0	0.0	0.797	0.390	0.0	0.376	0.046
2	0.0	0.602	0.600	0.0	0.0	0.572	0.600	0.0	0.262	0.685
3	0.0	0.998	0.075	0.0	0.0	0.981	0.075	0.0	0.262	0.997
4	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
5	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
6	0.0	0.998	0.075	0.0	0.0	0.981	0.075	0.0	0.262	0.997
7	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
8	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
9	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
10	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
11	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
12		1.000	0.009	0.0	0.0	0.984	0.009	0.0	0.262	1.000
13			1.000	0.0	0.0	0.810	1.000	0.0	0.0	0.009
14				1.000	0.0	0.0	0.0	0.0	0.0	0.0
15					1.000	0.0	0.0	0.0	0.0	0.0
16						1.000	0.010	0.0	0.004	0.978
17							1.000	0.0	0.0	0.009
18								1.000	0.0	0.0
19									1.000	0.290
20										1.000

VARIABLE NUMBER	21	22	23	24	25	26	27	28	29	30
1	0.779	0.398	0.376	0.376	0.0	0.861	0.806	0.0	0.0	0.863
2	0.567	0.612	0.263	0.268	0.0	0.581	0.525	0.0	0.0	0.640
3	0.948	0.075	0.262	0.262	0.0	0.971	0.956	0.0	0.0	1.000
4	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
5	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
6	0.948	0.075	0.262	0.262	0.0	0.971	0.956	0.0	0.0	1.000
7	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
8	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
9	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
10	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
11	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
12	0.950	0.010	0.262	0.262	0.0	0.972	0.959	0.0	0.0	0.998
13	0.011	0.987	0.0	0.0	0.0	0.032	0.002	0.0	0.0	0.075
14	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
15	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
16	0.972	0.011	0.084	0.084	0.0	0.958	0.966	0.0	0.0	0.981
17	0.011	0.987	0.0	0.0	0.0	0.032	0.002	0.0	0.0	0.075
18	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
19	0.050	0.0	1.000	1.000	0.0	0.244	0.131	0.0	0.0	0.262
20	0.943	0.010	0.290	0.290	0.0	0.972	0.956	0.0	0.0	0.997
21	1.000	0.012	0.050	0.050	0.0	0.921	0.926	0.0	0.0	0.948
22		1.000	0.0	0.0	0.0	0.033	0.002	0.0	0.0	0.075
23			1.000	1.000	0.0	0.244	0.131	0.0	0.0	0.262
24				1.000	0.0	0.244	0.131	0.0	0.0	0.262
25					0.0	0.0	0.0	0.0	0.0	0.0
26						1.000	0.989	0.0	0.0	0.971
27							1.000	0.0	0.0	0.956
28								0.0	0.0	0.0
29									0.0	0.0
30										1.000

VARIABLE NUMBER	31	32	33	34	35	36	37	38	39
1	0.0	0.0	0.863	0.863	0.0	0.863	0.863	0.997	-0.768
2	0.0	0.0	0.640	0.640	0.0	0.640	0.640	0.903	-0.805
3	0.0	0.0	1.000	1.000	0.0	1.000	1.000	0.862	-0.674
4	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
5	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
6	0.0	0.0	1.000	1.000	0.0	1.000	1.000	0.862	-0.674
7	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
8	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
9	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
10	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
11	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
12	0.0	0.0	0.998	0.998	0.0	0.998	0.998	0.840	-0.660
13	0.0	0.0	0.075	0.075	0.0	0.075	0.075	0.380	-0.233
14	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
15	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
16	0.0	0.0	0.981	0.981	0.0	0.981	0.981	0.798	-0.641
17	0.0	0.0	0.075	0.075	0.0	0.075	0.075	0.380	-0.233
18	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
19	0.0	0.0	0.262	0.262	0.0	0.262	0.262	0.367	-0.218
20	0.0	0.0	0.997	0.997	0.0	0.997	0.997	0.845	-0.661
21	0.0	0.0	0.948	0.948	0.0	0.948	0.948	0.776	-0.595
22	0.0	0.0	0.075	0.075	0.0	0.075	0.075	0.389	-0.243
23	0.0	0.0	0.262	0.262	0.0	0.262	0.262	0.367	-0.218
24	0.0	0.0	0.262	0.262	0.0	0.262	0.262	0.367	-0.218
25	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
26	0.0	0.0	0.971	0.971	0.0	0.971	0.971	0.857	-0.648
27	0.0	0.0	0.956	0.956	0.0	0.956	0.956	0.803	-0.620
28	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
29	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
30	0.0	0.0	1.000	1.000	0.0	1.000	1.000	0.862	-0.674
31	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
32		0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0
33			1.000	1.000	0.0	1.000	1.000	0.862	-0.674
34				1.000	0.0	1.000	1.000	0.862	-0.674
35					0.0	0.0	0.0	0.0	0.0
36						1.000	1.000	0.862	-0.674
37							1.000	0.862	-0.674
38								1.000	-0.814
39									1.000

SUB-PROBLM 1
 DEPENDENT VARIABLE 39
 MAXIMUM NUMBER OF STEPS 2
 F-LEVEL FOR INCLUSION 0.010000
 F-LEVEL FOR DELETION 0.005000
 TOLERANCE LEVEL 0.001000

STEP NUMBER 1
 VARIABLE ENTERED 2

MULTIPLE R 0.8051
 STD. ERROR OF EST. 0.0824

ANALYSIS OF VARIANCE				
	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	1	0.262	0.262	38.702
RESIDUAL	21	0.142	0.007	

VARIABLES IN EQUATION				VARIABLES NOT IN EQUATION			
VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE	VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
(CONSTANT	0.0			YS	-0.10691	0.2045	0.7200 (1)
NDEV 2	-0.00120	0.00019	38.7025 (9)	NYC	-0.34747	0.5904	2.7462 (1)
				QA	0.0	0.0	0.0 (1)
				QS	0.0	0.0	0.0 (1)
				QB1	-0.34747	0.5904	2.7462 (1)
				QB2	0.0	0.0	0.0 (1)
					0.0	0.0	0.0 (1)
					0.0	0.0	0.0 (1)
					0.0	0.0	0.0 (1)
					0.0	0.0	0.0 (1)
				TTLDTL	-0.37025	0.6374	3.1772 (1)
				ECL	0.52704	0.6401	7.6919 (1)
				MOS	0.0	0.0	0.0 (1)
				IIL	0.0	0.0	0.0 (1)
					-0.37019	0.6725	3.1773 (1)
					0.52704	0.6401	7.6919 (1)
				DIBLSI	0.0	0.0	0.0 (1)
				BIPWEN	-0.00928	0.9300	0.0017 (1)
				PINS	-0.36809	0.6341	3.1346 (1)
				NDG	-0.28461	0.6791	1.7628 (2)
				NLS	0.53217	0.6259	7.9018 (2)
				SITS	-0.00928	0.9300	0.0017 (1)
				NRON	-0.00928	0.9300	0.0017 (1)
				NRAM	0.0	0.0	0.0 (1)
				NC/DEV	-0.37310	0.6623	3.2342 (2)
				ZMCH#2	-0.37130	0.7239	3.1981 (2)
					0.0	0.0	0.0 (1)
					0.0	0.0	0.0 (1)
					-0.34747	0.5904	2.7463 (1)
					0.0	0.0	0.0 (1)
					0.0	0.0	0.0 (1)
					-0.34747	0.5904	2.7463 (1)
					-0.34747	0.5904	2.7463 (1)
					0.0	0.0	0.0 (1)
					-0.34747	0.5904	2.7462 (1)
					-0.34747	0.5904	2.7462 (1)
				RA	-0.33927	0.1043	2.6018 (1)

STEP NUMBER 2
 VARIABLE ENTERED 3

MULTIPLE R 0.8311
 STD. ERROR OF EST. 0.0791

ANALYSIS OF VARIANCE

	DF	SUM OF SQUARES	MEAN SQUARE	F RATIO
REGRESSION	2	0.280	0.140	22.333
RESIDUAL	20	0.125	0.006	

VARIABLES IN EQUATION				VARIABLES NOT IN EQUATION			
VARIABLE	COEFFICIENT	STD. ERROR	F TO REMOVE	VARIABLE	PARTIAL CORR.	TOLERANCE	F TO ENTER
(CONSTANT	0.0						
NDEV 2	-0.00094	0.00024	15.3217 (9)	YS 1	0.20866	0.0596	0.8649 (1)
NVC 3	-0.00100	0.00060	2.7463 (9)	QA 4	0.0	0.0	0.0 (1)
				QB 5	0.0	0.0	0.0 (1)
				QB1 6	-0.00044	0.0000	0.0000 (1)
				QB2 7	0.0	0.0	0.0 (1)
				8	0.0	0.0	0.0 (1)
				9	0.0	0.0	0.0 (1)
				10	0.0	0.0	0.0 (1)
				11	0.0	0.0	0.0 (1)
				TTLDL 12	-0.43685	0.0021	4.4306 (1)
				ECL 13	0.43679	0.4788	4.4290 (1)
				MOS 14	0.0	0.0	0.0 (1)
				IIL 15	0.0	0.0	0.0 (1)
				16	-0.19251	0.0315	0.4524 (1)
				17	0.43679	0.4788	4.4290 (1)
				DIGLSI 18	0.0	0.0	0.0 (1)
				SIPHEM 19	0.03652	0.9155	0.0254 (1)
				PINS 20	-0.31390	0.0034	2.0768 (1)
				NDS 21	0.10270	0.0985	0.2025 (2)
				NLG 22	0.43883	0.4566	4.5315 (2)
				BITS 23	0.03652	0.9155	0.0254 (1)
				NROM 24	0.03652	0.9155	0.0254 (1)
				NRAM 25	0.0	0.0	0.0 (1)
				MC/DEV 26	-0.14961	0.0544	0.4350 (2)
				ZMCW2 27	-0.14045	0.0728	0.3824 (2)
				28	0.0	0.0	0.0 (1)
				29	0.0	0.0	0.0 (1)
				30	0.0	0.0	0.0 (1)
				31	0.0	0.0	0.0 (1)
				32	0.0	0.0	0.0 (1)
				33	0.0	0.0	0.0 (1)
				34	0.0	0.0	0.0 (1)
				35	0.0	0.0	0.0 (1)
				36	-0.00044	0.0000	0.0000 (1)
				37	-0.00044	0.0000	0.0000 (1)
				RA 38	-0.08372	0.0474	0.1341 (1)

SPECIFIED STEP REACHED

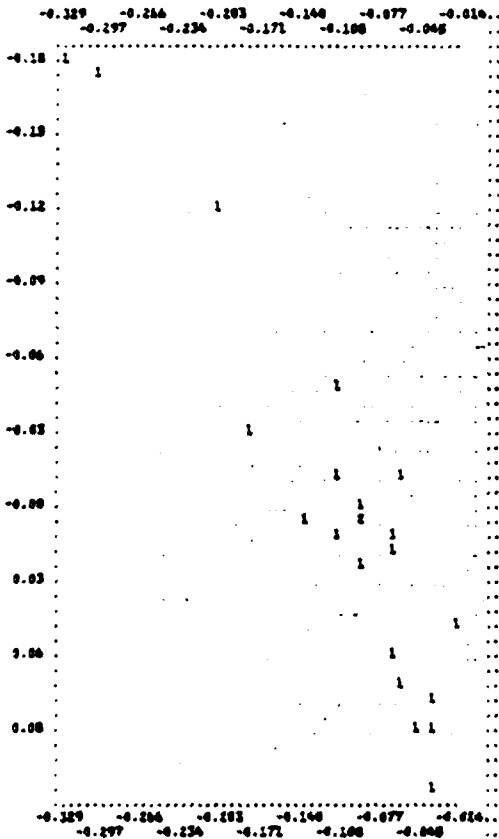
SUMMARY TABLE

STEP NUMBER	VARIABLE		MULTIPLE		INCREASE IN RSQ	F VALUE TO ENTER OR REMOVE
	ENTERED	REMOVED	R	RSQ		
1	NDEV	2	0.8051	0.6483	0.6483	38.7025
2	NVC	3	0.8311	0.6907	0.0425	2.7463

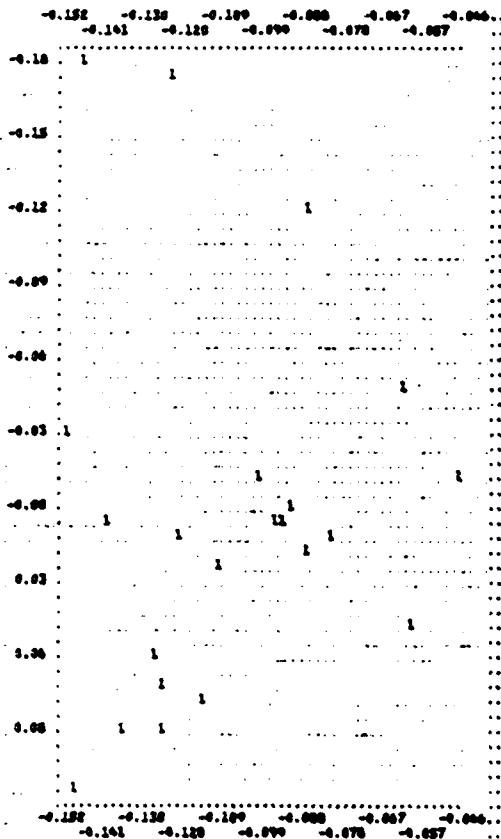
LIST OF RESIDUALS

CASE NUMBER	Y X(3)	Y COMPUTED	RESIDUAL	X(2)	X(3)
1	-0.0408	-0.1492	0.1084	149.0000	9.0000
2	-0.0619	-0.1273	0.0654	81.0000	51.0000
3	-0.1393	-0.1404	0.0011	129.0000	19.0000
4	-0.3011	-0.1248	-0.1763	73.0000	56.0000
5	-0.0943	-0.1113	0.0170	64.0000	51.0000
6	-0.0726	-0.1274	0.0549	128.0000	7.0000
7	-0.2107	-0.0879	-0.1228	54.0000	37.0000
8	-0.0619	-0.0483	-0.0134	30.0000	20.0000
9	-0.1165	-0.0637	-0.0529	40.0000	26.0000
10	-0.0513	-0.1359	0.0846	137.0000	7.0000
11	-0.3285	-0.1470	-0.1815	153.0000	3.0000
12	-0.0408	-0.1268	0.0360	73.0000	50.0000
13	-0.2165	-0.1228	0.0062	73.0000	54.0000
14	-0.0743	-0.0949	0.0006	54.0000	44.0000
15	-0.0943	-0.0666	0.0023	59.0000	41.0000
16	-0.1165	-0.1017	-0.0149	58.0000	47.0000
17	-0.0943	-0.0920	-0.0023	68.0000	28.0000
18	-0.0726	-0.0881	0.0156	66.0000	24.0000
19	-0.0726	-0.0823	0.0097	63.0000	23.0000
20	-0.0202	-0.0619	0.0417	36.0000	28.0000
21	-0.1053	-0.1515	-0.0348	160.0000	1.0000
22	-0.0408	-0.1161	0.0753	67.0000	53.0000

PLOT OF RESIDUALS (Y-AXIS)
VS. VARIABLE 39 (X-AXIS)



PLOT OF RESIDUALS (Y-AXIS)
VS. COMPUTED Y (X-AXIS)



Appendix B
Computer Program Documentation

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This appendix describes the computer program documentation for the MC LCC model. Figure B-1 gives a general overview of the LCC model flow diagram and describes the order in which the major CER's for the LCC program occur.

A detailed flowchart is also provided which gives a complete description of the LCC programs. At each step (box) of the flowchart the following information is provided:

- a) The line number in the source listing for which the step occurs (see page B-3).
- b) The step (box) number found on the upper right hand side of the box is a reference number for continuation branches in the program.
- c) In the continuation boxes, the number inside the box describes the page and box number for the next step. The page and box number are identified as follows:

Y.X

Where Y is the page number and X is the box number. The number on the lower right hand side of the box is the corresponding branch location to the source listing.

A source listing for the MC LCC program is provided following the detailed flow diagram. Comments describing what each section of the program executes are imbedded in the listing. All the CER's developed for the LCC model are provided as subroutines and are clearly marked in the listing.

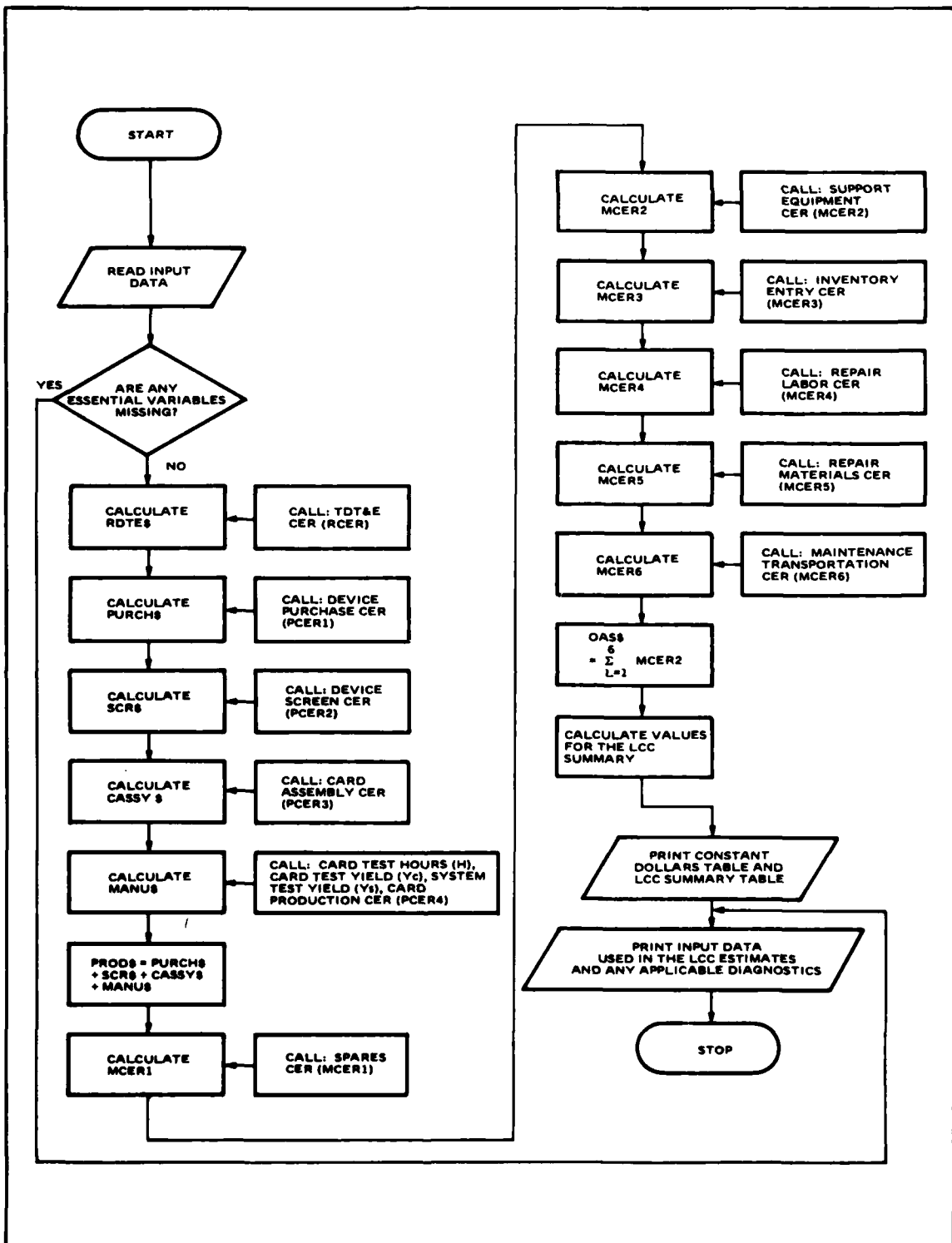
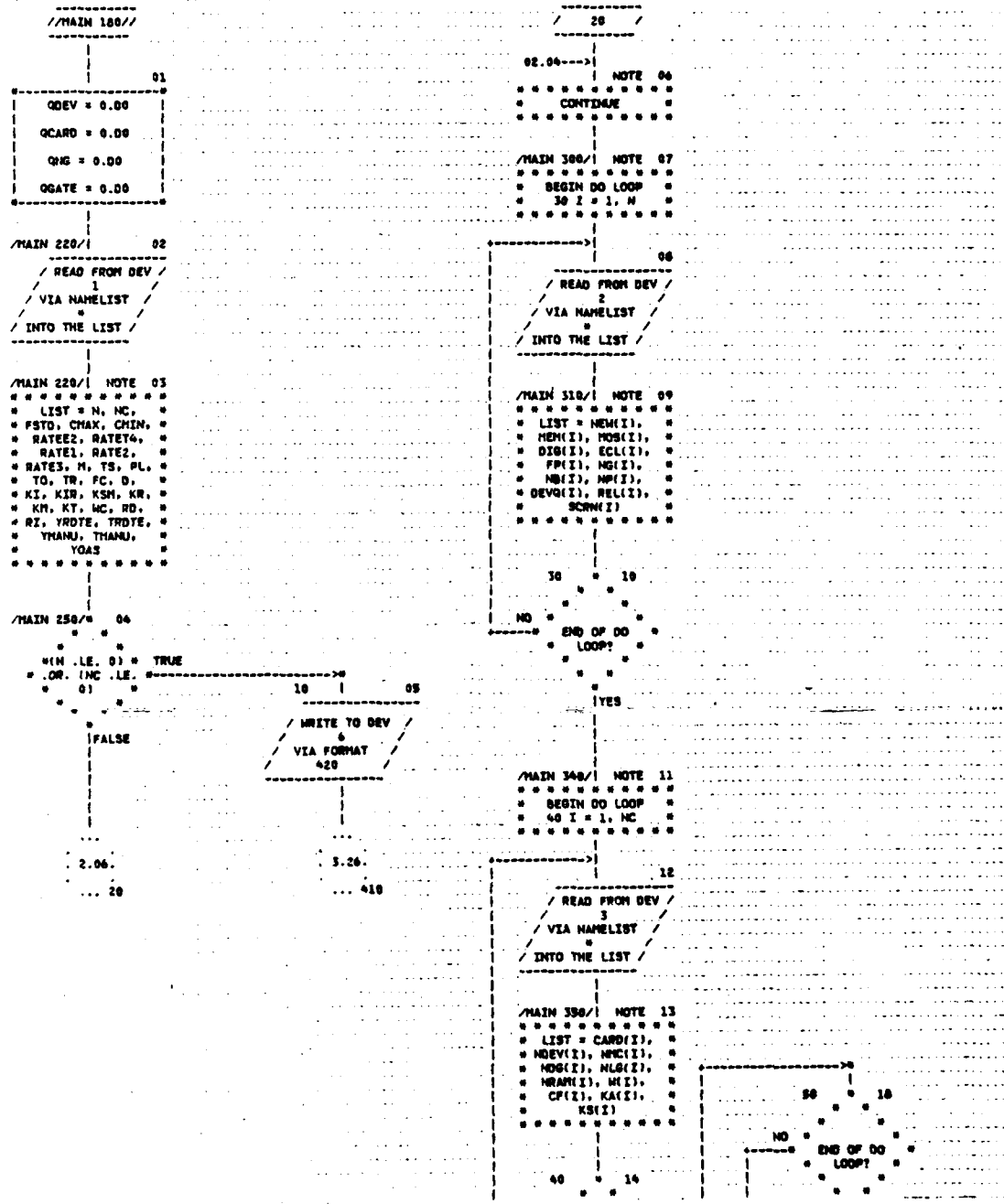
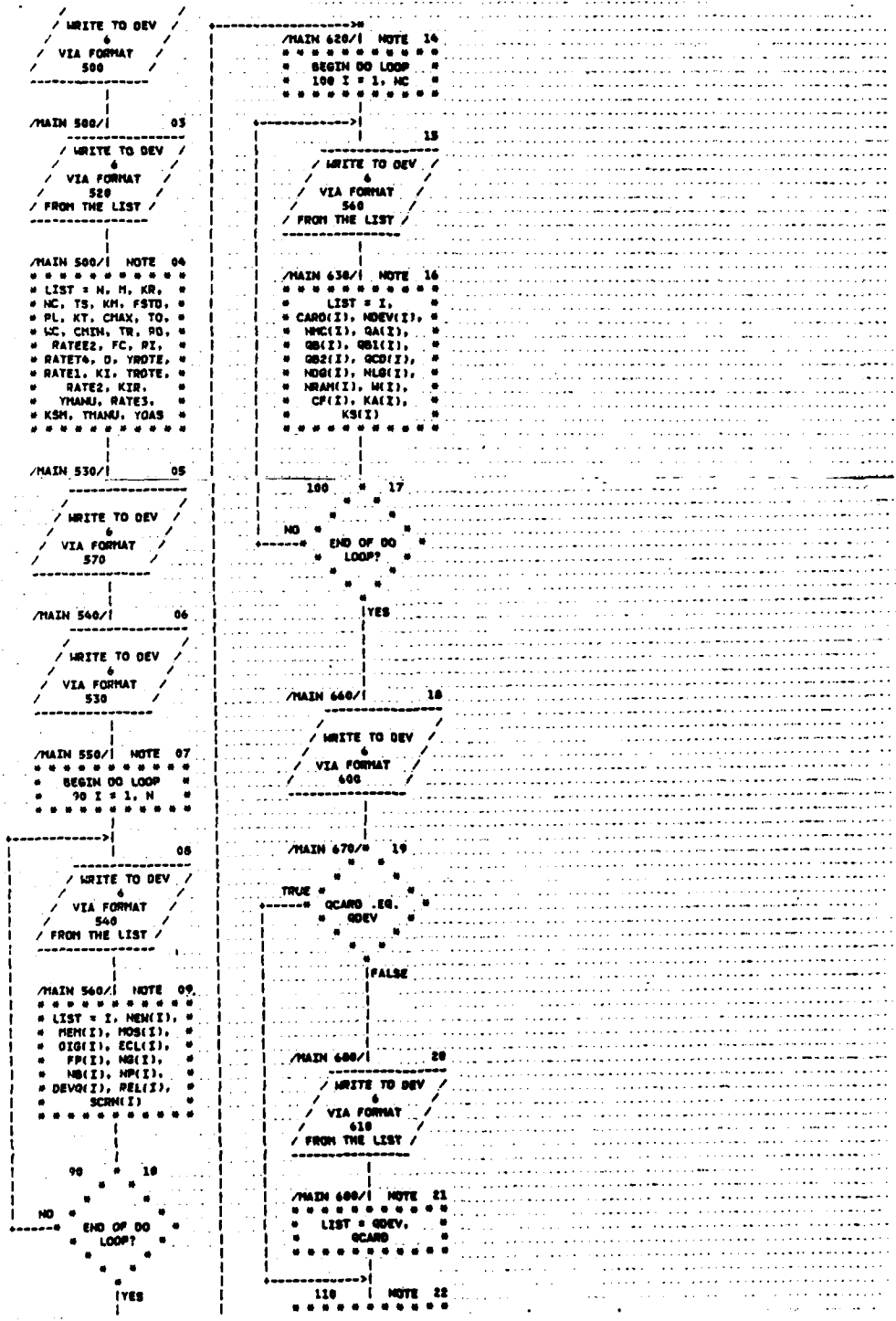


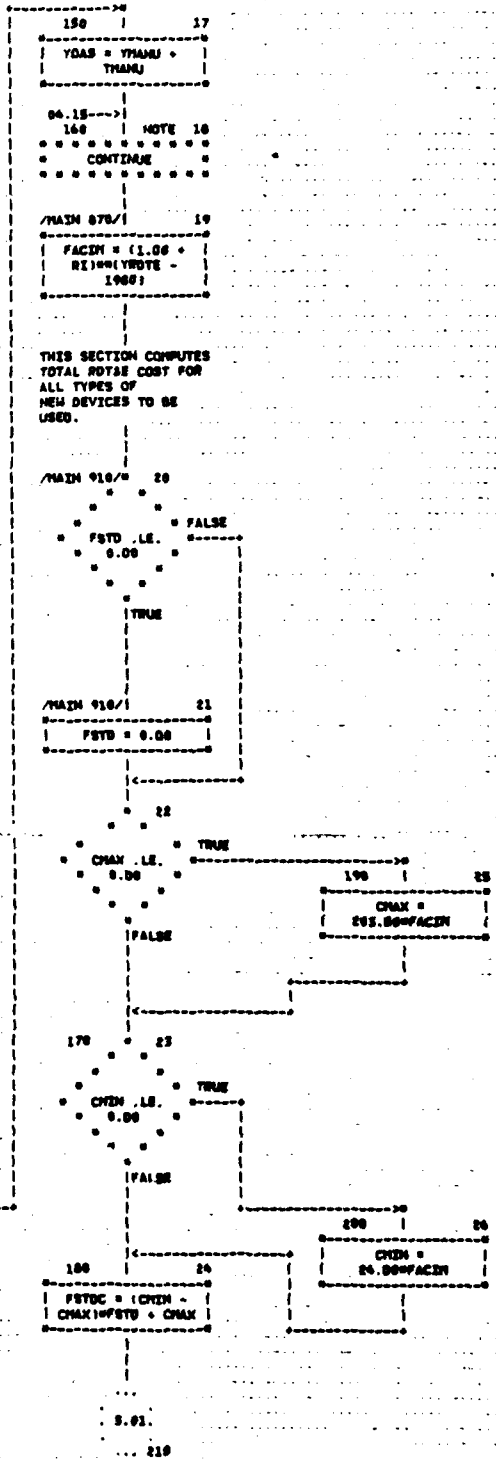
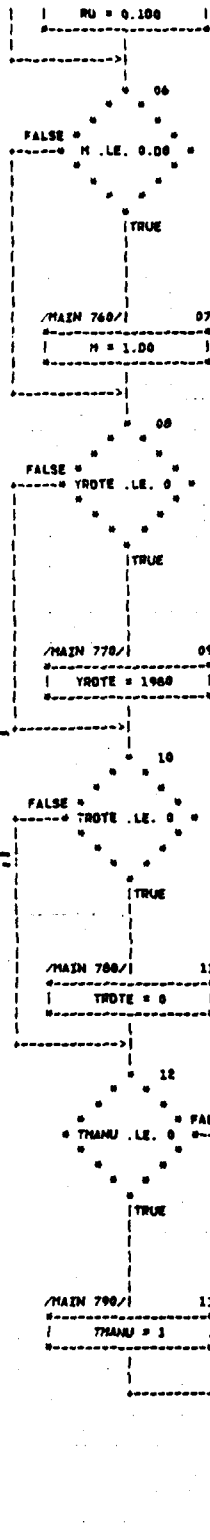
Figure B-1. Simplified Flowchart

B.1 DETAILED FLOW DIAGRAM FOR THE LCC PROGRAM

CHART TITLE - PROCEDURES







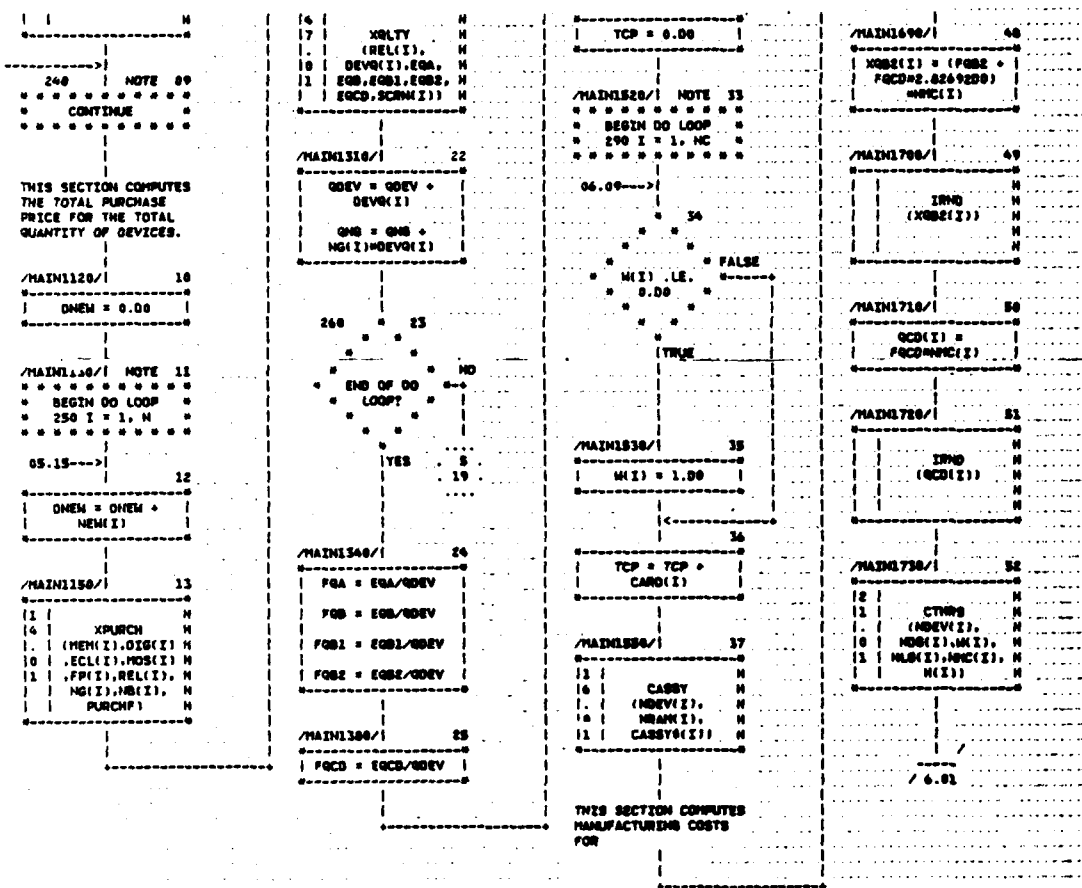
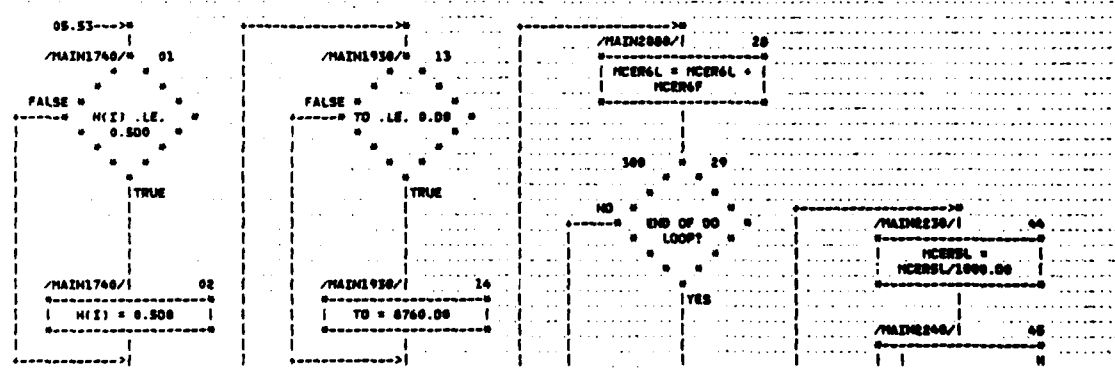


CHART TITLE - PROCEDURES



```

03
12 | XC1 | H
13 | (M1),RATE1 | H
14 | FACIN,C1 | H
15 | | H
-----
/MAIN1766/ 04
12 | XC2 | H
13 | (RATE2,FACIN, | H
14 | C2) | H
15 | | H
-----
/MAIN1770/ 05
12 | XC3 | H
13 | (RATE3,FACIN, | H
14 | C3) | H
15 | | H
-----
/MAIN1780/ 06
12 | XYS | H
13 | (NDEV(I), | H
14 | NDC(I),YS(I)) | H
15 | | H
-----
/MAIN1790/ 07
12 | XVC | H
13 | (NVC(I), | H
14 | NDEV(I), | H
15 | XORS(I),MLG(I), | H
16 | MS(I),VC(I)) | H
-----
/MAIN1800/ 08
12 | PROD | H
13 | (C1,C2,C3, | H
14 | VC(I),YS(I), | H
15 | PROOF(I)) | H
-----
290 09
END OF DO LOOP?
YES 5
NO 34
-----
/MAIN1820/ 10
IRND | H
(MAN18) | H
-----
THIS SECTION COMPUTES
MAJOR MAINTENANCE AND
SUPPLY COSTS.
-----
/MAIN1830/ 11
RNIL = 0.00

```

```

15
FALSE =
PC LE. 0.00
-----
TRUE
-----
/MAIN1940/ 16
PC = 0.30
-----
NOTE 17
* BEGIN DO LOOP *
* 300 I = 1, NC *
* * * * *
-----
18
13 | XPCER1 | H
14 | (MC,M,X,TS,PL, | H
15 | CARD9(I), | H
16 | CARD(I),TO,TR, | H
17 | CP(I),MI(I),PC, | H
18 | D,J,RNIF, | H
19 | NRNIF) | H
-----
/MAIN1960/ 19
RNIL = RNIL +
RNIF
NRNIF = NRNIF +
NRNIF
-----
/MAIN1980/ 20
13 | XPCER2 | H
14 | (KAI(I),KS(I), | H
15 | MCEZP) | H
16 | | H
-----
/MAIN1990/ 21
NCER2L = NCER2L +
NCER2P
-----
/MAIN2000/ 22
14 | XPCER4 | H
15 | (CARD(I),KR, | H
16 | TO,CP(I),MI(I), | H
17 | MI(I),PC,FACIN, | H
18 | MLG(I),MDG(I), | H
19 | MCEZP) | H
-----
/MAIN2040/ 23
NCER4L = NCER4L +
MCEZP
-----
/MAIN2060/ 24
14 | XPCER5 | H
15 | (CARD(I),TO, | H
16 | CP(I),MI(I),KR, | H
17 | CARD9(I), | H
18 | MCEZP) | H

```

```

/MAIN2100/ 30
13 | XPCER3 | H
14 | (NC,ONEM,M,KI, | H
15 | KIR,KSM,FACIN, | H
16 | RM, NRNIF) | H
-----
/MAIN2110/ 31
RNIL =
RNIL/1000.00
-----
/MAIN2120/ 32
IRND | H
(RNIF) | H
-----
/MAIN2130/ 33
NRNIF =
NRNIF/1000.00
-----
/MAIN2140/ 34
IRND | H
(NRNIF) | H
-----
/MAIN2150/ 35
NCER2L =
NCER2L/1000.00
-----
/MAIN2160/ 36
IRND | H
(MCEZL) | H
-----
/MAIN2170/ 37
RNIF =
RNIF/1000.00
-----
/MAIN2180/ 38
IRND | H
(NRNIF) | H
-----
/MAIN2190/ 39
NRNIF =
NRNIF/1000.00
-----
/MAIN2200/ 40
IRND | H
(NRNIF) | H
-----
/MAIN2210/ 41

```

```

IRND | H
(MCER5L) | H
-----
/MAIN2250/ 46
NCER6L =
NCER6L/1000.00
-----
/MAIN2260/ 47
IRND | H
(MCER6L) | H
-----
/MAIN2270/ 48
Y = 5
-----
310 49
RNIF(Y) = YNRNIF
NRNIF(Y) = NRNIF
MCER1(Y) =
RNIF(Y) + NRNIF(Y)
MCER2(Y) = MCER2L
-----
/MAIN2320/ 50
RNIF(Y) = YNRNIF
NRNIF(Y) = NRNIF
MCER3(Y) =
RNIF(Y) + NRNIF(Y)
MCER4(Y) =
MCER4L*Y
-----
/MAIN2340/ 51
MCER5(Y) =
MCER5L*Y
MCER6(Y) =
Y*MCER6L
ROAS(Y) =
RNIF(Y) + RNIF(Y) +
MCER4(Y) +
MCER5(Y) +
MCER6(Y)
-----
/MAIN2360/ 52
NRNIF(Y) =
NRNIF(Y) +
NRNIF(Y) +
MCER2(Y)
OAS(Y) =
MCER1(Y) +
MCER3(Y) +
MCER5(Y) +
MCER6(Y)
-----
/MAIN2410/ 53
TOTALC(Y) =
ROTE9 + PR9 +
OAS(Y)

```



```

NRH1L = 0.00
MCER2L = 0.00
RM3L = 0.00
NRH3L = 0.00

/MAIN1900/ 12
MCER4L = 0.00
MCER5L = 0.00
MCER6L = 0.00

```

```

/MAIN2060/ 25
MCER5L = MCER5L +
MCER5F

/MAIN2070/ 26
14 MCER6 H
15 MCER6 H
(CARD(I),MC H
70 RT,PACIM H
11 CFI(I),MI(I),PC H
MCER6F H

```

```

MCER4L =
MCER4L/1000.00

/MAIN2200/ 42
IRND H
(MCER4L) H

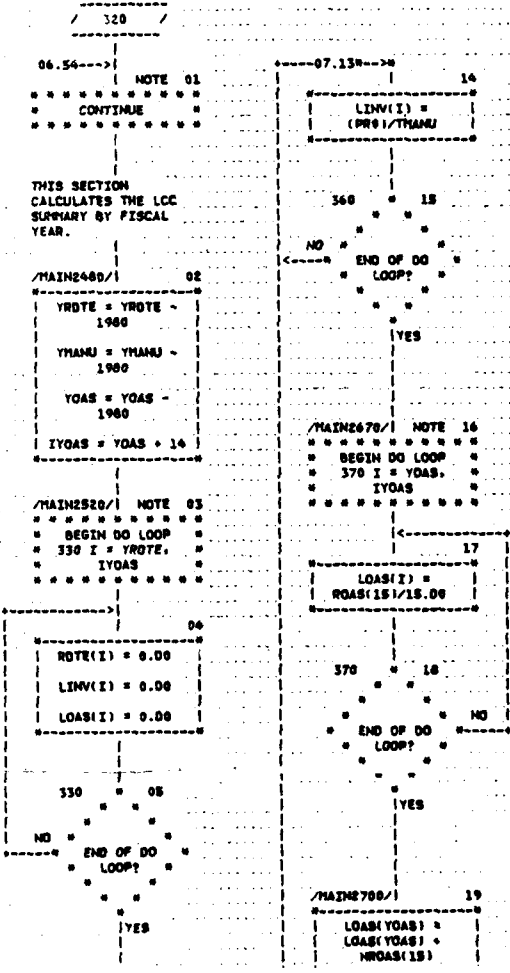
```

```

/MAIN2250/ 54
Y,OE,15
TRUE
FALSE 7
320
/MAIN2300/ 55
Y = Y + 5

```

CHART TITLE - PROCEDURES



```

/MAIN2570/ 04
TRUE
TROTE .EQ. 0
FALSE

```

```

/MAIN2580/ 07
IYRTE = YRTE +
TROTE - 1

```

```

/MAIN2590/ NOTE 09
*****
BEGIN DO LOOP
340 I = YRTE.
IYRTE
*****

```

```

09
ROTE(I) =
ROTE/TROTE

```

```

340 10
NO
END OF DO
LOOP?
YES

```

```

350 NOTE 11
*****
CONTINUE
*****

```

```

/MAIN2630/ 12
IYMAN = YMAN +
YMAN - 1

```

```

/MAIN2640/ NOTE 13
*****
BEGIN DO LOOP
360 I = YMAN.
IYMAN
*****

```

```

ROFAC =
DLOG(1.00 + RD)
TOTRAD = 0.00
TOTIMV = 0.00

```

```

/MAIN2740/ 20
TOTOAS = 0.00
TOTC = 0.00
TOTI = 0.00
TOTIAD = 0.00

```

```

/MAIN2780/ NOTE 21
*****
BEGIN DO LOOP
380 I = YRTE.
IYDAS
*****
06.07-->
22

```

```

IRND
(RTE(I))

```

```

/MAIN2800/ 23
IRND
(LIN(I))

```

```

/MAIN2810/ 24
IRND
(LOAS(I))

```

```

/MAIN2820/ 25
TOTRAD = TOTRAD +
ROTE(I)
TOTIMV = TOTIMV +
LINV(I)
TOTOAS = TOTOAS +
LOAS(I)

```

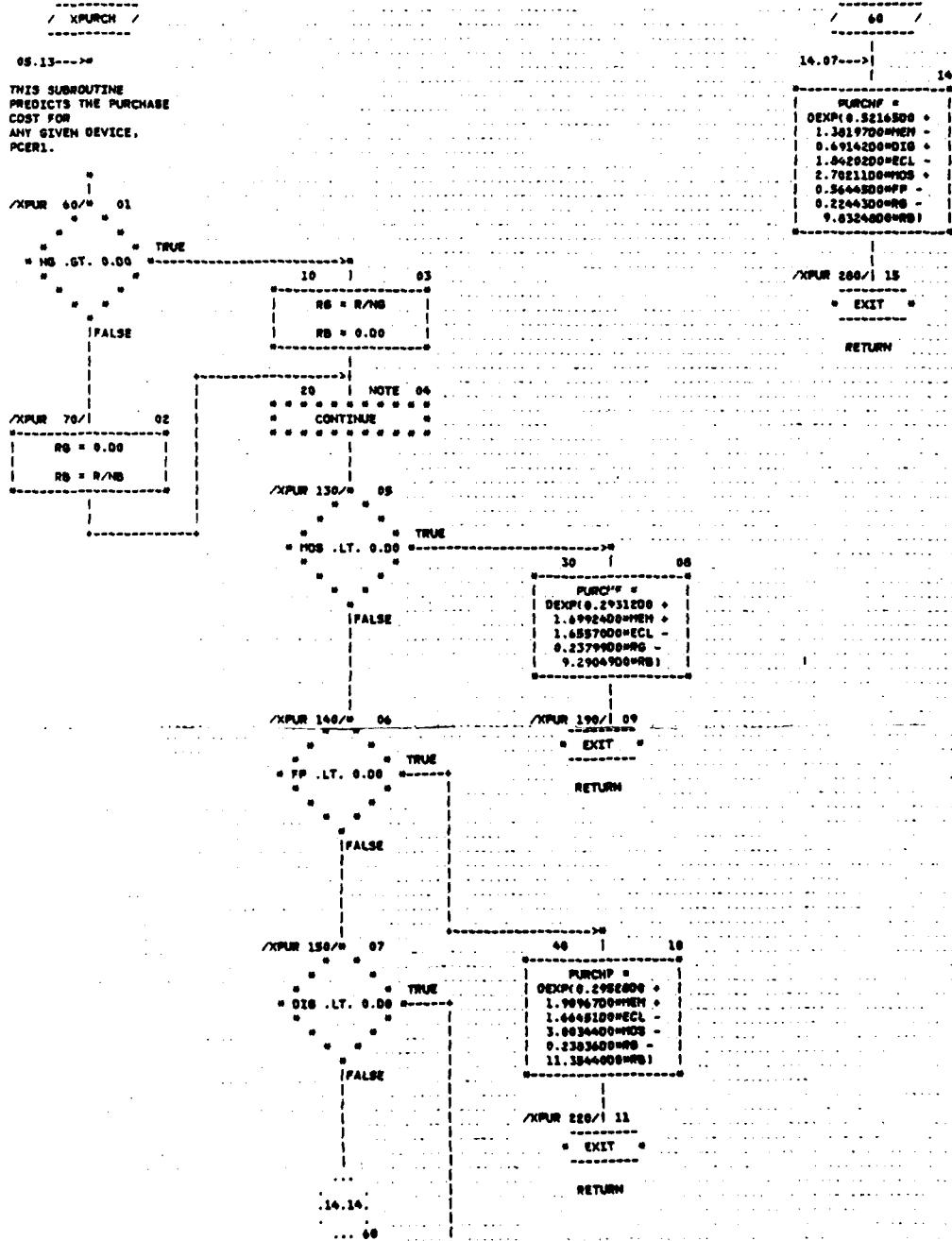
```

/MAIN2830/ 26
LTOTAL(I) =
ROTE(I) +
LINV(I) + LOAS(I)

```

/ 8.01

CHART TITLE - SUBROUTINE XPURCH(MEN,DIG,ECL,HOS,FP,R,NB,RS,PURCHF)



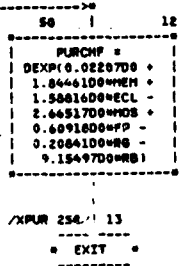


CHART TITLE - SUBROUTINE CASSY(NDIV,NRAH,CASSY6)

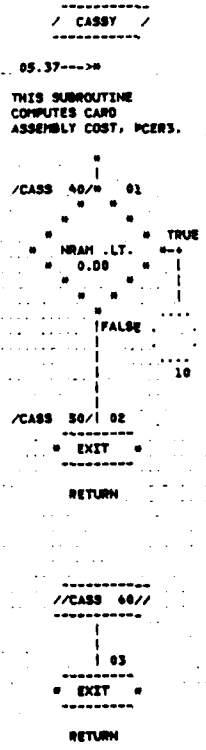


CHART TITLE - SUBROUTINE XSCR(DEVG,REN,HOS,MP,NB,RATEEZ,RATET4,FACIN,NEM,SCREEN

XSCR

05.28-->>

THIS SUBROUTINE COMPUTES THE COST OF PERFORMING THE SCREENING TEST, PCERZ.

XSCR 60/04

RATEEZ .LE. 0.00

TRUE

90 RATEEZ = 43.7500*FACIN

FALSE

10 05

RATET4 .LE. 0.00

TRUE

100 RATET4 = 39.00*FACIN

FALSE

20 NOTE 06 (NEM .EQ. 1.00) .AND. (MP .GE. 15.00) .AND. (MP .LT. 24.00)

XSCR 90/07

SEE NOTE ABOVE

TRUE

FALSE

10.67*50 SCREEN = (0.6841700* RATEEZ + 0.62100*RATET4 + 13.7500*FACIN) *DEVG + 46.00*RATEEZ

XSCR 90/08 (MP .GE. 0.00) .AND. (MP .LT. 17.00) .AND. (MP .GE. 10.00) .AND. (MP .LE. 100.00)

XSCR 90/09

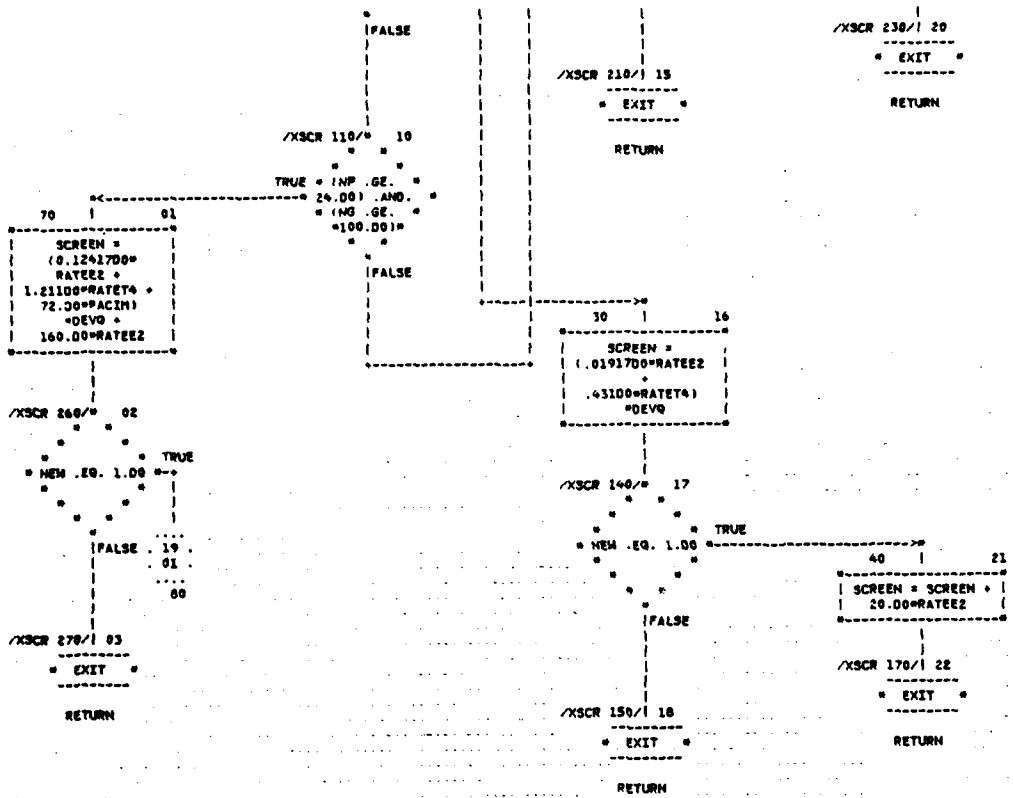
SEE NOTE ABOVE

TRUE

XSCR 200/14 NEM .EQ. 1.00

FALSE

40 SCREEN = SCREEN + 00.00*RATEEZ

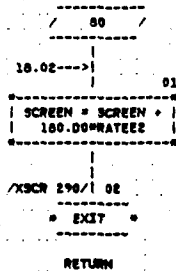


AUTOFLOW CHART SET -

MCF MODEL

PAGE 19

CHART TITLE - SUBROUTINE XSCR(DEVQ, MEM, NOS, NP, NB, RATE2, RATE4, FACIM, MEM, SCREEN




```

/XC1 70/ 03
  * EXIT *
RETURN

```

CHART TITLE - SUBROUTINE XC2(RATE2,FACIN,C2)

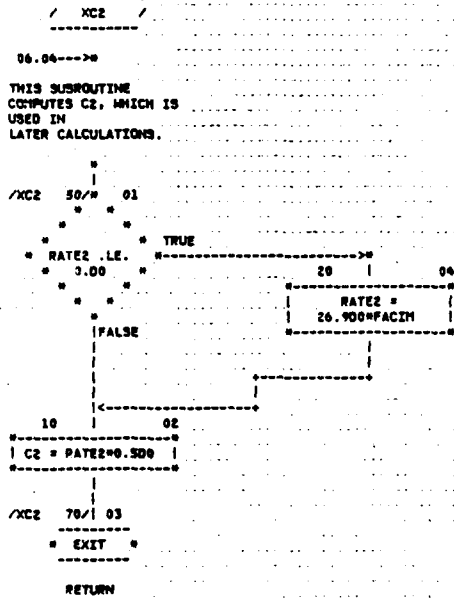
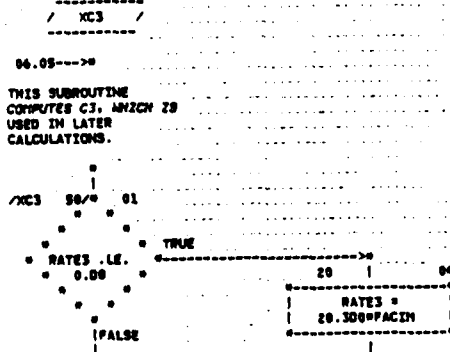


CHART TITLE - SUBROUTINE XC3(RATE3,FACIN,C3)



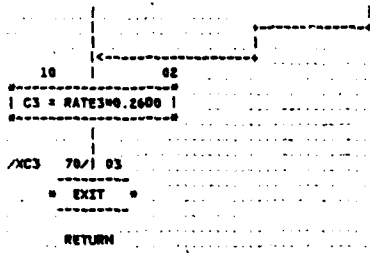


CHART TITLE - SUBROUTINE XYS(NDEV, NPC, YS)

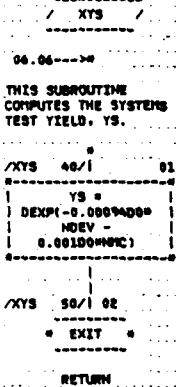
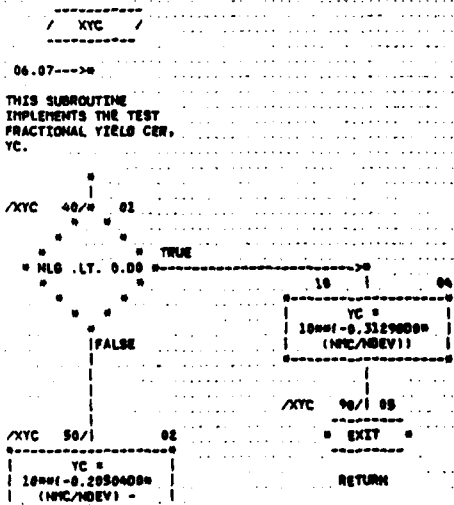


CHART TITLE - SUBROUTINE XYC(NPC, NDEV, QBE, NLS, M, YC)



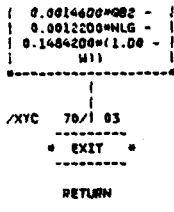


CHART TITLE - SUBROUTINE PROD(C1,C2,C3,YC,YS,PROF)

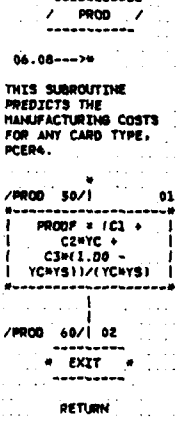
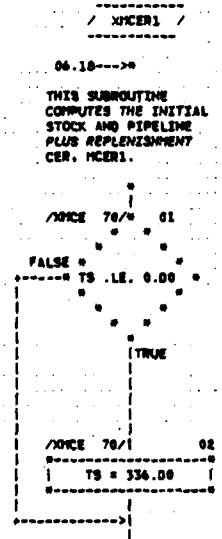
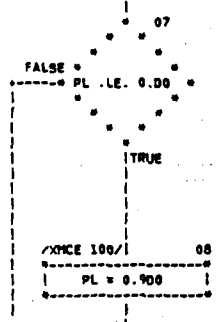
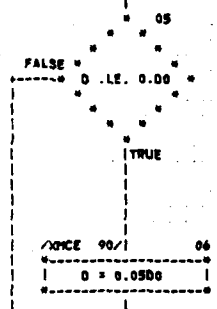
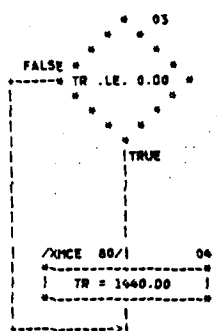


CHART TITLE - SUBROUTINE XICER1(INC,H,X,TS,PL,CARD\$,CARD,TO,TR,CF,W,FC,D,J,RHIF,



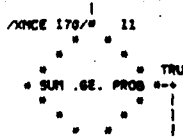


```

    09
    KC = CARDS
    QC = CARD/M
    X = 0
    A =
    TSHQCPCF*(1.00 +
    FC)
    PROB =
    PL*(1.00/MC)
  
```

```

    10
    SUM = DEXP(-A)
  
```

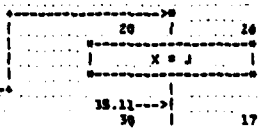
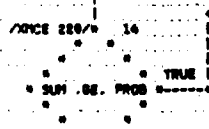


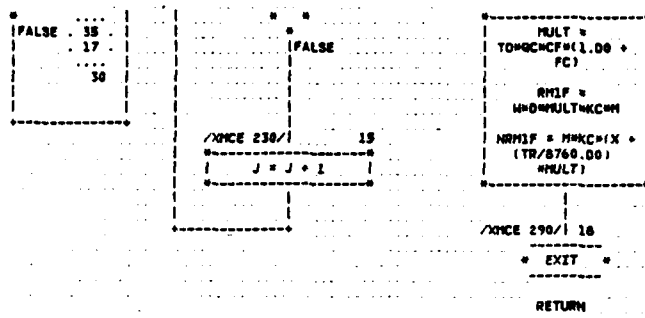
```

    12
    TERM = SUM
    J = 1
  
```

```

    13
    TERM = TERM*(A/J)
    SUM = SUM + TERM
  
```





AUTOFLON CHART Set -

MCF MODEL

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CHART TITLE - SUBROUTINE XICER2(KA,KS,MCER2F)

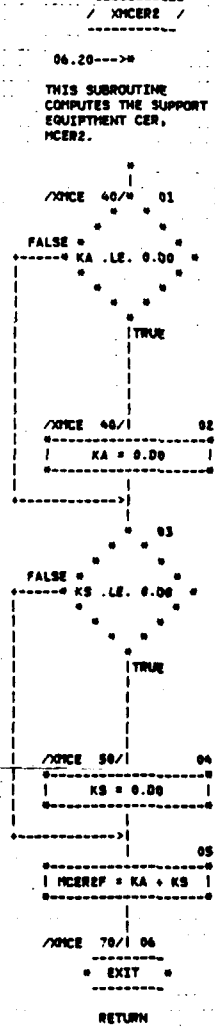


CHART TITLE - SUBROUTINE XNCERS(NC,ONEM,H,KI,KIR,KSH,FACIN,RHSL,IRHSL)

XNCERS

06.30-->

THIS SUBROUTINE
COMPUTES THE
INVENTORY ENTRY
OF SUPPLY MANAGEMENT
CER. NCERS.

/ONCE 60/ 01

* KI .LT. 0.00

TRUE

40 | 10
KI = 54.00FACIN

FALSE

10 02

* KIR .LT. 0.00

TRUE

50 | 11
KIR = 128.00FACIN

FALSE

20 03

* KSH .LT. 0.00

TRUE

FALSE

30 04

FALSE * KI .EQ. 0.00

60 | 12
KSH = 42.00FACIN

TRUE

/ONCE 90/ 05

KIR = 0.00

06

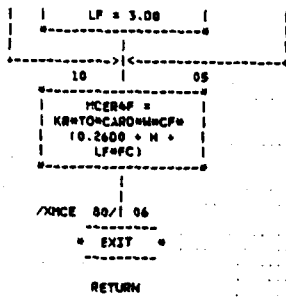


CHART TITLE - SUBROUTINE XICERS(CARO,TO,CF,M,KH,CAROS,NCERSF)

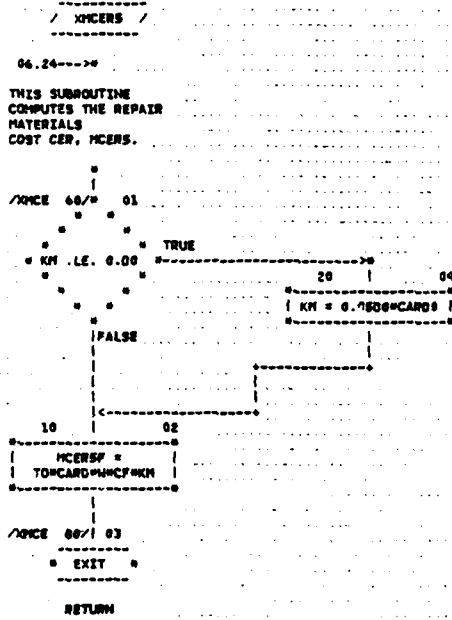
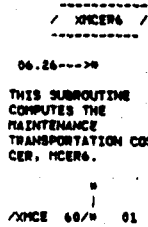
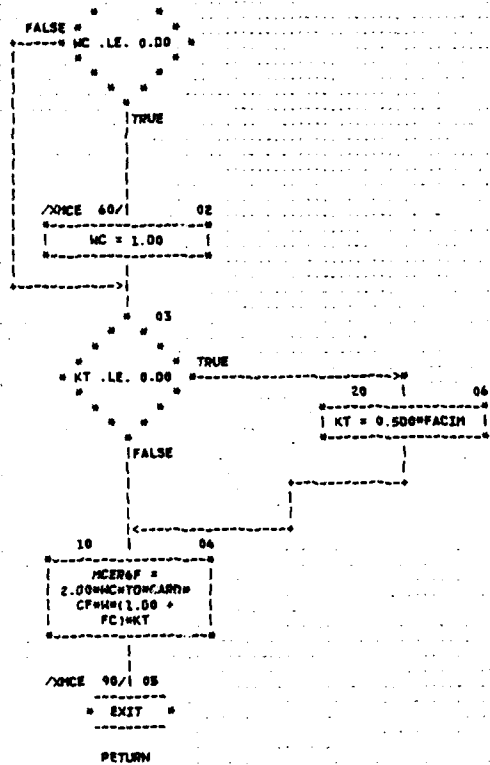


CHART TITLE - SUBROUTINE XICERS6(CARO,MC,TO,KT,FACIN,CF,M,FC,NCERS6F)





AUTOFLON CHART SET -

HCF MODEL

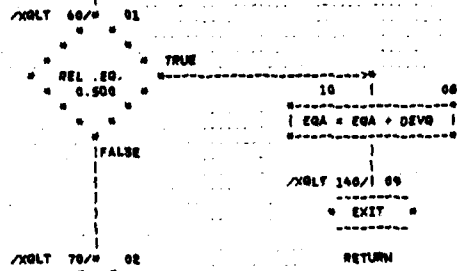
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CHART TITLE - SUBROUTINE XOLTY(REL,DEVO,EGA,EGD,EGD1,EGD2,EGCD,SCRN)

XOLTY

05.21-->

THIS SUBROUTINE ESTIMATES THE QUANTITIES OF MC'S. QUALITY GRADES A,B,B1,B2,AND BELOW FROM THE DEVICE RELIABILITIES.



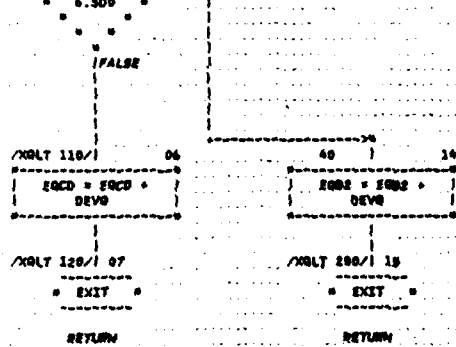
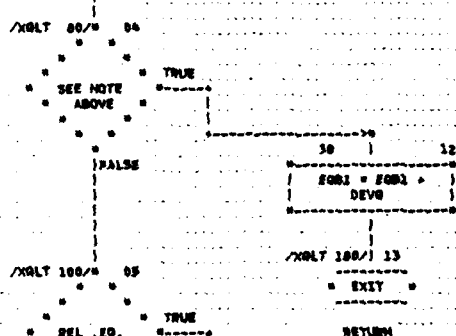
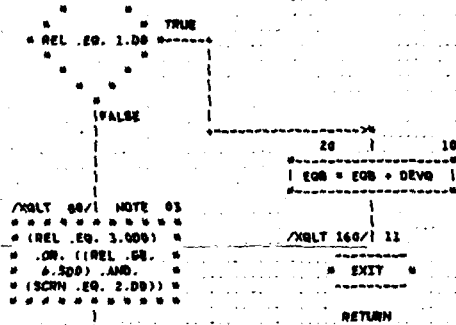
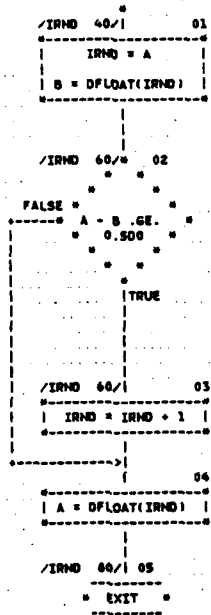


CHART TITLE - FUNCTION IRND(A)

THIS FUNCTION ROUNDS
THE LCC ESTIMATES TO
THE NEAREST INTEGER.



B.2 LCC MODEL SOURCE LISTING

```

C   MCF COMPUTERIZED MODEL ..... MAIN 10
C   ..... MAIN 20
      IMPLICIT REAL*8(A-H,K-Z) ..... MAIN 30
      INTEGER X,Y,NC,N,YRDE,TRDE,YMANU,TMANU,YOAS ..... MAIN 40
      DIMENSION NEW(100), SCRN(100), MEM(100), DIG(100), ECL(100), CF(10) MAIN 50
10)  MOS(100), FP(100), NG(100), NB(100), DEVQ(100), REL(100), CARDMAIN 60
      2(100), NDEV(100), NMC(100), QA(100), QB(100), QB1(100), QB2(100), MAIN 70
      3NDG(100), NLG(100), NRAH(100), W(100), KA(100), KS(100), NP(100), MAIN 80
      4H(100), YS(100), YC(100), XQB2(100), CASSYS(100), MCER1(100), MCERMAIN 90
      52(100), MCER3(100), QCD(100), PROOF(100), CARDS(100), MCER4(100), MAIN 100
      6MCER5(100), MCER6(100), OAS(100), RDTE(100), PURCH(100), SCR(100), MAIN 110
      7 MANU(100), LOAS(100), TOTALC(100), LINV(100), LTOTAL(100), LRI(10) MAIN 120
      80), LRD(100), LID(100), LIDD(100), RM1(100), NRM1(100), RM3(100), MAIN 130
      9HRM3(100), ROAS(100), NROAS(100) ..... MAIN 140
C   ..... MAIN 150
C   THIS SECTION READS & WRITES THE INPUT DATA AND TERMINATES THE ..... MAIN 160
C   PROGRAM IN CASES OF INSUFFICIENT INFORMATION. ..... MAIN 170
      QDEV=0.D0 ..... MAIN 180
      QCARD=0.D0 ..... MAIN 190
      QNG=0.D0 ..... MAIN 200
      QGATE=0.D0 ..... MAIN 210
      READ (1,*) N,NC,FSTD,CHAX,CMIN,RATEE2,RATET4,RATE1,RATE2,RATE3,M,THMAIN 220
1S,PL,TO,TR,FC,D,KI,KIR,KSM,KR,KH,KT,WC,RD,RI,YRDE,TRDE,YMANU,THMAIN 230
      2NU,YOAS ..... MAIN 240
      IF ((N.LE.0).OR.(NC.LE.0)) GO TO 10 ..... MAIN 250
      GO TO 20 ..... MAIN 260
10  WRITE (6,420) ..... MAIN 270
      GO TO 410 ..... MAIN 280
20  CONTINUE ..... MAIN 290
      DO 30 I=1,N ..... MAIN 300
      READ (2,*) NEW(I),MEM(I),MOS(I),DIG(I),ECL(I),FP(I),NG(I),NB(I),NPMMAIN 310
      1(I),DEVQ(I),REL(I),SCRN(I) ..... MAIN 320
30  CONTINUE ..... MAIN 330
      DO 40 I=1,NC ..... MAIN 340
      READ (3,*) CARD(I),NDEV(I),NMC(I),NDG(I),NLG(I),NRAH(I),W(I),CF(I) MAIN 350
      1,KA(I),KS(I) ..... MAIN 360
40  CONTINUE ..... MAIN 370
      DO 50 I=1,N ..... MAIN 380
      IF ((MEM(I).LT.0.D0).OR.(ECL(I).LT.0.D0).OR.(NEW(I).LT.0.D0).OR.(RMAIN 390
      1EL(I).LE.0.D0).OR.(NG(I).LT.0.D0).OR.(NB(I).LT.0.D0).OR.(DEVQ(I).LMAIN 400
      2E.0.D0).OR.(NP(I).LT.0.D0)) GO TO 70 ..... MAIN 410
50  CONTINUE ..... MAIN 420
      DO 60 I=1,NC ..... MAIN 430
      IF ((CARD(I).LE.0.D0).OR.(NDEV(I).LE.0.D0).OR.(NMC(I).LE.0.D0).OR. MAIN 440
      1(NDG(I).LT.0.D0).OR.(CF(I).LE.0.D0)) GO TO 70 ..... MAIN 450
60  CONTINUE ..... MAIN 460
      GO TO 120 ..... MAIN 470
70  WRITE (6,430) ..... MAIN 480
80  WRITE (6,500) ..... MAIN 490
      WRITE (6,520) N,M,KR,NC,TS,KH,FSTD,PL,KT,CHAX,TO,WC,CMIN,TR,RD,RATMAIN 500
      1EE2,FC,RI,RATET4,D,YRDE,RATE1,KI,TRDE,RATE2,KIR,YMANU,RATE3,KSM,MAIN 510
      2TMANU,YOAS ..... MAIN 520
      WRITE (6,570) ..... MAIN 530
      WRITE (6,530) ..... MAIN 540
      DO 90 I=1,N ..... MAIN 550

```

	WRITE (6,540) I,NEW(I),MEM(I),MOS(I),DIG(I),ECL(I),FP(I),NG(I),NB(I),NP(I),DEVQ(I),REL(I),SCRN(I)	MAIN 560
	CONTINUE	MAIN 570
90	WRITE (6,590)	MAIN 580
	WRITE (6,580)	MAIN 590
	WRITE (6,550)	MAIN 600
	DO 100 I=1,NC	MAIN 610
	WRITE (6,560) I,CARD(I),NDEV(I),NMC(I),QA(I),QB(I),QB1(I),QB2(I),Q	MAIN 620
	LCD(I),NDG(I),NLG(I),NRAM(I),W(I),CF(I),KA(I),KS(I)	MAIN 630
100	CONTINUE	MAIN 640
	WRITE (6,600)	MAIN 650
	IF (QCARD.EQ.QDEV) GO TO 110	MAIN 660
	WRITE (6,610) QDEV,QCARD	MAIN 670
110	CONTINUE	MAIN 680
	IF (QNG.EQ.QGATE) GO TO 410	MAIN 690
	WRITE (6,620) QNG,QGATE	MAIN 700
	GO TO 410	MAIN 710
120	CONTINUE	MAIN 720
	IF (RI.LE.0.DO) RI=0.06DO	MAIN 730
	IF (RD.LE.0.DO) RD=0.1DO	MAIN 740
	IF (M.LE.0.DO) M=1.DO	MAIN 750
	IF (YRTE.LE.0) YRTE=1980	MAIN 760
	IF (TRTE.LE.0) TRTE=0	MAIN 770
	IF (TMANU.LE.0) TMANU=1	MAIN 780
	IF (YMANU.LE.0) GO TO 140	MAIN 790
130	IF (YOAS.LE.0) GO TO 150	MAIN 800
	GO TO 160	MAIN 810
140	YMANU=YRTE+TRTE	MAIN 820
	GO TO 130	MAIN 830
150	YOAS=YMANU+TMANU	MAIN 840
160	CONTINUE	MAIN 850
	FACIM=(1.DO+RI)*(YRTE-1980)	MAIN 860
		MAIN 870
C		MAIN 880
C	THIS SECTION COMPUTES TOTAL RDT&E COST FOR ALL TYPES OF	MAIN 890
C	NEW DEVICES TO BE USED.	MAIN 900
	RDTE=0.DO	MAIN 910
	IF (FSTD.LE.0.DO) FSTD=0.DO	MAIN 920
	IF (CMAX.LE.0.DO) GO TO 190	MAIN 930
170	IF (CMIN.LE.0.DO) GO TO 200	MAIN 940
180	FSTD=(CMIN-CMAX)*FSTD+CMAX	MAIN 950
	GO TO 210	MAIN 960
190	CMAX=203.DO*FACIM	MAIN 970
	GO TO 170	MAIN 980
200	CMIN=24.DO*FACIM	MAIN 990
	GO TO 180	MAIN1000
210	CONTINUE	MAIN1010
	IF (TRTE.EQ.0) GO TO 240	MAIN1020
	DO 230 I=1,N	MAIN1030
	IF (NEW(I).EQ.0.DO) GO TO 220	MAIN1040
	CALL XRDTE (NG(I),FSTD,RDTE)	MAIN1050
	RDTE=RDTE+RDTEF	MAIN1060
220	CONTINUE	MAIN1070
230	CONTINUE	MAIN1080
	RDTE=RDTE/(1000.DO+TRTE)	MAIN1090
	CALL IRND (RDTE)	MAIN1100

	RDTE5=ROTES*TRDTE	MAIN1110
240	CONTINUE	MAIN1120
C		MAIN1130
C	THIS SECTION COMPUTES THE TOTAL PURCHASE PRICE FOR THE TOTAL	MAIN1140
C	QUANTITY OF DEVICES.	MAIN1150
	PURCHS=0.00	MAIN1160
	DNEW=0.00	MAIN1170
	DO 250 I=1,N	MAIN1180
	DNEW=DNEW+NEW(I)	MAIN1190
	CALL XPURCH (MEM(I),DIG(I),ECL(I),MOS(I),FP(I),REL(I),NG(I),NS(I),	MAIN1200
	IPURCH)	MAIN1210
	PURCHS=PURCHS+PURCHF*DEVQ(I)	MAIN1220
250	CONTINUE	MAIN1230
	PURCHS=(1.2500*PURCHS+FACIN)/(1000.00*TMANU)	MAIN1240
	CALL IRND (PURCHS)	MAIN1250
	PURCHS=PURCHS*TMANU	MAIN1260
C		MAIN1270
C	THIS SECTION ESTIMATES THE PROPORTIONAL DISTRIBUTION OF MC'S.	MAIN1280
C	QUALITY GRADES A,B,B1,B2 AND BELOW ON A CARD.	MAIN1290
	EQA=0.00	MAIN1300
	EQB=0.00	MAIN1310
	EQB1=0.00	MAIN1320
	EQB2=0.00	MAIN1330
	EQCD=0.00	MAIN1340
	ERA=0.00	MAIN1350
	DO 260 I=1,N	MAIN1360
	IF (SCRN(I).LE.0.00) SCRN(I)=2.00	MAIN1370
	CALL XQLTY (REL(I),DEVQ(I),EQA,EQB,EQB1,EQB2,EQCD,SCRN(I))	MAIN1380
	QDEV=QDEV+DEVQ(I)	MAIN1390
	QNG=QNG+NG(I)*DEVQ(I)	MAIN1400
260	CONTINUE	MAIN1410
	FQA=EQA/QDEV	MAIN1420
	FQB=EQB/QDEV	MAIN1430
	FQB1=EQB1/QDEV	MAIN1440
	FQB2=EQB2/QDEV	MAIN1450
	FQCD=EQCD/QDEV	MAIN1460
C		MAIN1470
C	THIS SECTION COMPUTES THE SCREENING TEST COST.	MAIN1480
	SCRS=0.00	MAIN1490
	DO 280 I=1,N	MAIN1500
	IF (SCRN(I).EQ.1.00) GO TO 270	MAIN1510
	CALL XSCR (DEVQ(I),MEM(I),MOS(I),NP(I),NG(I),RATEE2,RATET4,FACIN,NEW(I),SCREEN)	MAIN1520
	SCRS=SCRS+SCREEN	MAIN1530
		MAIN1540
270	CONTINUE	MAIN1550
280	CONTINUE	MAIN1560
	SCRS=SCRS/(1000.00*TMANU)	MAIN1570
	CALL IRND (SCRS)	MAIN1580
	SCRS=SCRS*TMANU	MAIN1590
C		MAIN1600
C	THIS SECTION COMPUTES TOTAL CARD ASSEMBLY COSTS FOR THE	MAIN1610
C	TOTAL QUANTITY OF CARDS.	MAIN1620
	ASSYS=0.00	MAIN1630
	TCP=0.00	MAIN1640
	MANUS=0.00	MAIN1650

	DO 290 I=1,NC	MAIN1660
	IF (W(I).LE.0.00) W(I)=1.00	MAIN1670
	TCP=TCP+CARD(I)	MAIN1680
	CALL CASSY (NDEV(I),NRAM(I),CASSYS(I))	MAIN1690
	ASSYS=ASSYS+1.2500*FACIM*CASSYS(I)*CARD(I)	MAIN1700
C		MAIN1710
C	THIS SECTION COMPUTES MANUFACTURING COSTS FOR	MAIN1720
C	THE TOTAL QUANTITY OF CARDS.	MAIN1730
	QCARD=QCARD+CARD(I)*NMC(I)	MAIN1740
	QGATE=QGATE+(NLG(I)+NDG(I))*CARD(I)	MAIN1750
	QA(I)=FQA*NMC(I)	MAIN1760
	CALL IRND (QA(I))	MAIN1770
	QB(I)=FQB*NMC(I)	MAIN1780
	CALL IRND (QB(I))	MAIN1790
	QB1(I)=FQB1*NMC(I)	MAIN1800
	CALL IRND (QB1(I))	MAIN1810
	QB2(I)=FQB2*NMC(I)	MAIN1820
	CALL IRND (QB2(I))	MAIN1830
	XQB2(I)=(FQB2+FQCD*2.8269200)*NMC(I)	MAIN1840
	CALL IRND (XQB2(I))	MAIN1850
	QCD(I)=FQCD*NMC(I)	MAIN1860
	CALL IRND (QCD(I))	MAIN1870
	CALL CTHRS (NDEV(I),NDG(I),W(I),NLG(I),NMC(I),H(I))	MAIN1880
	IF (H(I).LE.0.500) H(I)=0.500	MAIN1890
	CALL XC1 (H(I),RATE1,FACIM,C1)	MAIN1900
	CALL XC2 (RATE2,FACIM,C2)	MAIN1910
	CALL XC3 (RATE3,FACIM,C3)	MAIN1920
	CALL XYS (NDEV(I),NMC(I),YS(I))	MAIN1930
	CALL XYC (NMC(I),NDEV(I),XQB2(I),NLG(I),W(I),YC(I))	MAIN1940
	CALL PROO (C1,C2,C3,YC(I),YS(I),PROOF(I))	MAIN1950
	MANUS=MANUS+PROOF(I)*CARD(I)	MAIN1960
	CARDS(I)=((PURCHS+SCRS)/QDEV)*NMC(I)+1.2500*FACIM*CASSYS(I)+PROOF(I)	MAIN1970
	II)	MAIN1980
290	CONTINUE	MAIN1990
	MANUS=MANUS+ASSYS	MAIN2000
	MANUS=MANUS/(1000.00*TMANU)	MAIN2010
	CALL IRND (MANUS)	MAIN2020
	MANUS=MANUS*TMANU	MAIN2030
	PRS=PURCHS+MANUS+SCRS	MAIN2040
	KCARD=PRS*1000.00/TCP	MAIN2050
C	THIS SECTION COMPUTES MAJOR MAINTENANCE AND SUPPORT COSTS.	MAIN2060
	RM1L=0.00	MAIN2070
	NRM1L=0.00	MAIN2080
	MCER2L=0.00	MAIN2090
	RM3L=0.00	MAIN2100
	NRM3L=0.00	MAIN2110
	MCER4L=0.00	MAIN2120
	MCER5L=0.00	MAIN2130
	MCER6L=0.00	MAIN2140
	IF (TO.LE.0.00) TO=8760.00	MAIN2150
	IF (FC.LE.0.00) FC=0.00	MAIN2160
	DO 300 I=1,NC	MAIN2170
	CALL XMGER1 (NC,M,X,TS,PL,CARDS(I),CARD(I),TO,TR,CF(I),W(I),FC,D,J	MAIN2180
	1,RM1F,NRM1F)	MAIN2190
	RM1L=RM1L+RM1F	MAIN2200

	NRM1L=NRM1L+NRM1F	MAIN2210
	CALL XM CER2 (KA(I),KS(I),MCER2F)	MAIN2220
	MCER2L=MCER2L+MCER2F	MAIN2230
	CALL XM CER4 (CARD(I),KR,TO,CF(I),W(I),H(I),FC,FACIM,NL6(I),NDG(I),	MAIN2240
	MCER4F)	MAIN2250
	MCER4L=MCER4L+MCER4F	MAIN2260
	CALL XM CER5 (CARD(I),TO,CF(I),W(I),KM,KCARD,MCER5F)	MAIN2270
	MCER5L=MCER5L+MCER5F	MAIN2280
	CALL XM CER6 (CARD(I),WC,TO,KT,FACIM,CF(I),W(I),FC,MCER6F)	MAIN2290
	MCER6L=MCER6L+MCER6F	MAIN2300
300	CONTINUE	MAIN2310
	CALL XM CER3 (NC,DNEW,M,KI,KIR,KSM,FACIM,RM3L,NRM3L)	MAIN2320
	RM1L=RM1L/1000.00	MAIN2330
	CALL IRND (RM1L)	MAIN2340
	NRM1L=NRM1L/1000.00	MAIN2350
	CALL IRND (NRM1L)	MAIN2360
	MCER2L=MCER2L/1000.00	MAIN2370
	CALL IRND (MCER2L)	MAIN2380
	RM3L=RM3L/1000.00	MAIN2390
	CALL IRND (RM3L)	MAIN2400
	NRM3L=NRM3L/1000.00	MAIN2410
	CALL IRND (NRM3L)	MAIN2420
	MCER4L=MCER4L/1000.00	MAIN2430
	CALL IRND (MCER4L)	MAIN2440
	MCER5L=MCER5L/1000.00	MAIN2450
	CALL IRND (MCER5L)	MAIN2460
	MCER6L=MCER6L/1000.00	MAIN2470
	CALL IRND (MCER6L)	MAIN2480
	Y=5	MAIN2490
310	RM1(Y)=Y*RM1L	MAIN2500
	NRM1(Y)=NRM1L	MAIN2510
	MCER1(Y)=RM1(Y)+NRM1(Y)	MAIN2520
	MCER2(Y)=MCER2L	MAIN2530
	RM3(Y)=Y*RM3L	MAIN2540
	NRM3(Y)=NRM3L	MAIN2550
	MCER3(Y)=RM3(Y)+NRM3(Y)	MAIN2560
	MCER4(Y)=MCER4L*Y	MAIN2570
	MCER5(Y)=MCER5L*Y	MAIN2580
	MCER6(Y)=Y*MCER6L	MAIN2590
	ROAS(Y)=RM1(Y)+RM3(Y)+MCER4(Y)+MCER5(Y)+MCER6(Y)	MAIN2600
	NROAS(Y)=NRM1(Y)+NRM3(Y)+MCER2(Y)	MAIN2610
	OAS(Y)=MCER1(Y)+MCER2(Y)+MCER3(Y)+MCER4(Y)+MCER5(Y)+MCER6(Y)	MAIN2620
	TOTALC(Y)=RDTE+PRS+OAS(Y)	MAIN2630
	IF (Y.GE.15) GO TO 320	MAIN2640
	Y=Y+5	MAIN2650
	GO TO 310	MAIN2660
320	CONTINUE	MAIN2670
C		MAIN2680
C	THIS SECTION CALCULATES THE LCC SUMMARY BY FISCAL YEAR.	MAIN2690
	YRDE=YRDE-1980	MAIN2700
	YMANU=YMANU-1980	MAIN2710
	YOAS=YOAS-1980	MAIN2720
	IYOAS=YOAS+14	MAIN2730
	DO 330 I=YRDE,IYOAS	MAIN2740
	RDTE(I)=0.00	MAIN2750

	LINV(I)=0.00	MAIN2760
	LOAS(I)=0.00	MAIN2770
330	CONTINUE	MAIN2780
	IF (TRDTE.EQ.0) GO TO 350	MAIN2790
	IYRDTE=YRDTE+TRDTE-1	MAIN2800
	DO 340 I=YRDTE,IYRDTE	MAIN2810
	RDTE(I)=RDTE/TRDTE	MAIN2820
340	CONTINUE	MAIN2830
350	CONTINUE	MAIN2840
	IYMAN=YMANU+TMANU-1	MAIN2850
	DO 360 I=YMANU,IYMAN	MAIN2860
	LINV(I)=(PRS)/TMANU	MAIN2870
360	CONTINUE	MAIN2880
	DO 370 I=YOAS,IYOAS	MAIN2890
	LOAS(I)=ROAS(15)/15.00	MAIN2900
370	CONTINUE	MAIN2910
	LOAS(YOAS)=LOAS(YOAS)+NROAS(15)	MAIN2920
	RDFAC=DLOG(1.00+RD)	MAIN2930
	TOTRAD=0.00	MAIN2940
	TOTINV=0.00	MAIN2950
	TOTOAS=0.00	MAIN2960
	TOTC=0.00	MAIN2970
	TOTI=0.00	MAIN2980
	TOTIAD=0.00	MAIN2990
	DO 380 I=YRDTE,IYOAS	MAIN3000
	CALL IRND (RDTE(I))	MAIN3010
	CALL IRND (LINV(I))	MAIN3020
	CALL IRND (LOAS(I))	MAIN3030
	TOTRAD=TOTRAD+RDTE(I)	MAIN3040
	TOTINV=TOTINV+LINV(I)	MAIN3050
	TOTOAS=TOTOAS+LOAS(I)	MAIN3060
	LTOTAL(I)=RDTE(I)+LINV(I)+LOAS(I)	MAIN3070
	CALL IRND (LTOTAL(I))	MAIN3080
	TOTC=TOTC+LTOTAL(I)	MAIN3090
	LRI(I)=(1.00+RI)**(I-YRDTE)	MAIN3100
	LID(I)=LTOTAL(I)*LRI(I)	MAIN3110
	CALL IRND (LID(I))	MAIN3120
	TOTI=TOTI+LID(I)	MAIN3130
	LRD(I)=RD/(RDFAC*(1.00+RD)**(I+1))	MAIN3140
	LIDD(I)=LID(I)*LRD(I)	MAIN3150
	CALL IRND (LIDD(I))	MAIN3160
	TOTIAD=TOTIAD+LIDD(I)	MAIN3170
380	CONTINUE	MAIN3180
	YRDTE=YRDTE+1980	MAIN3190
	YMANU=YMANU+1980	MAIN3200
	YOAS=YOAS+1980	MAIN3210
C		MAIN3220
C	THIS SECTION PRINTS THE RESULTS OF THE LCC STUDY.	MAIN3230
	WRITE (6,510)	MAIN3240
	WRITE (6,450)	MAIN3250
	WRITE (6,440)	MAIN3260
	WRITE (6,460) RDTES,RDTES,RDTES,PRS,PRS,PRS,PURCHS,PURCHS,PURCHS,SMAIN3270	
	1CRS,SCRS,SCRS,MANUS,MANUS,MANUS,OAS(5),OAS(10),OAS(15),MCER1(5),MCHAIN3280	
	2ER1(10),MCER1(15),MCER2(5),MCER2(10),MCER2(15),MCER3(5),MCER3(10),MAIN3290	
	3MCER3(15),MCER4(5),MCER4(10),MCER4(15),MCER5(5),MCER5(10),MCER5(15)MAIN3300	


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7',112/64X,'YOAS',I13) MAIN3860
530 FORMAT (3X,'I',2X,'NEW',2X,'MEM',2X,'MOS',2X,'DIG',2X,'ECL',3X,'FPMAIN3870
1',5X,'NG',7X,'NB',3X,'NP',3X,'DEVQ*',4X,'REL',1X,'SCRN') MAIN3880
540 FORMAT (1X,I3,6(2X,F3.0),2(1X,F7.0),2X,F4.0,2X,F6.0,2X,F4.1,1X,F4. MAIN3890
10) MAIN3900
550 FORMAT (3X,'I',2X,'CARD*',2X,'NDEV',4X,'NMC',3X,'QA',3X,'QB',2X,'QMAIN3910
1B1',2X,'Q92',2X,'QCD',4X,'NDG',5X,'NLG',2X,'NRAM',2X,'N',7X,'CF',6MAIN3920
2X,'KA',5X,'KS') MAIN3930
560 FORMAT (1X,I3,1X,F5.0,2(1X,F6.0),5(1X,F4.0),2(1X,F7.0),1X,F4.0,1X,MAIN3940
1F4.2,1X,F8.7,2(1X,F6.0)) MAIN3950
570 FORMAT (//35X,'MC DEVICE DATA'/1X,'-----' ) MAIN3960
1-----' ) MAIN3970
580 FORMAT (//35X,'CARD DATA'/1X,'-----' ) MAIN3980
1-----' ) MAIN3990
590 FORMAT (1X,'* TOTAL QUANTITY OF MC DEVICES. ') MAIN4000
600 FORMAT (1X,'* TOTAL QUANTITY OF CARDS. '/') MAIN4010
610 FORMAT (1X,'NOTE: THE QUANTITY OF MC DEVICES AT THE DEVICE LEVEL DMAIN4020
1DOES NOT AGREE WITH THE QUANTITY OF MC DEVICES AT THE CARD LEVEL. MAIN4030
2 '/1X,'QTY @ DEVICE LEVEL:',F10.0/1X,'QTY @ CARD LEVEL:',F12.0//)MAIN4040
620 FORMAT (1X,'NOTE: THE TOTAL QUANTITY OF GATES AT THE DEVICE LEVEL MAIN4050
1DOES NOT EQUAL THE TOTAL QUANTITY OF GATES AT THE CARD LEVEL. '/1X,MAIN4060
2'QTY @ DEVICE LEVEL:',F15.0/1X,'QTY @ CARD LEVEL:',F17.0//') MAIN4070
END MAIN4080
C THIS SECTION SUPPLIES THE SUBROUTINES FOR THE MODEL. FORMULATED XRDT 10
C DEFAULT CERS ARE IMPLEMENTED WHEN PIECES OF INFORMATION XRDT 20
C ARE MISSING. CER'S FOR THE MAIN PROGRAM ARE SUPPLIED IN THIS XRDT 30
C SECTION. XRDT 40
C XRDT 50
SUBROUTINE XRDT (NG,FSTDC,RDTEF) XRDT 60
C THIS SUBROUTINE PREDICTS THE COST OF RDT&E FOR XRDT 70
NEW DEVICES, RCER. XRDT 80
C IMPLICIT REAL*8(A-H,J-Z) XRDT 90
RDTEF=NG*FSTDC XRDT 100
RETURN XRDT 110
END XRDT 120
SUBROUTINE XPURCH (MEM,DIG,ECL,MOS,FP,R,NG,NB,PURCHF) XPUR 10
C THIS SUBROUTINE PREDICTS THE PURCHASE COST FOR XPUR 20
ANY GIVEN DEVICE, PCER1. XPUR 30
C IMPLICIT REAL*8(A-H,J-Z) XPUR 40
INTEGER X,Y,NC,N XPUR 50
IF (NG.GT.0.D0) GO TO 10 XPUR 60
RG=0.D0 XPUR 70
RB=R/NB XPUR 80
GO TO 20 XPUR 90
10 RB=R/NG XPUR 100
RB=0.D0 XPUR 110
20 CONTINUE XPUR 120
IF (MOS.LT.0.D0) GO TO 30 XPUR 130
IF (FP.LT.0.D0) GO TO 40 XPUR 140
IF (DIG.LT.0.D0) GO TO 50 XPUR 150
GO TO 60 XPUR 160
30 PURCHF=DEXP(0.2931200+1.6992400*MEM+1.6557000*ECL-0.2379900*RG-9.2XPUR 170
1904900*RB) XPUR 180
RETURN XPUR 190
40 PURCHF=DEXP(0.2952800+1.9096700*MEM+1.6645100*ECL-3.0034400*MOS-0.XPUR 200

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	1238500*RG-11.354400*RB)	XPUR 210
	RETURN	XPUR 220
50	PURCHF=DEXP(0.02207D0+1.84461D0*MEM+1.58816D0*ECL-2.66517D0*MOS+0.160918D0*FP-0.20841D0*RG-9.15497D0*RB)	XPUR 230
	RETURN	XPUR 240
60	PURCHF=DEXP(0.52165D0+1.38197D0*MEM-0.69142D0*DIG+1.84202D0*ECL-2.170211D0*MOS+0.56445D0*FP-0.22443D0*RG-9.8324800*RB)	XPUR 250
	RETURN	XPUR 260
	END	XPUR 270
	SUBROUTINE CASSY (NDEV,NRAM,CASSYS)	XPUR 280
C	THIS SUBROUTINE COMPUTES CARD ASSEMBLY COST, PCER3.	XPUR 290
	IMPLICIT REAL*8(A-H,J-Z)	CASS 10
	IF (NRAM.LT.0.D0) GO TO 10	CASS 20
	CASSYS=5.91634D0*NDEV+27.57201D0*NRAM	CASS 30
	RETURN	CASS 40
10	CASSYS=6.26267D0*NDEV	CASS 50
	RETURN	CASS 60
	END	CASS 70
	SUBROUTINE XSCR (DEVQ,MEM,MOS,NP,NG,RATEE2,RATET4,FACIM,NEW,SCREEN)	CASS 80
	1)	CASS 90
C	THIS SUBROUTINE COMPUTES THE COST OF PERFORMING THE	XSCR 10
C	SCREENING TEST, PCER2.	XSCR 20
	IMPLICIT REAL*8(A-H,J-Z)	XSCR 30
	IF (RATEE2.LE.0.D0) GO TO 90	XSCR 40
10	IF (RATET4.LE.0.D0) GO TO 100	XSCR 50
20	IF ((MEM.EQ.1.D0).AND.((NP.GE.15.D0).AND.(NP.LT.24.D0))) GO TO 50	XSCR 60
	IF ((NP.GE.0.D0).AND.(NP.LT.17.D0).AND.(NG.GE.10.D0).AND.(NG.LE.10.D0)) GO TO 30	XSCR 70
	IF ((NP.GE.24.D0).AND.(NG.GE.100.D0)) GO TO 70	XSCR 80
	GO TO 50	XSCR 90
30	SCREEN=(.01917D0*RATEE2+.431D0*RATET4)*DEVQ	XSCR 100
	IF (NEW.EQ.1.D0) GO TO 40	XSCR 110
	RETURN	XSCR 120
40	SCREEN=SCREEN+20.D0*RATEE2	XSCR 130
	RETURN	XSCR 140
50	SCREEN=(0.05417D0*RATEE2+0.621D0*RATET4+13.75D0*FACIM)*DEVQ+40.D0	XSCR 150
	RATEE2	XSCR 160
	IF (NEW.EQ.1.D0) GO TO 60	XSCR 170
	RETURN	XSCR 180
60	SCREEN=SCREEN+80.D0*RATEE2	XSCR 190
	RETURN	XSCR 200
70	SCREEN=(0.12417D0*RATEE2+1.211D0*RATET4+72.D0*FACIM)*DEVQ+160.D0	XSCR 210
	RATEE2	XSCR 220
	IF (NEW.EQ.1.D0) GO TO 80	XSCR 230
	RETURN	XSCR 240
80	SCREEN=SCREEN+180.D0*RATEE2	XSCR 250
	RETURN	XSCR 260
90	RATEE2=43.75D0*FACIM	XSCR 270
	GO TO 10	XSCR 280
100	RATET4=35.D0*FACIM	XSCR 290
	GO TO 20	XSCR 300
	END	XSCR 310
	SUBROUTINE CTHRS (NDEV,NOG,W,NLG,NTC,H)	XSCR 320
C	THIS SUBROUTINE IMPLEMENTS THE CARD TEST HOURS CER, H.	XSCR 330
	IMPLICIT REAL*8(A-H,J-Z)	XSCR 340
		CTHR 10
		CTHR 20
		CTHR 30

	IF (NLG.LT.0.D0) GO TO 10	C1:=R	40
	H=-0.29669D0+0.0000889D0*NDEV*NDG+4.99908D0*(1.D0-W)+0.01514D0*NLCTHR	CTHR	50
	1G+1.98307D0*(NMC/NDEV)**2	CTHR	60
	RETURN	CTHR	70
10	H=0.37016D0+0.0000891D0*NDEV*NDG+5.13788D0*(1.D0-W)	CTHR	80
	RETURN	CTHR	90
	END	CTHR	100
	SUBROUTINE XC1 (H,RATE1,FACIM,C1)	XC1	10
C	THIS SUBROUTINE COMPUTES C1, WHICH IS USED IN	XC1	20
C	LATER CALCULATIONS.	XC1	30
	IMPLICIT REAL*8(A-H,J-Z)	XC1	40
	IF (RATE1.LE.0.D0) GO TO 20	XC1	50
10	C1=RATE1*H	XC1	60
	RETURN	XC1	70
20	RATE1=26.9D0*FACIM	XC1	80
	GO TO 10	XC1	90
	END	XC1	100
	SUBROUTINE XC2 (RATE2,FACIM,C2)	XC2	10
C	THIS SUBROUTINE COMPUTES C2, WHICH IS USED IN	XC2	20
C	LATER CALCULATIONS.	XC2	30
	IMPLICIT REAL*8(A-H,J-Z)	XC2	40
	IF (RATE2.LE.0.D0) GO TO 20	XC2	50
10	C2=RATE2*0.5D0	XC2	60
	RETURN	XC2	70
20	RATE2=26.9D0*FACIM	XC2	80
	GO TO 10	XC2	90
	END	XC2	100
	SUBROUTINE XC3 (RATE3,FACIM,C3)	XC3	10
C	THIS SUBROUTINE COMPUTES C3, WHICH IS USED IN LATER	XC3	20
C	CALCULATIONS.	XC3	30
	IMPLICIT REAL*8(A-H,J-Z)	XC3	40
	IF (RATE3.LE.0.D0) GO TO 20	XC3	50
10	C3=RATE3*0.26D0	XC3	60
	RETURN	XC3	70
20	RATE3=20.3D0*FACIM	XC3	80
	GO TO 10	XC3	90
	END	XC3	100
	SUBROUTINE XYS (NDEV,NMC,YS)	YS	10
C	THIS SUBROUTINE COMPUTES THE SYSTEMS TEST YIELD, YS.	YS	20
	IMPLICIT REAL*8(A-H,J-Z)	YS	30
	YS=DEXP(-0.00094D0*NDEV-0.00100*NMC)	YS	40
	RETURN	YS	50
	END	YS	60
	SUBROUTINE XYC (NMC,NDEV,QB2,NLG,W,YC)	XYC	10
C	THIS SUBROUTINE IMPLEMENTS THE TEST FRACTIONAL YIELD CER, YC.	XYC	20
	IMPLICIT REAL*8(A-H,J-Z)	XYC	30
	IF (NLG.LT.0.D0) GO TO 10	XYC	40
	YC=10**(-0.20504D0*(NMC/NDEV)-0.00146D0*QB2-0.00122D0*NLG-0.14842D0	XYC	50
	10*(1.D0-W))	XYC	60
	RETURN	XYC	70
10	YC=10**(-0.31298D0*(NMC/NDEV))	XYC	80
	RETURN	XYC	90
	END	XYC	100
	SUBROUTINE PROD (C1,C2,C3,YC,YS,PRODF)	PROD	10
C	THIS SUBROUTINE PREDICTS THE MANUFACTURING COSTS	PROD	20

C	FOR ANY CARD TYPE, PCER4.	PROD	30
	IMPLICIT REAL*8(A-H,J-Z)	PROD	40
	PRODF=(C1+C2*YC+C3*(1.00-YC*YS))/(YC*YS)	PROD	50
	RETURN	PROD	60
	END	PROD	70
	SUBROUTINE XMCE1 (NC,M,X,TS,PL,CARDS,CARD,TO,TR,CF,W,FC,D,J,RMIF,INRMIF)	XMCE	10
		XMCE	20
C	THIS SUBROUTINE COMPUTES THE INITIAL STOCK AND PIPELINE	XMCE	30
C	PLUS REPLENISHMENT CER, MCER1.	XMCE	40
	IMPLICIT REAL*8(A-H,K-Z)	XMCE	50
	INTEGER X,N,NC	XMCE	60
	IF (TS.LE.0.00) TS=336.00	XMCE	70
	IF (TR.LE.0.00) TR=1440.00	XMCE	80
	IF (D.LE.0.00) D=0.0500	XMCE	90
	IF (PL.LE.0.00) PL=0.900	XMCE	100
	KC=CARDS	XMCE	110
	QC=CARD/M	XMCE	120
	X=0	XMCE	130
	A=TS*QC*CF*(1.00+FC)	XMCE	140
	PROB=PL*(1.00/NC)	XMCE	150
	SUM=DEXP(-A)	XMCE	160
	IF (SUM.GE.PROB) GO TO 30	XMCE	170
	TERM=SUM	XMCE	180
	J=1	XMCE	190
10	TERM=TERM*(A/J)	XMCE	200
	SUM=SUM+TERM	XMCE	210
	IF (SUM.GE.PROB) GO TO 20	XMCE	220
	J=J+1	XMCE	230
	GO TO 10	XMCE	240
20	X=J	XMCE	250
30	MULT=TO*QC*CF*(1.00+FC)	XMCE	260
	RMIF=W*D*MULT*KC*M	XMCE	270
	NRMIF=M*KC*(X+(TR/8760.00))*MULT)	XMCE	280
	RETURN	XMCE	290
	END	XMCE	300
	SUBROUTINE XMCE2 (KA,KS,MCER2F)	XMCE	10
C	THIS SUBROUTINE COMPUTES THE SUPPORT EQUIPMENT CER, MCER2.	XMCE	20
	IMPLICIT REAL*8(A-H,J-Z)	XMCE	30
	IF (KA.LE.0.00) KA=0.00	XMCE	40
	IF (KS.LE.0.00) KS=0.00	XMCE	50
	MCER2F=KA+KS	XMCE	60
	RETURN	XMCE	70
	END	XMCE	80
	SUBROUTINE XMCE3 (NC,DNEW,M,KI,KIR,KSM,FACIN,RM3L,NRM3L)	XMCE	10
C	THIS SUBROUTINE COMPUTES THE INVENTORY ENTRY	XMCE	20
C	OF SUPPLY MANAGEMENT CER, MCER3.	XMCE	30
	IMPLICIT REAL*8(A-H,J-Z)	XMCE	40
	INTEGER N,NC	XMCE	50
	IF (KI.LT.0.00) GO TO 40	XMCE	60
10	IF (KIR.LT.0.00) GO TO 50	XMCE	70
20	IF (KSM.LT.0.00) GO TO 60	XMCE	80
30	IF (KI.EQ.0.00) KIR=0.00	XMCE	90
	IF (KIR.EQ.0.00) KI=0.00	XMCE	100
	RM3L=((DNEW+NC+1)*KIR+M*NC*KSM)	XMCE	110
	NRM3L=(DNEW+NC+1)*KI	XMCE	120

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RETURN
40 KI=54.D0*FACIM
GO TO 10
50 KIR=128.D0*FACIM
GO TO 20
60 KSM=42.D0*FACIM
GO TO 30
END
SUBROUTINE XMCE4 (CARD,KR,TO,CF,W,H,FC,FACIM,NLG,NDG,MCER4F)
C THIS SUBROUTINE COMPUTES THE REPAIR LABOR CER, MCER4.
C IMPLICIT REAL*8(A-H,J-Z)
IF (KR.LE.0.D0) GO TO 20
LF=1.500
IF (NLG.GT.NDG) LF=3.D0
10 MCER4F=KR*TO*CARD*W*CF*(0.26D0+H+LF*FC)
RETURN
20 KR=20.D0*FACIM
GO TO 10
END
SUBROUTINE XMCE5 (CARD,TO,CF,W,KM,CARDS,MCER5F)
C THIS SUBROUTINE COMPUTES THE REPAIR MATERIALS
C COST CER, MCER5.
C IMPLICIT REAL*8(A-H,J-Z)
INTEGER N,NC
IF (KM.LE.0.D0) GO TO 20
10 MCER5F=TO*CARD*W*CF*KM
RETURN
20 KM=0.0500*CARDS
GO TO 10
END
SUBROUTINE XMCE6 (CARD,WC,TO,KT,FACIM,CF,W,FC,MCER6F)
C THIS SUBROUTINE COMPUTES THE MAINTENANCE
C TRANSPORTATION COST CER, MCER6.
C IMPLICIT REAL*8(A-H,J-W)
INTEGER N,NC
IF (WC.LE.0.D0) WC=1.D0
IF (KT.LE.0.D0) GO TO 20
10 MCER6F=2.D0*WC*TO*CARD*CF*W*(1.D0+FC)*KT
RETURN
20 KT=0.500*FACIM
GO TO 10
END
SUBROUTINE XQLTY (REL,DEVQ,EQA,EQB,EQB1,EQB2,EQCD,SCRN)
C THIS SUBROUTINE ESTIMATES THE QUANTITIES OF MC'S,
C QUALITY GRADES A,B,B1,B2,AND BELOW FROM
C THE DEVICE RELIABILITIES.
C IMPLICIT REAL*8(A-H,K-Z)
IF (REL.EQ.0.500) GO TO 10
IF (REL.EQ.1.00) GO TO 20
IF ((REL.EQ.3.000).OR.((REL.GE.6.500).AND.(SCRN.EQ.2.D0))) GO TO 3XQLT
10 IF (REL.EQ.6.500) GO TO 40
EQCD=EQCD+DEVQ
RETURN
10 EQA=EQA+DEVQ

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XMCE 130
XMCE 140
XMCE 150
XMCE 160
XMCE 170
XMCE 180
XMCE 190
XMCE 200
XMCE 10
XMCE 20
XMCE 30
XMCE 40
XMCE 50
XMCE 60
XMCE 70
XMCE 80
XMCE 90
XMCE 100
XMCE 110
XMCE 10
XMCE 20
XMCE 30
XMCE 40
XMCE 50
XMCE 60
XMCE 70
XMCE 80
XMCE 90
XMCE 100
XMCE 110
XMCE 10
XMCE 20
XMCE 30
XMCE 40
XMCE 50
XMCE 60
XMCE 70
XMCE 80
XMCE 90
XMCE 100
XMCE 110
XQLT 10
XQLT 20
XQLT 30
XQLT 40
XQLT 50
XQLT 60
XQLT 70
XQLT 80
XQLT 90
XQLT 100
XQLT 110
XQLT 120
XQLT 130

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	RETURN	XQLT 140
20	EQB=EQB+DEVQ	XQLT 150
	RETURN	XQLT 160
30	EQB1=EQB1+DEVQ	XQLT 170
	RETURN	XQLT 180
40	EQB2=EQB2+DEVQ	XQLT 190
	RETURN	XQLT 200
	END	XQLT 210
	SUBROUTINE IRND (A)	IRND 10
C	THIS SUBROUTINE ROUNDS THE LCC ESTIMATES TO THE NEAREST INTEGER.	IRND 20
	REAL*8 A,B	IRND 30
	IRNDS=A	IRND 40
	B=DFLOAT(IRNDS)	IRND 50
	IF (A-B.GE.0.500) IRNDS=IRNDS+1	IRND 60
	A=DFLOAT(IRNDS)	IRND 70
	RETURN	IRND 80
	END	IRND 90

MISSION
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RADC plans and executes research, development, test and selected acquisition programs in support of Command, Control Communications and Intelligence (C³I) activities. Technical and engineering support within areas of technical competence is provided to ESD Program Offices (POs) and other ESD elements. The principal technical mission areas are communications, electromagnetic guidance and control, surveillance of ground and aerospace objects, intelligence data collection and handling, information system technology, ionospheric propagation, solid state sciences, microwave physics and electronic reliability, maintainability and compatibility.